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STUDY OF LIMITATIONS AND ATTRIBUTES OF MICROPROCESSOR TESTING TECHNIQUES

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I. GENERAL TEST PHILOSOPHY

The problems of testing microprocessors has been elevated past the conventional methods of testing integrated circuits. Just the fact that the microprocessor is not a simple collection of gates in a random format or a well ordered structure, like that of a large scale memory, does not lend itself to conventional means of testing. What is meant by the conventional means of testing is the commonly used DC test checking for inputs and output voltages and currents. This DC testing cannot prove that the microprocessor is operational, because there are from four to six or more levels of logic between the input and output pins. Also the conventional way to test random logic by applying a string of input patterns in a burst will only check for steady-state faults stuck at logic 1 or stuck at logic 0, and will not check for any instruction or data sensitivity.

There presently are many ways that both manufacturers and users are performing testing of microprocessors. These include methods such as selftesting, comparison testing, stored pattern testing, and algorithmic-aided pattern testing.

First Step in Testing

The first item to be considered when testing a microprocessor is to understand the operation and architecture structure of the microprocessor. The operation of the microprocessor is controlled by the execution of an

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instruction set unique to each microprocessor. There is a great variety of microprocessors on the market today, ranging from 2- and 4-bit slices to 4-, 8-, and 16-bit complete microprocessor units. But of all the product types, 4-bit slices, like the 2901, and 8-bit microprocessors, like the 8080, have gained the widest acceptance and therefore are good examples to use in describing testing techniques.

In general, a microprocessor has two internal buses: an 8-bit bidirectional data bus, and a 16-bit unidirectional address bus (Figure 1). The data bus carries both the instruction code and data. Instructions are decoded and executed in connection with the appropriate controls in which data going to both the arithmetic logic unit and accumulator can be manipulated by special arithmetic or logical operations. The address bus links the main memory where both instruction codes and data are stored. Stack pointers, program counters, and register files also supply information to the address. Finally, there is an instruction decoder which interprets each instruction and controls all operations of the microprocessor.

Since a microprocessor is a complex sequential logic structure and not simply a few gates or an LSI memory, a true and meaningful test requires the understanding of the hardware architecture and software functionality rather than only the simple logic of the elemental structures.

The hardware architecture is the internal organization with consists of an ordered set of modules, such as the register stack, accumulator, arithmetic logic unit, etc. Software functionality is a set of ordered

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FIGURE 1: Basic MPU Block Diagram

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microinstructions which can be used to monitor the operation of these modules.

Upon developing complete knowledge of the microprocessor unit through both areas, one can develop an ordered set of test sequences in the microprocessor's instruction set for testing each module one by one until a complete test has been developed.

In general, a microprocessor has two buses: an address bus and a data bus. The address bus performs two functions, addressing the external memory and/or addressing the internal scratch pad memory. The data bus also performs two functions, supplying input data to the processor and outputting processed data. The data bus links the internal functions of the scratch pad memory, registers, arithmetic logic unit, etc., together.

Modular Breakup

The next step in microprocessor testing is to partition the device into modules, with some modules possibly overlapping. The selection of each module should be accessible from the input/output bus by the execution of microinstructions. In other words, data should be able to be applied to the device input and propagated to the output directly or indirectly by the use of the microprocessor instruction set. The test then shall be generated for each module of the MPU so that a worst case test pattern will be run on that module. For instance, if the module in question is a RAM, a galloping l's and 0's test pattern is used as this type of pattern is

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considered to be worst case.

From the standpoint of software functionality, a set of MPU instructions should be executed when testing the first module. Proceeding toward the second module another set of new microprocessor instructions will be executed. (Some of these instructions may have been executed previously.) This process will then continue until all of the instructions within the instruction set are used while testing each module. Then a final test should execute all instructions to verify that all modules are working together.

Two-fold diagnostic information is provided by this technique. First, from a hardware point of view if a failure occurs, the faulty module is pinpointed. Inherent in this type of modular procedure is the fact that convenient breakpoints exist in a module-by-module basis. Second, in conjunction with each module, a set of microinstructions are executed; if any fault occurs, the specific instruction(s) can be isolated and identified.

Architecture and Test Flow

The architecture of the 2901 lends itself to the modular approach because of its own hardware and microinstruction architecture. Figure 2 illustrates the block diagram of the 2901. In examining this diagram, one will notice that the device can be divided into the following modules: RAM, Q register, arithmetic logic unit (ALU), ALU source decode multiplexer, RAM

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and Q register right/left shift logic.

Once the information has been acquired on the module breakdown, a test flow can be generated. Since the 2901 has an ALU section, the first areas to be tested should be those areas which supply data to the ALU. The most logical of these is in the RAM module and then in the Q register module. Once these modules have been tested, they can be used as reliable data sources for the ALU module test.

A typical test flow for the 2901 would start with the RAM memory, followed by the Q register, ALU source decode multiplexer, ALU, and finally, the RAM and Q register right/left shift logic (Figure 3). During this test flow, all microinstructions for the 2901 will be used.

Test Technique

Formulating a test plan will differ between the manufacturer and user. The reason for this being that the manufacturer has access to the logic diagrams of the device, which the user in most cases cannot obtain, and their quantities are in larger amounts than the user's. Therefore, more elaborate tests can be developed which optimizes test performance and test time. The user has an advantage over the manufacturer because his test, in its simplest form, can be tailored to his specific needs, but the manufacturers' test has to guarantee all operations of the microprocessor. Not receiving schematics, logic diagrams, or other circuit information the user must therefore rely on either vendor supplied test programs or perform

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TEST FLOW CHART	FUNCTIONAL TEST DESCRIPTION	TEST PATTERN
RAM Test	 A galloping "1" and "0" pattern is applied to the RAM in three combinations. 1. The RAM addressed by the "A" address and tested through the "Y" output port directly. 2. The RAM addressed by the "A" address and tested through the ALU. ALU is held at a fixed instruction. 3. The RAM addressed by the "B" address and tested through the ALU. ALU is held at a fixed instruction. 	Approx. 3000
"Q" REGISTER	A number 15 is loaded into the register and then read. Next, a number "O" is loaded and read. This is followed by a 14, 1, 13, 2, etc. until a "O" then a 15 is loaded.	Approx. 100
ALU Source Decode	The ALU Source Decodes are tested to see if all decodes are possible. The test is performed by loading values into the RAM and "Q" register and selecting all decodes while testing for any interaction between bits or selections.	Approx. 50
ALU	A series of numbers are loaded into the RAM and "A" register. These numbers are then used as inputs to the ALU. At the same time, all outputs and flags from the ALU are monitored, while incrementing operations the ALU can perform.	Approx. 1000
RAM and "Q" Register Right/Left Shift Mux.	All numbers from 0 to 15 are shifted through the RAM and "Q" register. While the RAM section is being tested, all locations are tested. After each shift, all possible number combinations are outputted to the output latch without clocking the latch, to see if there is any latch sensitivity.	Approx. 8200

FIGURE 3: 2901 Test Flow Diagram

extensive characterization to generate worst case test patterns. This characterization is needed to guarantee full operation of the microprocessor for a variety of applications in which the device is used.

The Optimum Test

At first glance of the 8080 MPU block diagram (Figure 4), the complexity of the device is not readily indicated. This is because there are only eight data input lines. However, in addition to accepting data from the input bus, the MPU can accept data from internal registers and accumulators. If the MPU could only perform one instruction, a test could be developed without much difficulty, but the MPU is capable of executing many instructions in sequence. Because of this, the number of combinations of instructions and data patterns that the MPU can perform would be extremely long.

A commonly used formula for calculating the total test time to exhaustively test an MPU is $C = 2^{MN}$. Where C is the number of combinations of instructions and data patterns, M is the number of data bits in each word, and N is the number of instructions the MPU is capable of executing.

For example, an 8-bit MPU that only has ten instructions would require 2^{80} test cycles for an exhaustive test of all possible combinations. Assuming a test cycle of 1 us, the MPU would take approximately 38 years to check all combinations of instructions and data patterns.

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FIGURE 4: 8080 Architecture

The 8080 MPU can perform approximately 76 different instructions. Using the above formula, there would be a total of 2^{608} possible combinations that could be performed. Obviously, this is an astonishing number to exhaustively test the 8080.

Test Techniques

Once realizing that the optimum test cannot be created, one looks for other means to test the MPU. The first approach considered is called selftest. The self-test is the simplest and cheapest means of determining if an MPU is working. Self-test, or in-circuit test, is the technique in which the device is placed in the circuit where it will be used and tested for correct operation. This is utilized by some users who feel the cost of incoming inspection cannot be justified. Therefore, they will typically test the device using several different system operations. The advantage of this testing is that the actual operation of the device is tested in its circuit, eliminating the requirement for a separate costly test system. The disadvantages of this technique is that any of the in-circuit condition changes, like voltage fluctations, temperature, timing, and instruction changes, may not be detected until the unit is in the field. The rework cost of finding and removing a faulty device must be considered before this method of testing is selected. Typical costs for finding and replacing a qate is as follows:

> \$3.00 to \$5.00: Board Level \$30.00 to \$50.00: System Level \$300.00 or Move: In Field

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Since an MPU is more complex than a gate, the above cost would be multiplied by the complexity factor of the MPU.

The second method of testing is called comparison testing. Comparison testing is the method in which a known good device is compared to the device under test. The hardware required for this type of test is very simple, requiring only a pseudo number generator connected to all inputs and all outputs from the known good device and comparing the device under test (Figure 5). If exact comparison does not occur, the device under test is considered bad. The advantages of this method is that the test system is inexpensive to develop and with a little more hardware added, voltage and timing conditions can be created. Also, if the device is operated for a few minutes, most paths through the device will be checked. Like any test method, it has its disadvantages also. The biggest disadvantage is that this method requires a known good device, which is a problem in itself. Some MPU's have illegal instructions, therefore, no guarantees can be made for the data coming out of the device. Also, critical timing into the device may not be able to be maintained if pseudo numbers are applied to the input of the MPU. Last of all, if the device fails, no failure information can be obtained to determine the cause.

The next method of testing is the stored pattern method which utilizes a known good pattern stored in some form of data memory. This pattern is then applied to the device under test in a burst mode and the device outputs compared to the stored response (Figure 6). There are two means of generating patterns using this method. The first method is to input a test pattern into a known good device and record all input stimuli and output data.

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FIGURE 5: Comparison Test



FIGURE 6: Stored Pattern Test

The input patterns would be created from some known application.

The second method of generating the stored pattern would be to develop a software or hardware simulator for the device to be tested. A known instruction sequence would then be stored and used to compare with the device under test. The advantage of this technique is that the user's instruction sequence can be completely tested and that sensitive data paths can be checked with ease. Since the tester that is required to perform this type of test usually incorporates variable voltage and timing circuits, these parameters can also be checked. The main disadvantage of using a known good device for generating the test pattern is a "known good device." What test is available to determine what is a known good device? The disadvantage of the stimulator approach is that a software or hardware similator is required. Since the schematic and logic diagrams for each MPU are not readily available from the vendor, it is difficult for a user to develop the simulator. Even if these could be obtained, it would take a knowledgeable programmer three to six months, at least, to develop the software. Other disadvantages to this method are:

> LARGE, EXPENSIVE MEMORY. High-speed random access memories or shift registers become quite expensive when any great amount of memory is needed. In testing the program counter for the 8080, for example, 262,000 distinct patterns are required. A memory test on the register array of an 8080 takes approximately 50,000 patterns. The cost of memory can quickly become a major part of the total cost of the test system.

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LONG TRANSFER TIME. The overhead time required to transfer a long pattern from disc, core, or other mass memory to high-speed RAM can make a large dent in the throughput rate of the test system. If transferring a 1,024-bit pattern from disc to RAM takes 50 milliseconds, a typical figure, transferring the test pattern from the program counter takes 13.1 seconds of overhead time, in addition, to the test execution time (262 X 50 X 10^{-3} Seconds).

INFLEXIBLE PROGRAM. The stored program cannot easily be modified while tests are in progress. This rigidity makes it difficult to perform special or unusual tests on a single unit. A substantial amount of off-line software support is needed if such tests are to be accomplished.

The algorithmic test method utilizes a high-speed programmable pattern generator in conjunction with a local buffer memory. The contents of the buffer memory is a test pattern consisting of microprocessor instruction sequences and either full or partial data input and output response patterns. The buffer memory pattern is then applied to the microprocessor under program control of the pattern generator. A distinct advantage of this test method offered by the use of a programmable pattern generator is the ability to choose how the test pattern is applied to the device under test. This will in turn determine whether the stored data pattern and output response of the microprocessor is full or partial.

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The first option is to apply the test pattern in a burst mode as in the previously defined stored response approach. In this case, the device data pattern and output response stored in the buffer memory is complete, with the pattern generator acting as a counter to advance the test pattern vectors.

In the second mode, special algorithms are written for the pattern generator which simulate the microprocessor instruction execution. These special algorithms input microprocessor instruction codes and data patterns at the proper point in the instruction cycle, and compare the device output accordingly. However, the device data pattern and output response may be partially stored in the buffer memory and partially generated in real time by the pattern generator algorithms. The effect is to enhance the MPU test program by allowing a significant increase in the number of test patterns used, enable additional tests to be performed that would be difficult, if possible at all by any of the previous methods, and reduce the total amount of stored test vectors. A disadvantage here is that in addition to the buffer test pattern required, a separate program for the pattern generator may be necessary which increases the complexity of the total effort.

This technique, which eliminates the delay time in transferring patterns to mass memory, is extremely efficient and flexible in generating patterns for logic modules such as binary counters, random access and read only memories, shift registers, as well as microprocessors.

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When used in conjunction with the module approach, algorithm pattern generation permits faults to be diagnosed so that the particular module or instruction which caused a failure can be isolated. The disadvantages of this method is that a sophisticated tester is required. The programmer needs to be knowledgeable of both operation of the MPU and the test system itself to develop the program.

The recommended approach to be described is a combination of stored pattern and algorithmic techniques. This approach was selected because of its ease of program development (stored pattern) and its thorough testing ability (algorithmic).

II. BASIC BLOCK DIAGRAM

As shown in Figure 4, the basic microprocessor unit includes a data and address bus, accumulator, arithmetic logic unit, register files, stack pointer, program counter, and timing controls. In the following figures, Figures 7 through 11, the 8080, 8008, 2901, 6800, and 1802, block diagrams are illustrated.

8080

Using the 8080 (Figure 7) as a reference, all other MPU's are structured very similar. Other than their instruction set, they differ as described below.

8008

The 8008 (Figure 8) is very similar in architecture to the 8080. The basic difference is that the 8008 has seven 14-bit stack registers for storage of return addresses as a result of subroutine calls. The 8080 has one 16-bit pointer for controlling an external memory stack allowing more than seven levels of subroutine testing.

2901

The 2901 (Figure 9) differs the most from the 8080. The 2901 is only the process portion of a basic MPU, a 4-bit processor, which lacks any



FIGURE 7: 8080 Block Diagram



FIGURE 8: 8008 Block Diagram



FIGURE 9: 2901 Block Diagram

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ordered instruction set. Therefore, the 2901 does not have an instruction decoder. The 2901 does have a register array (16 words X 4-bits), an accumulator (4-bits), and an arithmetic logic unit (ALU). The 2901 does not have a program counter to control from which memory location the next instruction will be fetched. This is controlled by external circuitry. Last of all, the 2901 cannot execute a jump or subroutine call by itself; thus, it also lacks a stack pointer.

6800

The 6800 (Figure 10) is structured similar to the 8080 but does not contain a register array. External RAM is used for all scratch pad operations. Also, the 6800 includes two accumulators as opposed to one provided by the 8080.

1802

The 1802 (Figure 11) architecture is similar to the 8080 except that the program counter and stack pointer are included as part of the register array. Also, instead of having a 16-bit address bus it has an 8-bit bus, which multiplexes the address in 8-bit bytes.

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EXPANDED BLOCK DIAGRAM



FIGURE 10: 6800 Block Diagram





III. MODULAR APPROACH

As previously shown, all microprocessor units have a similar architecture from which a basic test philosophy can be adopted. This philosophy is to develop an approach to test each module separately accomplishing the following goals:

- A. Verify the functionality of each module within the device using the input/output pins of the device and its instruction set.
- B. Test for destructive interaction between functional modules.
- C. Verify all timing, status information, and interrupt operations of the device.

IV. DESCRIPTIONS OF THE MODULAR TEST APPROACH

Since each MPU is structured around a similar architecture, a common test approach can be adopted and applied to each device. Once this approach has been established, further requirements are to implement the approach according to the specific architecture and instruction set of each device. The following is a basic description of a generalized test approach for each module previously described.

- A. Program Counter
 - 1. Verify reset state.
 - Verify that the counter can be incremented through its maximum range.
 - 3. Check any possible register transfer to the program counter.

B. Register Arrays

- Verify that each register can be loaded individually, if possible, and its contents stored to the data bus.
- Verify register-to-register and register-to-output transfers with all possible number combinations.
- 3. If the registers can be incremented and/or decremented, verify that they can accomplish this through their complete range.

C. Stack Pointer

- 1. Verify that the stack pointer (registers) can be loaded.
- 2. Check to see if stack pointer transfers are valid.
- 3. Verify increment and decrement operations.
- D. Arithmetic Logic Unit
 - 1. Verify ADD operations, with and without carry.
 - 2. Verify a SUBTRACT operation, with and without a borrow.
 - 3. Verify all shift left or shift right operations.
 - 4. Verify rotation of a numerical value, if applicable.
 - 5. Check all logical operations, for example, AND, OR, EOR, etc., when applicable.
- E. Accumulator
 - 1. Test to see if it can be loaded and read.
 - 2. Check for any transfer operation that can be performed.
 - 3. Verify that the accumulator can be incremented and decremented.
- F. Timing and Control
 - Verify that all control timing occurs at correct reference points, for example, data bus enable, sync signals, write enables, etc.

- Exercise all control operations on the device to verify operation, for example, WAIT, HOLD, INTERRUPT, etc.
- Verify any status flags that are produced during an arithmetic operation, such as carries, negative or positive numbers, overflows, etc.
- G. Instruction Decodes
 - 1. Verify full operation by execution of the complete instruction set.
 - 2. Verify execution of branch and jump operations.
 - Test for interaction between all modules, and verification of all data paths between modules.

V. PROCESSOR TEST DESCRIPTIONS

A. 8080

The 8080 is an 8-bit microprocessor using an N-channel silicon gate MOS process. The 8080 can be divided into the following modules based on its functional block diagram (see Figure 7).

Functional Module Breakup

- 1. Timing and Control
- 2. Instruction Decoder
- 3. Program Counter

4. Register Array

5. Stack Pointer

6. Accumulator

7. Arithmetic Logic Unit (ALU)

Due to the complexity of some tests on the modules, a flow chart of the recommended test will be used to ease the burden of understanding the test.

Timing and Control Test

The first test on the 8080 is to verify the operation of all timing and control signals. This test was selected first because the basic operation of the MPU requires that timing and control be present. TEST 1, RESET: Verify that the Hold Acknowledge (HLDA) appears following the rising edge of clock Øl and that the Data and Address buses go into a tristate condition following the rising edge of clock Ø2. Verify that the Interrupt Enable (INTE) is reset. Last, following the removal of the reset, the Program Counter is equal to 0, which will appear on the address bus. When performing a reset note that the reset signal should be present for at least four clock periods.

TEST 2, TIMING: Execute a NOP instruction following a reset, verify that the SYNC signal occurs within the first clock cycle, that the DBIN signal occurs in the second clock cycle, and finally, that the Program Counter increments and that it is present on the address bus during the fourth clock cycle. Follow this NOP instruction with a Store Accumulator (STA) direct instruction and verify that the Write (\overline{WR}) goes low during the third clock cycle of that instruction.

TEST 3, HOLD: Present a Hold signal to the 8080 and verify that during T2 time cycle Hold Acknowledge (HLDA) appears and the Address and Data buses go to tristate. Upon removing the Hold signal, verify that HLDA is removed, and the buses are enabled. During the time that the Hold signal is present, the 8080 should be in a Hold operation for the time

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that the Hold signal is present.

TEST 4, INT: Execute an Enable Interrupts (INTE) instruction, followed by a few NOP instructions, and present an Interrupt Request (INT) to the 8080 during an NOP instruction cycle. Verify that the Interrupt Enable is present during T1 time of the next instruction. This INTE signal should not go high until T1 time. Upon presenting a reset signal to the 8080, verify that the INTE signal is removed.

Instruction Decoder Test

The next test on the 8080 should check the Instruction Decoder. This test is used to verify that the complete device is operational and that it will execute all instructions in the instruction set. This recommended test is designed to test all instructions but not all data patterns. Table 1 is a listing of the recommended instruction sequence.

Program Counter Test

This test includes a reset, which clears the Program Counter, and 2^{16} NOP instructions or any other instruction(s) to verify that the counter will increment through all possible addresses. A flow chart of this test is illustrated in Figure 12. This test will verify that the Program Counter resets and increments. The only operation

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| NOP ************************************ |
|--|
| EI + LOCATIONS 0=15 ARE FOR THE + |
| DI + HALT-HOLD-INTERUPT ROUTINE + |
| EI *==================*======= |
| LXT SP |
| (VERIFIES HIGH IMPEDANCE DURING HOLD & HALT) |
| SPL=02 SP=0102 |
| SPH=01 |
| RST (AT 0038) |
| PCH(00) TO (SP-1) |
| PCL(07) TO (SP-2) SP-2=0100 |
| EI |
| HALT |
| RST (AT 0000) |
| PCH(00) TO (SP-1) |
| PCL (3A) TO (SP-2) SP-2=00FE |
| LXT B |
| C = 0 2 |
| 8=01 *====================== |
| LXI D * MAIN INSTRUCTION SEQUENCE * |
| E=08 * STARTS AT LOCATION 16 * |
| D=04 ************************************ |
| LXI Ĥ |
| L=20 |
| H = 1 0 |
| LXI SP |

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TABLE 1: Recommended Instruction Sequence

NOP			
SPL=FE SP=00FE			
SPHERO			
LDA (B3B2)TO A			
82		١	
B 3			
(00FF) TO A A=40			
STA A TO (B382)	· ·	•	
82			
83			
40 TO FFFF		·	
POP PSW			
(SP) TO F F=06		i	
(SP+1) TO A A=80	SP+2=9100		
PUSH PSW			
A TO (SP-1)			
E TO (SP-2)	SP-2=BAFE		
PUSH B		. · ·	
B TO (SP-1)			
C'TU (SP=2)	SP=2=00FC		
PUSH D			
D TO (SP-1)			
E TO (SP-2)	SP-2=00FA		
PUSH H		· · ·	
H TO (SP-1)			
L. TO (SP-2) SP-2	=00F8		

NOP			
РИР В			
(SP) TO C	C = Ø 4		
(SP+1) TO B	B=02	SP+2=00FA	
P0P 0			
(SP) TO E	E=10		
(SP+1) TO D	D=08	SP+2=00FC	
РИР Н			
(SP) TO L	L=40	•	
(SP+1) TO H	H=20	SP+2=00FE	
MØV M,A			
A TO (HL)			
MØV M,8			
8 TO (HL)			
MØV M.C			
C TO (HL)			
MØV M,D			
D TO (HL)	· .		
MOV M,E			
E TO (HL)		·	•
MØV M,H			
H TO (HL)			
MØV M,L			
L TO (HL)			
XCHG D=20,H=	И8,E=40,L:	= 1 0	
MØV M,D		· · ·	

NOP D TO (HL) MOV M.E E TO. (HL) MOV M,H H TO (HL) MOV MIL L TO (HL) XTHL (SP) TO L L=FE (SP+1) TO H H=00 OLD H TO (SP+1) OLD L TO (SP) MOV M,H H TO (HL) MOV M.L L TO (HL) PCHL PC=(HL) SPHL SP=(HL) DAD SP HL=HL+SP PUSH H H TO (SP-1) L TO (SP-2) MOV M,H H TO (HL) MOV M.L ,

PC=00FE SP=00FE

HL=0100

SP-2=00FC

NOP L TØ (HL) DAD B HL=HL+BC HL=01FC+0204=0400 MAV M.H H TO (HL) MOV M.L L TØ (HL) PAD D HL=HL+DE HL=0400+2040=2440 MOV M.H. H TO (HL) MOV M.L L ТИ (HL) -DAD H HL=HL+HL HL=2440+2440=4880 MOV M.H H TO (HL) MOV M.L L TO (HL) STAX B A TO (BC) STAX D A TO (DE) LDAX B 00 TO A FROM (BC) MOV M, A A TO (HL) LDAX D

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NOP FF TØ A FROM (DE) MEV M.A A TO (HL) 1NX B BC+1=0205 1NX D DE+1=2041 1NX H HL+1=4881 1NX SP SP+1=FD PUSH H (H) TØ (SP-1) (L) TO (SP-2) SP-2=FB MOV M,B B TO (HL) MOV M.C С ТИ (НЦ) MOV M.D D TØ (HL) MOV M.E E TO (HL) MOV H.H H TØ (HL) MOV M.L L TO (HL) DCX B BC-1=0204 DCX D DE-1=2040 DCX H HL-1=4880

NOP DCX SP SP-1=FA PUSH H H TA (SP-1) L TO (SP-2) SP-2=F8 MOV M.B B TP (HL) MOV M.C C TØ (HL) MOV M.D D TO (HL) MOV M,E E TO (HL) MØV M,H H TØ (HL) MOV M.L L TO (HL) CMA COMPLEMENT A (=00) STC SET CARRY =1 PUSH PSW A TØ (SP-1) F TO (SP=2) SP=2=F6 CMC COMP. CARRY (=0) IN 82 DEV=0F 90 TO A FROM OFOF

NOP PUSH PSW A TØ (SP-1) F TO (SP-2) SP-2=F4 DAA A TO BCD A=03, SET FO, F4 PUSH PSW A TO (SP-1) F TØ (SP+2) SP-2=F2 DAA A TO BCD A=69 CLEAR F4 PUSH PSW A TØ (SP-1) F TU (SP-1) SP-2=F0 SHLD 82 **B**3 L TØ (B3B2) H TO (B3B2+1) LHLD 82 83 00 TO L FROM B3B2 FF TO H FROM B3B2+1 MOV M,H H TO (HL) MOV M.L L TM (HL)

NOP INR M FF FROM (HL) +1=00 00 TO (HL) DCR M 00 FR0M (HL) -1=FF FF TO (HL) NØP RUT B2 DEV=AA 69 TO DEV AAAA FROM A MOV A,M 01 TO A FROM (HL) MOV B,M 08 TO B FROM (HL) MOV C.M 04 TO C FROM (HL) MOV D,M . 08 TO D FROM (HL) MOV E,M 10 TO E FROM (HL) MOV H.M 20 TO H FROM (HL) MAY L.M 40 TO L FROM (HL) MOV M,A

	NOP	
	A TO (HL)	
)	MØV M,B	
	B TO (HL)	
	MØV M,C	
	C TH (HL)	
	MØV M,D	
	D TØ (HL)	
	MOV M,E	
	E 10 (HL)	
	MOV M.H	
	H TØ (HL)	
	MOV M.L	
	L TØ (HL)	
	AJVM	
,	B2 02 T0 A	
	MVI 8	
	82 04 TO B	
	MVIC	
	82 08 TO C	
	MVI D	
	82 10 TO D	
	MVI E	
	82 20 TØ E	
	MVI H	
	82 40 TO H	

NOP MVI L 82 80 TO L MOV M,A A TO (HL) MAV M.B 8 TÚ (HL) MOV M.C C TO (HL) MUV M.D D TO (HL) MOV M,E E TO (HL) MOV M.H H TO (HL) MOV MIL L TO (HL) MVI M 82 FF TO (HL) INR A A+1=03 MOV M.A A TO (HL) 1NR 8 8+1=05 MOV M.B 8 TØ (HL)

NOP	NOP
1NR C C+1=9	MEV M,D
MØV M,C	D TØ (HL)
C T0 (HL)	DCR E E-1=20
1NR D D+1=11	MØV M,E
MØV M,D	E TO (HL)
D TØ (HL)	DCR H H+1=40
1NR E E+1=21	Mev M,H
MØV M,E	H TO (HL)
E TO (HL)	DCR L L-1=80
1NR H H+1=41	MOV M,L
MØV M,H	L T0 (HL)
H TA (HL)	MOV A, B A=04
INP L L+1=81	NOV B, C B=08
MAV M,L	MØV C, D C=10
L TA (HL)	MØV D,E D=20
DCR A A-1=02	- MØV E,H E=40
MRV M,A	MOV HIL H=BO
А ТО (HL)	MOV L, A L=04
DCR B B-1=04	MOV M,A
MØV M,B	A TØ (HL)
В ТØ (HL)	MUV M,B
DCR C C-1=08	B TØ (HL)
MUV M.C	MOV M.C
С ТИ (HL)	C TØ (HL)
DCR: D D-1=10	MEV M.D

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	1
NOP	NOP
D TO (HL)	
MOV M,E	
E TO (HL)	MOV M.L
MOV M,H	L TO (HL)
H TO (HL)	MOV A,D A=80
MOV M.L	MOV B,E B=04
	MOV C,H C=10
	MQV D,L D=20
	MOV M,A
MÜV 8,0 8=20	A TO (HL)
MOV C, $E C = 40$	MOV M.B
MOV D,H D=80	B TO (HL)
MOV E,L E=04	MOV M,C
MOV M,A	C TO (HL)
A TO (HL)	MOV M,D
MOV M,B	D TO (HL)
B TO (HL)	NOV E A E=80
MOV M,C	
C TO (HL)	
MOV H,D	MOV_L,C L=10
D TO (HL)	MOV M,E
MOV M,E	E TO (HL)
E TO (HL)	MOV M,H
	H TO (HL)
	MOV M.1
	L TO (HL)
nuv møn	MOV E.M
	1

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TABLE] Continued	
(ADE-	NOP
	L TO (HL)
	NOV A.H A=10
NOP	H=40
(HL) TO E	MOV 115
HAV HIM	MOV DID
H=08	MOV B.L
(HC)	MOV LIE LEN
MOV LIT L=02	MOV E.C E=02
(HL) TO L	404 C+A C=10
MOV A,E	mov
MOV E.B E=WA	L VOM
B=08	A TO CITE
H=10	MON W'B
MUA C=NS	B TO (HL)
MOV CIL	MOV M.C
MOV LID DEAR	C TO (HL)
MOV U.A	H.P.
MOV M.A	MOV TO (HL)
A TO (HL)	
NON M.B	MOV M.E
HUY (HL)	E TO (HL)
B 10 C	MOV M.H
MON MIL	H TO (HL)
C TO (HL)	Line Mek
HOV MOD	MUY TO (HL)
D TD (HL)	L TU CILL
NOV ME	MOV AIL
mut the (HL)	MOV L.H LEND
F In .	MOV H.E HEOR
MOV Man	
H TO (HL)	1
MOV.M.L	·

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NOP					
MOV E,D	E=08		•		
MOV D,C	D=10				
MOV C,B	C=20				
MOV B,A	B=04				
MOV M,A					
A TO (HL)				
MOV M,B		•			
B TO (HL)				
MOV M,C					
C TO (HL)				
MOV M,D					
D TO (HL)				
MOV M,E					
E TO (HL)				
MOV M.H					
H TO (HL)		-		
MOV M,L					
L TO (HL)				
POP PSW		SP=00F0	(SEE	LINE	186)
(SP) T	0 F	F=02		·	
(SP+1) T	A C	A=80	SP	+2=001	2
PUSH PSW					
A TO (SP	-1)				
F TO (SP	-2)	SP-2=00F0	9		
ADD B A=	A+B=80	+04=84	F=86	A = 8	34

NOP	
PUSH PSW	
A TO (SP-1)	
F TO (SP-2)	SP-2=00EE
ADD C A=A+C	A=A4 F=82
PUSH PSW	
A TO (SP-1)	
F TO (5P-2)	SP-2=00EC
ADD D A=A+D	A=B4 F=86
PUSH PSW	
A TO (SP-1)	
F TO (SP-2)	SP-2=90EA
ADD E A=A+E	A=BC F=82
PUSH PSW	
A TO (SP-1)	
F TO (SP-2)	SP-2=00E8
ADD H A=A+H	A=BE F=86
PUSH PSW	
A TO (SP-1)	
F TO (SP-2)	SP-2=00E6
ADD L A=A+L	A=FE F=B2
PUSH PSW	,
A TO (SP-1)	
F TO (SP-2)	SP-2=00E4
ADD M A+(HL)	
(HL) IN=01	A=FF F=86

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NOP	
PUSH PSW	· ·
A TO (SP-1)	
F TO (SP-2)	SP-2=90E2
ADD A A=A+A	A=FE F=93
PUSH PSW	
A TO (SP-1)	
F TO (SP-2)	SP-2=90E0
ADC B A=A+B+1	A=43 F=17
PUSH PSW	
A TO (SP-1)	
F TO (SP-2)	SP-2=00DE
ADC C A=A+C+1	A=24 F=06
PUSH PSW	
A TO (SP-1)	
.F TO (SP-2)	SP-2=90DC
ADC D A=A+D	A=34 F=02
PUSH PSW	
A TO (SP-1)	
F TO (SP-2)	SP-2=000A
ADC E A=A+E	A=3C F=06
PUSH PSW	
A TO (SP-1)	
F TO (SP-2)	SP-2=0008
ADC H A=A+H	A=3E F=02
PUSH PSW	

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			•
NOP			
A TO (SP-1)			A=3E
F TO (SP-2)	SP-2=90	06	8=194
ADC M A=A+(HL)	A=00	F=57	C=20
(HL) IN=C2			D=10
PUSH PSW			E=08
A TO (SP-1)		•	H=02
F TO (SP=2)	SP-2=00	D 4	L=4P
ADC L A=A+L+1	A = 4 1	F=06	
PUSH PSW			
A TO (SP-1)			
F TO (5P+2)	SP-2=00	02	
ADC A A=A+A	A=82	F=86	
PUSH PSW			
A TD (SP-1)			
F TN (SP-2)	SP-2=00	DØ	
SUB B A=A-B -	A=7E-	F=06	
PUSH PSW			
A TO (SP-1)			
F TO (SP-2)	SP-2=00	CE	
SUB C A=A+C	A=5E	F=12	
PUSH PSW			
A TO (SP-1)		·	
F TO (SP-2)	SP-2=00	CC	
SUB D A=A-D	A=4E	F = 16	
PUSH PSW	•		

NOP				
A TO	(SP-1)			
F TO	(SP-2)	SP=2=0	A J &	
SUBE	A=A-E	A=46	F=12	
PUSH P	SW			
A TO	(SP-1)			
FTO	(SP-2)	SP-2=0	008	
SUB H	A = A - H	A=44	F=16	
PUSH P	SW			
A TO	(SP-1)			
F TO	(SP-2)	SP-2=0	006	
SUB L	A = A - L	A=04	F=12	
PUSH P	SW			
A TO	(SP-1)	•		
F TO	(SP-2)	SP=2=2	204	
SUB A	A = A = A	A=00	F=56	
PUSH P	SW			
A TO	(SP-1)			
FTO	(SP-2)	SP-2=9	0C2	
SUB M	A=A-(HL)		
(ዞ닎)	IN=FF	A=01	F=03	
PUSH PSW				
A TO	(SP-1)			
F T0	(SP-2)	SP=2=01	100	
588 B	A=A-B-1	A=FC	F≖87	
PUSH PSW				

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NOP	
A TO (SP-1)	
F TO (SP-2)	SP=2=908E
SBB C A=A-C-1	A=DB F=96
PUSH PSW	
A TO (SP-1)	
F TO (SP=2)	SP-2=00BC
SBB D A=A-D	A=CB F=92
PUSH PSW	
A TO (SP-1)	
F TO (SP-2)	SP-2=008A
SBB E A=À-E	A=C3 F=96
PUSH PSW	
. A TO (SP-1)	
F TO (SP-2)	SP-2=0088
SBB H A=A-H	A=C1 F=92
PUSH PSW	
A TO (SP-1)	
F TO (SP-2)	SP-2=0086
SBB L А=А-L	A=81 F=96
PUSH PSW	
A TO (SP-1)	
F TO (SP-2)	SP-2=0084
SEB M A=A-(HL))
(HL) IN=82	A=FF F=87
PUSH PSW	

NOP
A TO (SP-1)
F TO (SP=2) SP=2=0082
SBB A A=A-A-1 A=FF F=87
PUSH PSW
A TO (SP-1)
F TD (SP-2) SP-2=0080
ADI A=A+(B2)
82=01 A=00 F=57
PUSH PSW
A TO (SP-1)
F TO (SP-2) SP-2=00AE
ACI A=A+(B2)+1
B2=FF A=00 F=57
PUSH PSW
A TO (SP-1)
F TO (SP-2) SP-2=00AC
SUI A=A-(B2)
B2=01 A=FF F=87
PUSH PSW
A T(1 (SP-1)
F TO (SP-2) SP-2=00AA
SBI A=A-(B2)-1
82=40 A=BE F=96
PUSH PSW
A TO (SP-1)

NOP		•	
F TO (SP-2)	SP-2=0048		
ORA B A IOR B	A=BE	F=86	A=BE
PUSH PSW			B=Ø4
A TO (SP-1)	. · ·		C = 20
F TO (SP=2)	SP-2=0046	· ·	D=10
XRA B A XÓR B	A=BA	F=82	E=08
PUSH PSW			H=02
A TO (SP-1)			L=40
F TO (SP-2)	SP-2=00A4		
ORAC A IOR C	A=BA	F=82	
PUSH PSW			
A TO (SP-1)			
F TO (SP-2)	SP-2=00A2		
XRA C A XOR C	A = 9 A	F=86	
PUSH PSW			
A TO (SP-1)			
F TO (SP-2)	SP=2=00A0		
ORA D A IOR D	A = 9 A	F=86	
PUSH PSW			
A TO (SP=1)			
F TD (SP+2)	SP-2=009E		
XRA D A XOR D	A=8A	F=82	
PUSH PSW			
A TO (SP-1)			
F TO (SP-2)	59-0+840C		

NOP ORA E A IOR E A=8A F=82 PUSH PSW A TO (SP-1) F TO (SP-2) SP-2=0094 XRA E A XOR E A=82 F=86 PUSH PSW A TO (SP-1) F TO (SP=2) SP=2=0098 ORA H A IOR H A=82 F=86 PUSH PSW A TO (SP-1) F TO (SP-2) SP-2=0096 XRA H A XOR H A=80. F=82 PUSH PSW A TO (SP-1) F TO (SP-2) SP-2=0094 ORALAIORLA=CØ F=86 PUSH PSW A TO (SP-1) F TO (SP=2) SP=2=0092 XRAL A XORL A=80 F=82 PUSH PSW A TO (SP-1) F TO (SP=2) SP=2=0090 ORA A A IOR A A=80 F=82

NOP		••
PUSH PSW		
A TO (SP-1)		1
F TO (SP-2) SP-2=008E		
XRAA AXORA A=00	F=46	
PUSH PSW		
A TO (SP-1)		
F TO (SP-2) SP-2=008C		
ORA M A IOR (HL)		,
(HL)IN=BE A=BE	F=86	
PUSH PSW		
A TO (SP-1)		
F TO (SP-2) SP-2=008A		
XRA M A XOR (HL)		
(HL)IN=78 A=C6	F=86	
PUSH PSW		
A TO (SP-1)		• .
F TO (SP-2) SP-2=0088		
ANA M A=A AND (HL)		
(HL)IN=FC	A=C4	F=92
PUSH PSW		
A TO (SP-1)		
F TO(SP-2) SP-2=0086		
ANA A A=A AND A	A = C 4	F=82
PUSH PSW		
A TO (SP-1)		

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NOP				
F TO	(SP-2)	SP-2=0084		
ANA B	A=A AND	8	A = 9 4	F=02
PUSH P	SW	· ` .		· · · · · · · · · · · · · · · · · · ·
A TO	(SP-1)			
F 10	(SP-2)	SP-2=0082	·	
ORI	A=A INR	(82)		
82=70	:		A = 7 C	F=02
PUSH P	SW			
A TO	(SP-1)			
FTO	(SP=2)	SP-2=0080		
ANA. C	A=A AND	С	A=20	F=12
PUSH F	PSW			
A TO	(SP-1)			
F TO	(SP-2)	SP-2=007E		
ANI	A=A AND	(82)		
82=65	5		A=20	F=02
PUSH P	S.₩			
A TO	(SP-1)			
F 10	(SP-2)	SP-2=007C		
XRI	A=A XOR	(82)		
82=50	2		A=7C	F=02
PUSH P	2 S W		•	
A 10	(SP-1)			
F 10	(SP-2)	SP-2=007A		
ANA D	A=A AND	0	A = 10	F=12

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			-
NOP .			
PUSH PSW			
A TO (SP-)	1)		
F TO (SP+2	2) SP-2=0078	· ·	A=10 -
CMP C A+C	F=97		B=04
PUSH PSW			C=20
A TO (SP-)	1)	•	D=10
F TO (SP+2	2) SP-2=0076		E=08
RAR	A = 8.8	F=96	H=02
PUSH PSW			L=40
A TO (SP-1	1)		
F TO (SP-2	2) SP-2=0074		
ANA E A=A	AND E	A=08	F=12
PUSH PSW			
A TO (SP-1	1)		
F TQ (SP+2	2) SP-2=0072		
RAR		A = Ø 4	F=12
PUSH PSW			
A TO (SP-)	1)		
F TO (SP-2	2) SP-2=0070		
RRC		A = 0.2	F=12
PUSH PSW			
A TO (SP-1	1)		
F TO (SP-2	2) SP-2=006E		
ANA H A=A	AND H	A=02	F=02
PUSH PSW			

NOP A TO (SP-1) F TO (SP-2) SP-2=906C RLC A=04 F=02 PUSH PSW A TO (SP-1) F TD (SP-2) SP-2=006A CMP A A-A F=56 PUSH PSW A TO (SP-1) F TO (SP-2) SP-2=0068 CMP B A-B F=56 PUSH PSW A TU (SP-1) F TO (SP-2) SP-2=0066 CMP D' A-D F=93 PUSH PSW A TO (SP=1)F TO (SP-2) SP-2=0064 CMP E A-E F=87 PUSH PSW A TO(SP-1) F TO(SP-2) SP-2=0062 CMP H A-H F=12 PUSH PSW A'TO (SP-1)

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NOP F TO (SP-2) SP-2=0060 CMP M A-(HL) F=12 (HL)IN=00 PUSH PSW A TO (SP-1) F TO (SP=2) SP=2=005E CMP L A-L E=93 PUSH PSW A TO (SP-1) F TO (SP=2) SP=2=005C A=09 F=92 RAL PUSH PSW A TO (SP-1) F TO (SP-2) SP-2=005A ORAL A=A IOR L A=49 F=02 PUSH PSW A TO (SP-1) F TO (SP-2) SP-2=0058 ANA LA=AAND L A=40 F=12 PUSH PSW A TO (SP=1) F TO (SP-2) SP-2=0056 CPI A-(82) F=07 B2=FF PUSH PSW

NOP			
A TO (SP-1)			
F TO (SP-2)	SP-2=0054		
RLC		A = 8 Ø	F=06
PUSH PSW			
A TO (SP-1)		•	
F TO (SP-2)	SP-2=0052		
RLC		A = 0 1	F=07
PUSH PSW			
A TO (SP-1)			
F TO (SP-2)	SP-2=0050		
RRC		A = 8 Ø	F=07
PUSH PSW	· .		-
A TO (SP-1)			
F TO (SP-2)	SP-2=004E		
RAL		A = Ø 1	F=07
PUSH PSW		•••	
A TO (SP-1)			
F TO (SP=2)	SP=2=004C	· .	
JMP (8382) TO	PC		
BS			
B3			
JC (8382) TO	PC (CARRY	(=1)	
BS			
83			
JNC NO JUMP,C	ARRY=1		

NOP			
ВS		A = Ø 1	
83		F=07	
JZ	NO JUMP, ZERO=0	CARRY, PARITY	SET
82			
83			
JNZ	(B3B2) TO PC		· .
82			
83			
JM	NO JUMP, SIGN=0		
B 2			
83	· ·		
JP	(B3B2) TO PC		
82	· · ·		
83			
JPE	(8382) TO PC PARITY=1		
B2	•	÷ ,	
83			
JP0	NO JUMP		
82			
B 3	• •	•	
CALL	(B3B2) TO PC		
82			
83	PC+1		
РСН	TO (SP-1)	`	
PCL	10 (SP-2) SP-2=0044	•	

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NOP
RET
(SP) TO PCL
(SP+1) TO PCH SP+2=004C
CC CALL, CARRY=1 (B382)TO PC
B2
83 PC+1
PCH TO (SP-1)
PCL TO (SP-2) SP-2=004A
RC RET, CARRY=1
(SP) TO PCL
(\$P+1) TO PCH SP+2=004C
CNC NO CALL, CARRY=1
В2
83
RNC NO RET, CARRY=1
CZ NO CALL, ZERO=0
B2
83
RZ NO RET, ZERO=0
CNZ CALL,ZERD=0 (8382) TO PC
B2
83 PC+1
PCH TO (SP+1)
PCL TO (SP-2) SP-2=004A
RNZ RET, ZERD=0

NOP	
(SP)	TOPCL
(SP+1)	TO PCH SP+2∍004C
CM NO	CALL,SIGN=0
82	
83	
RM NO	RET, SIGN=0
CP CA	LL,SIGN=0 (B3B2)TO PC
B2	
83 PC	+ 1
РСН ТО	(SP-1)
PCL TO	(SP-2) SP-2=004A
b b	
(SP)	TO PCL
(SP+1)	TO PCH SP+2=004C
CPE C	ALL,PARITY=1 (B3B2)TO PO
8 2	
83	PC+1
РСН ТО	(SP+1)
PCL TO	(SP-2) SP-2=004A
RPE R	ET, PARITY=1
(SP)	TO PCL
(SP+1)	TO PCH SP+2=004C
CPO NO	CALL, PARITY=1
BS	
83	

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NOP RPO NO RET, PARITY=1 POP PSW (SP) TO F A=03 (SP+1)TO A SP+2=004E F=C2 PUSH PSW (SIGN,ZERO=1) A TO (SP-1) F TO (SP=2) SP=2=004C JMP (B3B2) TO PC 82 вз ¹ JC NO JUMP, CARRY=2 B2 83 (B3B2) TO PC JNC 82 B3 · (B3B2) TO PC JZ 82 83 NO JUMP, ZERO=1 JNZ B2 83 JM (8382) TO PC SIGN=1 85 83

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NOP		
JP NO JUMP		
B S		
B 3		
JPE NO JUMP,	PARITY=0	1
B5		
В3		
JPD (8382) TO	PC	
B2		
83		
CALL (B3B2) TO	PC	
85		
83	PC+1	
PCH TO (SP-1)	•	
PCL TO (SP-2)	SP-2=004A	
RET		
(SP) TO PCL	•	
(SP+1) TO PCH	SP+2=004C	
CC NO CALL,C	ARRY=0	
B2		
B3	۱	
RC NO RET		
CNC (8382) TO	PC , CARRY=0	
B2		
83	PC+1	
PCH TO (SP-1)		

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NOP
PCL TO (SP-2) SP-2=004A
RNC RET, CARRY=0
(SP) TO PCL
(SP+1) TO PCH SP+2=004C
CZ CALL, ZERO=1
B2 (B3B2)TO PC
B3 PC+1
PCH TO (SP-1)
PCL TO (SP-2) SP-2=004A
RZ RET
(SP) TO PCL
(SP+1) TO PCH SP+2=004C
CNZ NO CALL, ZERO=1
82
B 3
RNZ NO RETURN
CM CALL,SIGN=1 (8382) TO PC
B2
83 PC+1
PCH TO (SP-1)
PCL TO (SP-2) SP-2=004A
RM RETURN
(SP) TO PCL
(SP+1) TO PCH SP+2=004C
CP NO CALL, SIGN=1

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	NOP				
•	NUF			•	
	82				
	83		·		
	RP NO	RET			
	CPE NO	CALL, PARITY=0		·	
	85				
	B 3		· · ·	•	
	RPE NO	RET			
	CPO CA	LL, PARITY=0 (B	382) TO PC		
	BS				
	В3	PC+1			
	PCH TO	(SP-1)			
	PCL TO	(SP-2) SP-2=00	4 6		
	RPO RE	TURN			
	(\$P)	TO PCL			
	(SP+1)	TO PCH SP+2=00	40	-	
RST AT UNON PC+1					
	PCH TO	(SP-1)			
	PCL TO	(SP-2) SP-2=00	4 A		
	RET				
	(SP)	TO PCL			
	(SP+1)	TO PCH SP+2=00	4C		
RST AT 0008 PC+1					
	РСН ТО	(SP-1)			
	PCL TO	(SP-2) SP-2=00	44		
	n C T				

RET

NOP (SP) TO PCL (SP+1) TO PCH SP+2=004C RST AT 0010 PC+1 PCH TO (SP-1) PCL TO (SP=2) SP=2=004A RET (SP) TO PCL (SP+1) TO PCH SP+2=004C RST AT 0018 PC+1 PCH TO (SP-1) PCL TO (SP-2) SP-2=004A RET (SP) TO PCL (SP+1) TO PCH SP+2=004C RST AT 0020 PC+1 PCH TO (SP-1) PCL TO (SP-2) SP-2=004A RET (SP) TO PCL (SP+1) TO PCH SP+2=004C RST AT 0028 PC+1 PCH TO (SP-1) PCL TO (SP-2) SP-2=004A RET (SP) TO PCL
NOP (SP+1) TO PCH SP+2=004C RST AT 0030 PC+1 PCH TO (SP-1) . PCL TO (SP-2) SP-2=004A RET (SP) TO PCL (SP+1) TO PCH SP+2=004C RST AT 0038 PC+1 PCH TO (SP-1) PCL TO (SP-2) SP-2=004A RET (SP) TO PCL (SP+1) TO PCH SP+2=004C NOP



FIGURE 12: Program Counter Test

not checked is the Register Transfer to the Program Counter. This operation is verified during the Register Array Test.

Register Array Test

The test on the Register Array is accomplished by two tests. One verifies that each register is independent of any other register, and two, that any register can be moved from one register to another with any data combination. The test to determine uniqueness of each register is to first load each register (B, C, D, E, H, and L) with unique data and read to verify the load operation. The test is performed using the instruction shown in Table 2. An explanation of the instruction mnemonics appears in Table 3.

The next test on the Register Array will verify that the registers can move from one register to another and move any data combination. This test will also check register-to-Program Counter transfers. This recommended test loads the H and L registers directly with a pattern of 0's, transfers the H register contents to all other registers, and outputs from the H and L registers through the Program Counter. The pattern is incremented until all 256 numerical combinations have been checked. A flow chart of this test is illustrated in Figure 13. The instructions that should be used for this test are LXIH, PCHL, and MOV_{r1 r2}.

Stack Pointer Test

The Stack Pointer test is just like the Program Counter test, both

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Instru	ction	Register	Value
- 1.	MVI	A	(000)8
2.	MVI	B .	(001) ₈ o
3.	MVI	C ·	(002) ₈ d
4.	MVI	D	$(004)_8$ $\left< \begin{array}{c} R \\ o \end{array} \right>$
5.	MVI	E	(010) ₈ t
6.	MVI	Н	(020) ₈ i
7.	MVI	L	(040) ₈ / e
8.	LXI	SP	(125) ₈ (252) ₈
9.	MO.V	M,A	e
10.	MOV	M,B	t s
11.	MOV	M,C	R
12.	MOV	M,D	0 U +
13.	MOV	M,E	i i
14.	MOV	M,H	- / e
15.	MOŅ	M,L	

TABLE 2: <u>Register Array Test</u>

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				Inst	tructi	on E	080	IJ.		Clock 121	1				Inst	veni	on C	o de l'	1		Clock (7)
Marmanic	Description	07	06	05	04	D	, D ₂	0	, Do	Çycles	· Mnemonic	Description	07	Dg	05	04	Dj	Dy	0	00	Cycles
MOV.12	Move register to register	0	!	0	0	Ð	ş	ş	S	. 5	RZ -	Réturn on zero	1	1	0	0	1	0	0	0	5/11
	Move register to memory	0	1.			Ň		3				Keturn on no zero	1	1	0	u .	0	0	C	0	5/11
NIT	Nove memory to register	ň	÷.	,		0	-	-		,	84	Return on positive		-	2				0	2	5/11
MVIC	Move immediate register	ŏ	ò	0	'n	Ď	i	÷	ň	;	APF	Return on nanty even		1	-	÷	-	Ň	0	ň	5/11
MVIM	Move immediate memory	ō	ŏ	ī	ĩ	ō	i	i	ŏ	10	BPO	Return on parity odd	- 1	÷	÷	ň		ň	ň	ň	5/11
INA /	Increment register	ō	ō	ò	Ď	ō	j.	ò	ŏ	5	RST	Apatart	j	i		Ă	Ă	ĭ	ĭ	š	11
DCR	Decrement register	ō	ō	Đ	Ď	Ď	1	ō	1	5	IN	input	i	í	õ	ĩ	ĩ	ó	í	í	10
INR M	Increment memory	Ō	Ō	1	1	0	1	ō	0	10	001	Outout	i	i	ŏ	i	å	õ	i	i	10
DCR M	Decrement memory	0	0	1	1	0	1	0	1	10	LXI B	Load immediate register	ò	ò	ō	ò	ō	õ	Ó	i	10
A00 r	Add register to A	1	0	0	0	0	S	s	s	4		Parr B & C	-	-	-	-	•	-	•		
ADC r	Add register to A with carry	1	0	0	0	1	S	5	S	4	LXID	Load immediate register	0	0	0	1	0	0	0	1	10
SUBr	Subtract register from A	1	0	0	1	0	S	5	S	4		Paur D & E					-	-	-		
SBBr	Subtract register from A	1	0	0	1	1	5	S	S	4	LXIH	Load immediate register	0	.0	1	0	0	0	0	1	10
	with borrow											Pair H & L									
ANA r	And register with A	1	0	1	0	0	S	5	* s -	4	LXI SP	Load immediate stack pointer	0	0	1	1	0	0	0	1	10
XRAr	Exclusive Or register with A	1	0	1	0	1	5	5	\$	4	PUSH B	Push register Pair B & C on	1	1	0	0	0	1	0	T I	
ORA r	Or register with A	1	0	1	1	0	\$	S	S	4		stack									
CMPr	Compare register with A	1	0	1	1	1	S	S	\$	4	PUSH D	Push register Pair D & E on	1	1	0	1	0	1	0	1	11
ADD M	Add memory to A	1	0	٥	0	0	3	3	0	7	ł	stack									
ADC M	Add memory to A with carry	1	0	0	0	1	1	1	0	7	PUSH H	Push register Pair H & L on	1	1	1	0	0	1	0	1	11
SUB M	Subtract memory from A	1	0	0	1	0	1	1	0	1		stack									
588 M	Subtract memory from A	1	0	0	1	1	1	1	0	7	PUSH PSW	Push A and Flags	1	1	1	1	0	1	0	1	11
	with borrow											on stack									
ANA M	And memory with A	1	0	1	0	0	1	1	0	7	POP 8	Pop register pair B & C off	1	1	0	0	0	0	0	1	10
XRA M	Exclusive Or memory with A	1	0	1	0	1	1	1	0	7		stack									•
ORA M	Or memory with A	1	0	1	1	0	1	1	0	7	POP D	Pop register pair D & E off	1	1	0	1	0	0	0	ŧ.	10
CMP M	Compare memory with A	1	0	1	1	1	1	1	0	7		stack									
ADI	Add immediate to A	1	1	0	0	0	1	1	0	7	POPH	Pop register pair H & L off	1	1	1	0	0	0	6	1	10
ACI	Add immediate to A with	r	1	σ	Q	1	T.,	r	a	7		stack								•	
	carry									· .	POP PSW	Pop A and Flags	1	1	1	1	0	0	0	1	10
501	Subtract immediate from A		!	ů.	1		:	!	0			off stack									
381	SUDIFACT IMMEDIATE TOM A	,	,	Û	'	'	'	,	V	,	SIA	Store A direct	0	0			0	0		0	13
	with corrow				•	•			•	,	LUA	Load A direct		0	2		1	0		0	13
YPI	And immediate with A	;	-	-	Ň	Ň	÷		Ň	1	XLHG	Exchange U & E, H & L	1		'	U	1	U	1	1	4
A.11	A	•		•			•	•		,		Frederik and all stack M R I				•	•	•		,	10
081	Or immediate with A	1		,		۵	1	1	n	7	CPUI	W & f to stack pourse		-	-					;	6
CPI .	Compare immediate with A	i	i	i	i	ĩ	i	i	ő	'n	Prwi	H & I to program coupler			÷			ň	ň		5
RLC	Rotate A left	ò	ò	ò	ò	Ó	i	i	ĩ	4	DADB		'n	'n	'n	ň	÷	õ	ň	÷.	10
RRC	Rotate A right	ŏ	ō	õ	õ	ī	1	1	i	i.	DADD		ň	ň	ň	ň	÷	ŏ	ň	÷	10
RAL	Rotate A left through carry	ā	ō	Ď	ĩ	Ó	i	1	i	i.	DADH		ň	ň	ĭ	ò	i	ň	ň	÷	10
RAR	Rotate A right through	ō	ā	õ	1	1	1	1	1	4	DAD SP	Add stack nounter in H.& I	ň	ň	i.	ĩ	÷	ň	ñ	÷	10
	Carry										STAX 8	Store A indirect	ō	ŏ	ò	ò	ò	õ	ĭ	'n	,
JMP	Jump unconditional	1	1	0	0	0	0	1	1	10	STAX D		ō	ō	.0	ĩ	ō	ň	;	ŏ	· ·
JC	Jump on carry	1	1	0	1	1	0	1	0	10 .	LOAXB	Load A indirect	ō	ō	õ	ů.	ī	ō	i	ō	,
JNC	Jump on no carry	1	1	0	1	0	0	1	0	10	LDAX D	Load A indirect	ō	õ	ō	ĩ	-1	ō	1	ō	,
JZ	Jump on zero	1	1	0	0	1	0	1	0	10	INXB	Increment B & C registers	ō	ō	0	Ó	0	ō	1	i.	5
JN Z	Jump on no zero	1	1	0	0	0	0	1	0	10	INX D	Increment D & E registers	ō	ō	ō.	` ī	ō	õ	1	i	ŝ
9L	Jump on positive	1	1	1	1	0	0	1	0	10	INXH	Increment H & L registers	Ō	0	1	٥	ō	0	1	i	5
JM	Jump on minus	1	1	1	1	1	0	1	0	10 .	INX SP	Increment stack pointer	ŏ	õ	1	ĩ	ō	õ	1	i	5
JPE	Jump on parity even	1	1	1	0	1	0	1	0	10	DCX 8	Decrement B & C	Ō	ō	0	0	1	õ	1	1	5
JPO	Jump on parity odd	1	1	1	0	0	0	,	0	10	DCXO	Decrement D & E	٥	ō	٥	1	T	ō	1	1	5
CALL	Call unconditional	1	1	0	0	1	1	0	1	17	ОСХН	Decrement H & L	0	Ó	1	0	1	0	1	1	5
CC	Call on carry	1	1	0	1	1	11	0	0	11/17	OC X SP	Decrement stack pointer	0	0	1	1	١	0	1	١	5
CNC	Call on no carry	1	1	0	1	0	1	Ũ	0	11/17	CMA	Complement A	0	0	1	0	1	1	1	1	4
C2	Call on zero	1	1	0	0	1	1	0	0	11/17	STC	Set carry	0	0	1	1	0	1	1	1	•
CNZ	Call on no zero	1	1	0	0	0	1	0	0	11/17	СМС	Complement carry	0	0	1	1	1	1	1	1	4
CP	Cell on positive	1	1	1	1	0	1	0	0	11/17	DAA -	Decimal adjust A	0	0	1	0	0	1	1	1	4
CM	Call on minus	1	1	1	1	1	1	0	0	11/17	SHLD	Store H & L direct	0	0	1	0	0	0	1	0	16
CPE	Call on parity even	1	1	1	0	1	1	0	0	11/17	LHLO	Load H & L direct	0	0	1	0	1	0	1	0	16
CPO	Call on parity odd	1	1	1	0	0	1	D	0	11/17) E;	Enable Interrupts	1	1	1	1	1	0	1	1	4
RET	Return	1	1	0	0	1	0	0	١	10	Di	Disable interrupt	1	1	1	1	0	0	1	1	4
RC	Return on carry	1	1	0	1	1	0	0	0	5/11	NOP	No-operation	0	0	٥	٥	0	0	0	0	4
RNC	Return on no carry	1	1	0	-1	0	0	0	0	5/11	}			•							
											1										
											•										

NOTES: 1. DDD or SSS - 000 B - 001 C - 010 D - 011 E - 100 H - 101 L - 110 Memory - 111 A.
 2. Two possible cycle times, (5/11) indicate instruction cycles dependent on condition flags.

TABLE 3: 8080 Instruction Mnemonics



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FIGURE 13: Register Array Test

are 16-bit registers with the additional feature of incrementing and decrementing. Therefore, the test on the Stack Pointer should check for incrementing and decrementing, and the ability to load and transfer to another register. Figure 14 is a flow chart of a recommended test and Table 4 lists the instructions used during the test.

Accumulator Test

The accumulator in the 8080 is 8-bits wide. A recommended test on the accumulator is to verify, load, readback, rotate, and transfer operation through its entire range. The recommended instructions (see Table 1) to be used during this test are $MOV_{A,M}$, $MOV_{M,A}$, CMA, RCL, RRC, RAL, and RAR. A flow chart of the recommended test is shown in Figure 15.

Arithmetic Logic Unit Test

The Arithmetic Logic Unit (ALU) is 8-bits wide and used to perform all arithmetic and logical data operations in the 8080. The ALU has been left until last because error analysis is simplified once all other modules have been verified. A recommended test for the ALU is to test all ALU data paths and related instructions through its range. All instructions are used during this test which operation on the ALU, such as ADD, ADC, SUB, SBB, etc. A flow chart of this recommended test is shown in Figure 16.

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FIGURE 14: Stack Pointer Test

MNEMONICS	CYCLES	CLOCKS	CODE (DATA WORD) 7654321Ø	OPERATION
LXIH	3	10	00100001	
<b2></b2>				<b<sub>2>(L)</b<sub>
<b3></b3>				<b<sub>3>(H)</b<sub>
SPHL	1	5	11111001	(H) (L) (SP)
INXSP	1	5	00110011	(SP) + 1 (SP)
DADSP	3	10	00111001	(H) (L) + (SP) → (H) (L)
PCHL	1	5	11101001	(H) (L)(PC)
DCXSP	1	5	00111011	(SP) - 1 (SP)
PUSHPSW	3	11	11110101	(A) → [SP-1],(F) → [SP-2]



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FIGURE 16: Arithmetic Logic Unit Test

B. 8008

The test program for the 8008 is divided into the major sections listed below.

1. Accumulator

2. Register Array

3. Arithmetic Logic Unit (ALU)

4. Address Stack

5. Input/Output Instruction

6. Halt and Interrupt

Accumulator

The accumulator of the 8008 is part of the scratch pad register array with an address of $\emptyset \emptyset \emptyset_7$. This register is a working register for the arithmetic and logical instructions. Intially, a verification test would be implemented in a series of MOV instructions to load and store data to verify the basic functionality. Data patterns should consist of all 1's, all 0's, CHECKERBOARD, inverted CHECKERBOARD, 1_7 , 2_7 , 4_7 , 10_7 , 20_8 , 40_8 , and 100_8 .

Register Array

The scratch pad register array test is designed to verify that each register can increment and decrement throughout its entire range, that each

register can be transferred to all other registers of the array, and that the H and Z registers can properly provide a correct address for the $MOV_{R,M}$ and $MOV_{M,R}$ instructions.

Initially the device is reset and all registers of the array loaded to a different value with the $MOV_{R,M}$ instruction, except register R which is set to 0. Register Rl is now incremented from 0 to 255 to 0, to verify the wrap-around characteristic. After each increment, the contents of the register is examined using the $MOV_{M,R}$ instruction.

At the completion of this process, the contents of all remaining registers are stored and verified. Register Rl is now decremented from 0 to 255 to 0, verifying the underflow characteristic. After each decrement, the register contents are stored and verified using the $MOV_{M,R}$ instruction. At the completion of this process, the contents of all other registers are read and verified.

The increment/decrement test is now performed on all remaining registers of the array.

Transfer Operations

In order to accomplish transfer operations and preserve the unique identification of all other registers, the previously verified instructions of $MOV_{R,M}$, VMIr, $MOV_{M,R}$, INRr, and DECr will be used. Initially

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all registers are cleared. Register R1 will be tested first. Register R1 is incremented and transferred to R2. R1 is again incremented and transferred to R3. This process is repeated until all registers have received data from R1. The accumulator is the last register to receive data. All register contents are now stored and verified starting the the accumulator. After repeating this process 42 times, the sequence is repeated, only this time register R2 is used as the origin of all data to be transferred. All remaining registers, except the accumulator, are verified in the same manner.

Since the accumulator cannot increment, the test for verification of transfer is accomplished in a slightly different manner. Again, all registers are set to O. Register B is then incremented and transferred to the accumulator, which is in turn transferred to register C. Register B is again incremented and transferred to the accumulator, which is now transferred to register D. This process is repeated until all registers have received data from the accumulator. All register contents are now stored and verified. This process is repeated 51 times. During this test procedure the transfer of the accumulator contents to register B is not possible, since register B is being used to generate the test pattern internal to the device. Therefore, it is necessary to repeat this test using register C to generate the internal test pattern, transferring its contents to the accumulator and then transferring the accumulator to register B, incrementing register B, and then storing all registers. The purpose of incrementing register B is to preserve the unique addressing of that register for transfer verification.

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Arithmetic Logic Unit (ALU)

The previously verified instructions are now utilized to test the add, subtract, logical, and shift instructions. Results of the add and subtract instructions effect all condition flip-flops, while the rotate and shift instructions effect only the carry bit. The logical instructions do not effect the condition flip-flops.

The condition flip-flops cannot be gated to the data or address bus for purposes of verification. Therefore, it will be necessary to use the conditional jump instructions, JC, JZ, JM, JPE, JNC, JNZ, JP, and JPO.

After each arithmetic operation it is necessary to execute all six conditional jump instructions to test for proper operation of the condition flip-flops.

The data chosen should generate the criteria to set and reset all condition flip-flops resulting in patterns that will verify that the ALU can recognize a O, negative number, even parity, and a carry, or borrow.

The data patterns required for proper verification of the ALU should be designed such that execution of the arithmetic or logical instruction being tested generates the following results:

Arithmetic Instruction

- 1. Positive Number
- 2. Negative Number
- 3. Even Parity
- 4. Non-Even Parity
- 5. Carry (Borrow)
- 6. No Carry (Borrow)
- 7. Zero Value
- 8. Non-zero Value

Logical Instructions

- 1. Positive Number
- 2. Negative Number
- 3. Zero Value
- 4. Non-zero Value
- 5. Even Parity
- 6. Non-Even Parity

Rotate Instructions

- 1. Carry
- 2. No Carry
- 3. Shift a 1 Through Carry
- 4. Shift a O Through Carry
- 5. Shift a 1 Through a Field of O's
- 6. Shift a O Through a Field of O's

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Address Stack

Testing of the address stack is designed to verify that all levels of the stack are operative in response to the CALL and RETURN instructions. The device test program simulates repeated subroutine CALL's and RETURN's nesting up to the seven allowable levels. The program should be structured so that the carry feature from the lower order 8bits of the address to the higher order 6-bits is verified. In addition, all conditional CALL and conditional RETURN instructions are verified. The jump instruction should also be included in this test as an easy means of manipulating the contents of the Program Counter in generating the return addresses to be stored in the address stack.

Input/Output Instructions

Verification of the input/output instructions consist of executing a series of eight input instructions each followed by an output instruction. During this sequence, the code for the selected input and output port is different so that all combinations are tested. The actual data used to write into the accumulator is not of critical importance.

Halt and Interrupt

The Halt instruction and Interrupt feature of the 8008 can be tested together. The Interrupt is verfied first. The critical parameter of the Interrupt is that the interrupt signal to the 8008 cannot be allowed

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to occur within 200 ns of the falling edge of \emptyset 1.

The test program should verify that the 8008 will properly respond to an external interrupt which occurs within the allowable timeframe as indicated below. In addition, the Interrupt signal to the 8008 should be applied during all time states of instruction execution.

After this test, the Halt instruction is executed and the ability of the 8008 to respond to an external interrupt is verified over the same time span by executing a series of Halt instructions followed by Interrupts.



The 2901 4-bit bipolar microprocessor slice is not like other microprocessors being only the process portion of the typical microprocessor. Like the typical microprocessor, the 2901 has a data bus, but is not bidirectional. It also provides a register file (16 Word X 4-bits), an Accumulator (4-bits), and an Arithmetic Logic Unit (ALU).

The 2901 does not include an instruction decoder, rather all instructions directly control an operation from an code input. In a typical MPU the instruction code applied on the data bus into the decoder for the complete cycle. The 2901 complete cycle lasts only one clock cycle and if the instruction lines change during the cycle a new operation will occur. Also, the 2901 is not capable of addressing external memory directly, because it does not include an address or program counter. A typical MPU can execute jumps, subroutines, and return from subroutines due to the existance of a stack pointer which the 2901 does not contain.

The architecture of the 2901 can easily be broken up into testable modules that can be controlled and tested by the device pins and its microinstructions (see Figure 2).

The 2901 can be broken up into the following modules:

RAM (16 addressable registers) controlled by the "A" address field.
 RAM (16 addressable registers) controlled by the "B" address field.

C. 2901

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- 3. "Q" Register or Accumulator
- 4. ALU Source Selector
- 5. Eight Function ALU
- 6. Output Data Selector
- 7. RAM Shift
- 8. "Q" Shift

Examination of the microinstruction control shows that the 2901 has a 9-bit microinstruction. This microinstruction is divided into three groups: ALU source control, ALU function control, and destination control. The ALU source control controls from what data path the data will be applied into the ALU (Table 5). The ALU function controls what function the ALU will perform. For example, R field + S field, R field or S field, etc., (Table 6). The destination control routes the output of the ALU (or RAM) to different destinations within the 2901. These destinations include the RAM register stack, the "Q" register accumulator, both the RAM and "Q" register or the RAM directly out of the device (Table 7). The microinstruction controls thus route and/or manipulate data through the device.

RAM Addressable Register Test

The RAM Address Register should be divided up into four unique portions structured to test (1) the RAM using the "A" address stored through the output by passing the ALU, (2) the RAM using the "A" address outputted through the ALU, (3) the RAM using the "B" address

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	MIC	ALU SOURCE OPERANDS			
1 ₂	I	1 ₀	R	S	
L	L	L	0	A	·Q
L	L	H	1	A	В
L	Н	L	2	• 0	Q
۲. ۲	H	н	3	0	В
Н	L	L __	4	0	A
н	L	Н.	5	D	A
Н	Н	L	[.] 6	D	Q
н	H	н	7	D	0

TABLE 5: ALU Source

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	MICRO	CODE		ALU	Symbol
I ₅	I ₄	^I 3	Octal Code	Function	
. L	L	L	0	R Plus S	R + S
L	L	H	1	S Minus R	.S – R
Ľ.	Н	L	2	R Minus S	R – S
L	Н	Н	. 3	RORS	RVS
н	L	L	4.	R AND S	RĄS
Н	L	Н	5	\overline{R} and s	RΛS
Ĥ	Н	L	6	R EX-OR S	R¥-S
н	н	Н	6	R EX-NOR S	R - A S

.

TABLE 6: ALU Function Control

	MICRO CODE			FUN	RAM	Q-RE Fun	GISTER	Ŷ	· RA SHIF	M	Q SHIFTER		
^I 8	I 7	^I 6	OCTAL CODE	SHIFT	LOAD	SHIFT	LOAD	001001	' RAM 0	RAM ₃	Q ₀	Q ₃	
L	L	L	0	X	None	None	F Q	F.	Х	Х	x	Х	
L	L	н	1	x	None	X	None	F	X	· X	x	X	
L	H	L	2	None	Б В	X	None	A	Х	X	x	x	
L	Н	H	3	None	. F →→ B	X	None	F	. X	Х	x	Х	
Н	L	L	4	Down	F/2→ B	Down	Q/2→Q	F	F _O	IN ₃	Q ₀	IN ₃	
H	L	H	5	Down	F/2→ B	X	None	F	F ₀	IN ₃	Q ₀	X	
Н	Н	L	6	Up	2F→ B	Up	2QQ	F	INO	F ₃	INO	Q3	
н	Н	H	7	Up	2F B	x	None	F	INO	F ₃	X	Q ₃	

X=Don't care. Electrically, the shift pin is a TTL input internally connected to a three-state output which is in the high-impedance state.
B=Register Address by B inputs.
Up is toward MSB.
Down is toward LSB.

TABLE 7: ALU Destination Control

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outputted through the ALU, and (4) the right/left shift operation of the RAM.

To test the RAM using the "A" address outputted bypassing the ALU, the following is recommended. The object of the test is to run a GALPAT pattern on the RAM using all combinations from 0 to 15 for the test pattern and the compliment of this as the background pattern. Since the RAM can only be written into a location addressed by the "B" address, care has to be taken to address only the test location when writing into the RAM. When a location is being tested or read, the "B" address should be different then the "A" address. The easiest solution to this would be to compliment the "B" address relative to the "A" address when reading a test cell. The setup to run this test would be to set the ALU source operand to octal code 7 (D,\emptyset) when writing into the RAN and octal code 4 (\emptyset ,A) when reading out a location. The ALU function is used during this test to route the data on the data input pin to the RAM. This should be programmed for a recommended function, octal code 3 (R OR S), as this will be used in a later test. The destination control should be programmed for octal code 2 which selects the RAM "A" data port to the output, bypassing the ALU. The clock pins should be held in a high state. Throughout this test the only pins that will be sampled will be the "Y" ouput pins. Once this test setup has been executed a GALPAT pattern should be performed using all test patterns of 0 to 15 and background patterns of 15 to 0. What the GALPAT does is to write a background pattern then write a test pattern. The test pattern is then read, a background

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pattern location read, then the test location again, then another background location, test location, etc., until all background locations have been read. Then the test pattern is moved and the process repeated until all locations have been used as a test pattern. The test pattern is then incremented and the background pattern decremented. This process is then continued until all pattern combinations have been tested (see Figure 17 for illustration).

Performing this test will verify that all data combinations can be written into and read out of with every data combination.

The second test on the RAM is to check the RAM addressed'by the "A" address field but checking the data output path through the ALU. The same test should be run as previously described with only one change in the microinstruction. This change would be to modify the destination control to an octal code 3. This modifies the output path from the RAM "A" address output to the ALU output. This would then check if the RAM "A" address path through the ALU is functional with all data sequences.

The next test on the RAM would be similar to the second test, but the "B" address and output path is checked. The changes to the second test would be to have addressing to the RAM entirely controlled by the "B" address field. During this test it is recommended that the "A" address field be the compliment of the "B" address. This would cause the worst interaction between the RAM addressing. The remaining difference would be to modify the ALU source operand to select octal code

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FIGURE 19: GALPAT Read Example

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3 when performing a read of the RAM. This will select a source of \emptyset , B, thus enabling the "B" output of the RAM to pass through the RAM.

The final test to be run on the RAM is verification of the right/ left shift operation. The recommended test will only describe a shift operation from the left as to test the right shift all that would be required is to input data from the right input and test the left output. The object of this test is to verify that all data combinations from 0 to 15 can be shifted through the RAM. Also, since latches are noted to be sensitive to noise, and the 4-bit output of the RAM uses a latch, the test will also recommend how to check for this. The recommended test sequence is as follows:

The test should start out by loading a 0 into location 0, and a 15 into location 15 of the RAM. The purpose of this is that one location will be used to shift data input and the other location will be used as a background test pattern. The microinstruction for the ALU source operation when writing the initial patterns should be an octal 7 which selects the data bus. All other times during the test an octal code 4 should be selected which selects "A" output latch for input to the ALU. (Note: An octal code of 3 should be selected when checking the "B" output latch.) The ALU function should be selected for an octal code 3 (R OR S) so that the output latch can be tested throughout the test. The advantage of using the R OR S function is that the ouput of the ALU will be the same as the output latch. The microinstruction for the destination control should be selected to octal code 4 which will execute

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a left shift. (Octal codes 5, 6, and 7 should also be tested using this same test. When selecting codes 6 and 7, the input and output shift pins should be complimented when codes 4 and 5 are selected.) The "A" and "B" address fields should be exactly the same throughout this test. This allows an easy modification to the ALU source operand to check the "B" output latch as described earlier. Last of all, the final setup should be to produce a clock pulse each time there is a requirement to write to the RAM, but not during a test cycle when the background location is being addressed.

The test on the right/left shift will verify that (1) the shift operation will occur, (2) this shift operation can shift all combinations of 1's and 0's, (3) the output latches will hold data, and (4) the shift operation can be accomplished using any RAM address. Following the initial loading of the test and background patterns one bit of the shift pattern (101000111100101) is shifted into the RAM and the shift and Y outputs checked. Then the background address is addressed but no clock is produced and the outputs again checked. This will verify that the output latch will hold data. The next bit is now shifted in and verified and the background location addressed and data verified. This process continues until all bits have been shifted into the RAM. Then the testword and background address are incremented and decremented, respectively, and the above test repeated. This will continue until all RAM locations have been used for the test location and background location. Upon completion of the first pass, the background pattern is decremented until the initial pattern has

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gone from 15 to 0. This will check for a sensitivity in the RAM output latches. This test is then repeated for both right and left shift operations on the RAM.

The next test performed is on the "Q" register. There should be two tests on the "Q" register. First, a test that will load the register with all combinations from 0 to 15 and follow each load with the compliment of the previous load. Second, a test to check the right/left shift operation on the register.

The first test should start by loading a "O" into the register and testing. Next a "15" should be loaded and tested, then 1, 14, 2, 13, ..., until a O and 15 are again reloaded. This test verifies that any number can be loaded into register and that all data tranactions are checked.

The second test checks the right/left shift of the "Q" register (ALU Destination Control, octal codes 4 and 6). To check these operations an initial value should be loaded into the register and checked. Destination control octal code 4 is selected and a pattern (1010000111100101) is shifted into the register. After each bit shift the register data is checked. Then an octal code is selected on the destination control and the other shift operation checked as previously described.

The next test will test the ALU source operands. This test verifies

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that all ALU sources can be selected and that all data combinations can pass through the selector. The test should start by first loading RAM locations 0, 5, 10, and 15 with data equal to the address. The "Q" register is intially loaded with a 0. Using the ALU function "R OR S" (octal code 3), and a destination control which loads neither the RAM nor the "Q" register (octal code 1), the sequence of ALU source operands shown in Table 8 should be tested. During this test the "A" and "B" address will equal the data being selected by the source operand.

The ALU functions and flags should be tested next, since all other sections of the devices have now been verified as operational. First, all locations in the RAM are loaded with a data pattern equal to its address. Then data values of 0, 5, 10, and 15 and RAM values of 0, 5, 10, and 15 and CN values of 0 and 1 in all combinations are used to test each of the eight possible ALU functions. In all cases, R is the data bus and S is the "A" output from the RAM (ALU source operand, octal code 5). First, the R & S function (octal code 0) is tested. The basic sequence is as shown in Table 9.

This sequence is then repeated for each of the other ALU functions.

Function	Octal Code
S - R	1
R - S	2
R OR S	3

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R		S
A = 1010		Q = 0000
A = 0101		Q = 0000
A = 1010		Q = 0000
	(Load Q with 1010)	
A = 0000		Q = 1010
	(Load Q with 0101)	
A = 0000		Q = 0101
	(Load Q with 1010)	
A = 0000	• .	Q = 1010
A = 1010		B = 0000
A = 0101		B = 0000
A = 1010		B = 0000
A = 0000		B = 1010
A = 0000		B = 0101
A = 0000		B = 1010
	(Load Q with 1111)	
Ø		Q = 1111
Ø		B = 0000
ø	· .	B = 1111
Ø		A = 0000
Ø		A = 1111
D = 1010		A = 0000
D = 0101		A = 0000
D = 0101		A = 0000
D = 0000		A = 1010
D = 0000		A = 0101
D = 0000		A = 1010
	(Load Q with 0000)	
D = 1111		Q = 0000
D = 0000		Q = 0000
	(Load Q with 1111)	
D = 0000		Q = 1111

TABLE 8: <u>ALU Source Operands</u>

CN	R = A	S = D
0	0000	0000
1	0000	0000
0	1111	0000
1	1111	0000
0	0101	0000
	0101	0000
0	1010	0000
	1010	0000
0	0000	1111
1	0000	1111
0	1111	. 1111
	1111	1111
0	0101	1111
	0101	1111
0	1010	1111
	1010	1111
U	0000	0101
1	0000	1010
· U		0101
1		. 0101
U	0101	0101
	0101	0101
U	1010	0101
	1010	1010
U	0000	1010
	0000	1010
U I	1111	1010
	0101	1010
0	0101	1010
0		1010
1	1010	1010
1	1010	1010

TABLE 9: ALU Function Sequence

Function	Octal Code
R AND S	_4
R AND S	5
R XOR S	6
R SNOR S	7

The last test on the device is to check to see if the output enable/ disable will cause the output to go to tristate. This is accomplished by inputting a 0, 5, 10, and 15 into the Data bus and outputting it through the ALU (R OR S function) to the Y output. After each data pattern is on the Data bus the "Y" output is checked with the output enable. Then the outputs are disabled and the outputs checked for tristate. D. 6800

The 6800 microprocessor unit is divided into the basic modules as listed below:

1. Program Counter

2. Stack Pointer

3. Index Registers

4. Accumulators A and B

5. Arithmetic Logic Unit

6. Timing and Control Logic

7. Interrupt Capability

For thorough testing of the 6800, the functional test sequence should thoroughly exercise each module independent of all other modules with the specific instructions applicable to that module. In addition, sufficient data patterns are used to verify proper operation of each module. An interactive type test is also performed to ensure that execution of an instruction on one module will not cause destruction of data in a different module or an otherwise malfunction of the device.

In determination of the instruction sequence, the possible discovery of instruction and/or data pattern sensitivities was not considered.

Program Counter

The Program Counter (PC) test consists of resetting the PC to O

and then incrementing the PC through its entire range. Results of this test may be verified after each increment or after the PC has reached full value. Benefits of this test are proof that the device is basically operational, there are no stuck-at-one stuck-at-zero defects in the PC and the address bus drivers are capable of driving a logic 0 or logic 1 in any combination of bits present on the address bus.

Operation of the device during this test is as follows:

- 1. Reset the device.
- 2. Verify the reset address vectors of FFFE₁₆ and FFFF₁₆.
- 3. Input an instruction that will cause the PC to increment by 1.
- 4. Continue operation of this instruction until the PC equals FFFF₁₆.
- 5. Execute the instruction one more time to verify the overflow characteristic of the program counter.

Stack Pointer

Operational Modes:

- 1. Load
- 2. Store
- 3. Increment

4. Decrement

5. Transfer +1 to Index Register

- 6. Receiver -1 from Index Register
- 7. Output Data on Address Bus for:
 - a. Push, Pull Data
 - b. Store Device Status in Stack
 - c. Pull Device Status from Stack

Stack pointer contents are available on the data bus and also the address bus during instruction execution. Accordingly the test approach is defined to verify both conditions of output. The method of defining the test approach follows that of all modules, i.e., start with instruction sequences designed to verify basic module operation, increasing the complexity of instructions for total testing of the particular module. The transfer of SP contents to the index register and transfer of index register contents to the stack pointer require verification of the index register's functionality, and will therefore be defined in the index register section of this description.

Load/Store, Data Bus

To initiate testing of the stack pointer, a load instruction is executed followed by a store instruction to output the SP contents on the data bus.

Stack Pointer Instructions

LDS Immediate, Direct, Index, Extended
STS	Direct, Index, Extended	
INS		Implied
DES		Implied
TXS		Implied
TSX		Implied
	•	

Several data patterns should be chosen such that all bits of the stack pointer have been loaded to both a logic 1 and 0. In addition, all different operational codes of the load stack pointer/store stack pointer instruction are executed at this time. This instruction sequence is defined as illustrated in Table 10.

Benefits of this test are that the stack pointer is identified as an addressable register, is capable of being loaded to several values, each bit of the stack pointer is capable of being a logic 1 or logic 0 and that each bit of the data bus is capable of driving a logic 1 or logic 0.

Increment/Decrement

Execution of this test requires initial loading of the SP to 0000_{16} , the incrementing the SP from 0000_{16} to FFFF₁₆ using the increment stack pointer instruction.

For detailed error analysis, the contents of the SP should be outputted to the data bus after each increment. This method may prove

INSTRUCTION	ADDRESS MODE	DATA PATTERN
Load Stack Pointer	Immediate	ØØØØ 16
Store Stack Pointer	Direct	-
Load Stack Pointer	Direct	FFFF 16
Store Stack Pointer	Index	-
Load Stack Pointer	Index	AAAA 16
Store Stack Pointer	Extended	-
Load Stack Pointer	Extended	⁵⁵⁵⁵ 16
Store Stack Pointer	Extended	-

TABLE 10: Stack Pointer Load Routine

not feasible due to test system capability and in that case the increment stack pointer instruction would be repeated 16,384 times, and the SP contents then read. The increment stack pointer instruction is then executed one more time and the SP contents outputted to verify the overflow characteristic.

The Decrement Test is similar to the previous test with the exception of initially loading the stack pointer to FFFF₁₆, using the decrement stack pointer instruction and executing the decrement instruction on additional time after the SP is equal to 0 to verify the underflow characteristic.

In either of the above tests, the choice of which stack pointer store instruction to use is arbitrary and left to the discretion of the test engineer.

Address Bus Output (Push/Pull)

The Push and Pull instructions of the 6800 will cause the contents of the stack pointer to appear on the address bus and also increment or decrement the contents of this register.

Verification of this mode is performed by resetting the 6800 (getting a starting address of 0000_{16} to the PC) and execution of repeated PUL instructions. During instruction execution, the address is read

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during all four to verify that the following information is present:

Cycle 1:	Program Counter
Cycle 2:	Program Counter +1
Cycle 3:	Stack Pointer
Cycle 4:	Stack Pointer +1

The PUL instruction is repeatedly executed until both PC and SP are equal to FFFF_{16} .

The PSH instruction is now executed in a similar manner, again verifying the address bus during all four clock cycles as follows:

Cycle 1:	Program Counter
Cycle 2:	Program Counter +1
Cycle 3:	Stack Pointer
Cycle 4:	Stack Pointer +1

This sequence is repeated until the SP is equal to O.

Index Register (X)

Operational modes:

1.	Local	Load Immediate,	Direct,	Index,	Extended
2.	Store	Store	Direct,	Index,	Extended
3.	Increment	Increment			
4.	Decrement	Decrement			

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INSTRUCTION	ADDRESS MODE	DATA PATTERN
Load Index Register	Immediate	ØØØØ ₁₆
Store Index Register	Direct	-
Load Index Register	Direct	FFFF ₁₆
Store Index Register	Index	-
Load Index Register	Index	AAAA
Store Index Register	Extended	-
Load Index Register	Extended	5555 ₁₆
Store Index Register	Extended	-
	· .	· .

TABLE 11: Index Register Load Routine

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5. Transfer to Stack Pointer TXS

6. Receive from Stack Pointer TSX

The Index Register is identical in size (16-bits X 1) and similar in operation to the Stack Pointer. Therefore, the test plan defined for this module closely parallels that of the Stack Pointer.

Load/Store

The Index Register is loaded with several data patterns, storing the register contents after each load to verify proper load operation. All different OP codes of the load and store instruction should be used to verify proper operation. The instruction sequence is defined as illustrated in Table 11.

Increment

Execution of this test requires initial loading of the Index Register to 0000_{16} , repeating execution of the increment Index Register (INX) instruction to increment the X register from 0000_{16} to FFFF₁₆.

As in the Stack Pointer test, the contents of the X register should be stored in the data bus after every increment. If not feasible, the increment instruction should be repeated continuously and the X register contents outputted when equal to $FFFF_{16}$. The increment instruction should then be executed one more time and the contents of the Index Register stored to verify the overflow characteristic.

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Decrement

The Decrement test is similar to the previous test with the exception of initially loading the Index Register to FFFF_{16} , using the decrement Index Register instruction. When the X register is equal to 0000_{16} , the decrement instruction should be executed one more time and the register contents stored to verify the underflow characteristic.

Stack Pointer and Index Register Transfers

Transfers of the Stack Pointer and Index Register are limited to transferring the Stack Pointer contents +1 to the Index Register or the Index Register contents -1 to the Stack Pointer. The two instructions which define those operations are TSX and TXS respectively.

The test sequence to verify this sequence takes advantage of the functionality of these registers proven by previous tests.

Both registers are initially loaded to O. An instruction sequence which increments the SP executes a TSX instruction and stores the Index Register contents is repeatedly executed until the Index Register is equal to FFFF₁₆.

This procedure is now repeated in a reverse fashion by executing a decrement Index Register, TXS, instruction followed by a read of the Stack Pointer. This instruction sequence is repeated until the Stack

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Pointer is equal to 0.

Accumulators A and B

Accumulators A and B are two general purpose 8-bit registers used to store operands and results for ALU operations. The instruction set for each accumulator is similar with one or two exceptions. At this point, the definition of the different modules of the 6800 are open to different philosophies as to where one module ends and another module begins. For example, controversy may arise as to whether a logical OR instruction is an accumulator instruction or an ALU instruction.

This situation illustrates the problem of two different modules being involved in the execution of an instruction. The operation of the logical OR instruction of the contents of the Accumulator A (ACCA) with a byte of memory involves the input of a byte of memory, input of ACCA and the byte of memory to the ALU, execution of the logical OR between the two and transferring this results back to ACCA. Here two different modules are involved in the instruction execution and the question is to which module group the instruction belongs. For the purposes of clarity, this type of instruction will be attributed to the ALU module. In a more general sense, where more than one module is involved in the execution of an instruction, the instruction will be classified as belonging to the module which performs the basic operation intended by the instruction. Accumulator A and B, Load/Store

As in the Stack Pointer and Index Register test, the initial phase of the accumulator test consists of executing a load and store accumulator routine, using all applicable operation codes in conjunction with numerous data patterns. The specific instruction sequence is defined as illustrated in Table 12. Note that the contents of the accumulator not involved in a series of instructions is stored on data bus to verify no interaction of the two accumulators.

Increment/Decrement

Accumulator A is loaded to all O's and the increment Accumulator A instruction is executed followed by a store Accumulator A instruction. This process is continued until ACCA is equal to FF_{16} . The decrement Accumulator A instruction is now executed followed by a store ACCA instruction. This instruction sequence is repeated until ACCA is equal to 0.

The above process is repeated on Accumulator B substituting the appropriate Accumulator B instructions.

Transfer ACCA to ACCB, ACCB to ACCA

This test is designed to verify the internal transfer of accumulator to accumulator by using previously verified instructions.

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INSTRUCTION	DATA PATTERN	INSTRUCTION	DATA PATTERN
Load A Store A Load B Store B Load A Store A Load B	$ \begin{array}{c} FF \\ FF \\$	Load A Store A Load B Store B Load A Store B Load A Store B Load A Store A Load B	4016 4016 8016 8016 FE16 FD16 FD16 FD16 FB16 FB16 F716 EF16 EF16 DF16 BF16 BF16 FF16 FF16
Store B	10	Store B	10

TABLE 12: Accumulator Load Routine

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Both accumulators are initially loaded to all O's. An increment ACCA is executed followed by a transfer ACCA to ACCB, clear ACCA and then store both accumulators. Now, an increment ACCB is executed, followed by a transfer ACCB to ACCA, clear ACCB and store both accumulators. This sequence is repeated until ACCA is equal to X'FF.

Shift/Rotate Capability

The Accumulator registers of the 6800 are equipped with five modes of shift and/or rotate instructions. To properly verify the operation of these instructions, each is executed with several data patterns designed to represent worst case. Also, included in the execution of the shift and rotate instructions is verification of the Condition Code register, in particular the Carry Bit (C).

The test routine for the shift and rotate instructions initializes the MPU to a O state and then executes all five instructions on each accumulator. The recommended data patterns for each instruction is:

> FF16 AA16 5516 Ø116 ØØ16

Each instruction is executed a total of eight times in order to

shift or rotate the data pattern through the entire accumulator. The contents of the accumulator being tested should be stored after each execution of the shift or rotate instruction. Also the contents of the Condition Code register should be stored after each eight executions of the instruction being used.

Arithmetic Logic Unit (ALU)

The function of the ALU is to perform addition, subtraction, and logical operations (OR, AND, Exclusive OR, 1's complement and 2's complement). Arithmetic comparisons can also be performed to set or reset bits of the Condition Codes register (CCR) which are testable for use in condition branch instructions.

Proper verification of the ALU includes execution and verification of all associated instructions in conjunction with worst case data patterns to verify that the ALU can add, subtract, recognize a carry, half carry, positive number, negative number and 2's complement overflow. As the CCR is an intergral portion of the ALU, its contents should be verified after execution of each instruction.

As in previous situations, the actual order of the instruction and data sequence should be structured such that, when possible, only instructions that have been previously verified are used for verification of unused instructions. The actual data patterns must be chosen such that the desired results will be generated.

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Timing and Control Logic

Timing and control logic verification includes testing proper generation of the Valid Memory Address (VMA), Bus A available (BA), and Read/Write control signals (R/W). The control signals BA, VMA, and R/W are generated according to the decode of each instruction with 30 different possible combinations. Therefore, each instruction must be verified as producing the proper response of these signals.

Interrupt Capability

The 6800 microprocessor unit has been designed to offer two priority levels of hardware interrupt capability, the $\overline{\text{IRQ}}$ (maskable) and $\overline{\text{NMI}}$ (non-maskable) interrupts, $\overline{\text{NMI}}$ having priority of $\overline{\text{IRQ}}$.

Upon detection of an interrupt, the 6800 will enter the interrupt state at the end of the instruction being executed or after the completion of next instruction, depending upon what clock cycle of the present instruction execution the interrupt has occurred.

The "I" bit of the Condition Codes register has been designated as the mask bit for the \overline{IRQ} interrupt. If an \overline{IRQ} occurs and the "I" bit is set, the interrupt is ignored. If not, the interrupt state is entered.

The objectives of this test can now be stated as verification of

the following conditions.

- Proper 6800 response to an IRQ interrupt by testing the data bus for storage of internal register contents, address bus for Stack Pointer address generation during the above storage and the address bus for generation of the IRQ address interrupt vector.
- 2. The "I" bit is set as a results of an IRQ interrupt.
- 3. That the 6800 will not respond to an \overline{IRQ} interrupt when the "I" bit of the CCR is set.
- 4. Proper response to an NMI interrupt when the "I" bit is set and reset.
- 5. Priority of the $\overline{\text{NMI}}$ interrupt over $\overline{\text{IRQ}}$ by causing both signals to indicate interrupts simultaneously.

A third mode of interrupt is under software control by means of the SWI (Software Interrupt Instruction). Execution of this instruction is not hardware related and will therefore be executed whenever it occurs in the user program. This instruction is verified by testing the data and address bus for proper storage of internal 6800 register contents and the generation of the SWI address interrupt vector.

Execution of the WAI (Wait for Interrupt Instruction) stores all internal register in the stack and then places the 6800 in an inactive wait state. The device will remain in this state until either an \overline{IRQ} or \overline{NMI} interrupt occurs. This instruction is verified by first observing the data and address bus during internal register content storage

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and second that an \overline{IRQ} and \overline{NMI} interrupt will be allowed to respond as previously described for these signals.

The IRQ and NMI signals are asynchronous and as such should be tested for interrupt generating capability by causing the interrupts to occur within several timeframes. First each interrupt should occur such that the recognition routine starts after completion of the present instruction being executed at the time of interrupt and second, after completion of the next instruction at the time of interrupt.

Instruction Decode Test

The Instruction Decode test verifies proper execution of all jump, branch, and subroutine instructions.

The major aspect of the jump instruction is to test for proper address generation in response to the two addressing modes of this instruction.

Testing of the branch instructions requires execution of each instruction and testing that (1) the branch address is generated, if the branch condition is true, and (2) that the branch does not occur, if the associated condition is false.

Subroutine instructions tests are required to verify that (1) the Stack Pointer address occurs on the address bus simultaneously with the

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return address on the data bus, (2) the correct subroutine address is generated, and (3) that the return from subroutine generates the Stack Pointer address on the address bus for the purpose of pulling the return address from stack.

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E. 1802

The 1802 microprocessor unit is a static 8-bit device employing CMOS technology. The device provides the following internal architecture (see Figure 11).

- 1. 16-bit by 16-bit Register Array
- 2. 8-bit Arithmetic Logic Unit (ALU)
- 3. 8-bit Accumulator (D)
- 4. Two 4-bit Instruction Registers (I and N)
- A 4-bit Register P used to specify which of the 16-bit Registers in (1) is the present program counter.
- 6. A 4-bit Auxiliary Register (X)
- 7. An 8-bit Temporary Register (T)
- 8. A 1-bit Register (Q)

Examination of the instruction set of the 1802 reveals that the major data path to and from the internal register array is through the D register. Therefore, this module of the 1802 is of extreme importance and the test program will exercise this module fully as an initial starting point. Next, the uniqueness and functionality of the 16-bit by 16-bit register array will be proven. Arithmetic and Logical instructions will be tested next followed by the Branch and Skip instructions.

A unique feature of the 1802 is a built-in DMA feature which uses an internal register as a counter for the number of bytes transferred to or from memory. This feature is evaluated for both the DMA in and

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DMA out modes of operation. The Interrupt feature is verified for proper operation and also tested for its masking capability.

D Register

The importance of the D register is its function of being the path by which to load or store contents of the scratch pad register array via the data bus and as a working register of the arithmetic logic unit. The initial phase of the test on this register is to ensure the ability to load worst case data patterns in the D register and also store the same.

Execution of this test consists of a series of load instructions to walk a 1 through a field of 0's and a 0 through a field of 1's, each load instruction being followed by a store to verify the load operation.

Register Array

The purpose of the register array is to provide a program counter, 16-bit vectored interrupt address storage, DMA address counter, and general purpose scratch pad registers. The initial test on this module consists of a series of instructions to verify that each register can be loaded to worst case data patterns and that each register can be accessed for the retrival of this information. All input and storage of data patterns to the register array will take place through the D

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register. An important point is that at all times one of the 16 registers is being utilized as a program counter, as determined by the value in the 4-bit P register. Upon initial start-up and reset of the 1802, the P register is reset to 0, making R(0) the current program counter. Therefore registers R(1) through R(15) are tested first and then the SET P instruction must be executed to change the register being used as the program counter. Register R(0) is then tested in the same manner as the others. Due to the use of R(0) as a program counter during this exercise, R(0) should be stored through the D register at the completion of this test to check that it has been incrementing during the execution of the test. Then a test sequence which loads and stores worst case data patterns can be executed. The actual test sequence of loading and storing data patterns in the register array should use different data such that the uniqueness of each register is proven.

The next portion of the Register Array test will verify operation of the increment and decrement instructions, INC and DEC.

The procedure is to verify that each of the 16 registers of the register array can increment and decrement throughout the entire range of 0 to 2^{15} -1. Also to be verified is the over and underflow characteristics of each register. Registers R(1) through R(15) are to be tested first with R(0) acting as the program counter. Then R(0) is tested with R(1) as the program counter. The test procedure is as

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follows:

- 1. Reset device.
- Load registers R(2) through R(15), each with a distinct data pattern.
- 3. Load register R(1) with O and using the increment N instruction, cause this register to increment from O to 2^{15} -1. Then execute the increment instruction an additional time to cause R(1) to overflow to O. Each increment instruction should be followed by PUT low register N and PUT high register N instructions to verify the increment.
- 4. At the completion of step 3, all other registers should be stored on the data bus to verify that no destructive interaction has occurred.
- 5. The decrement register N instruction is now executed to cause register R(1) to decrement from 0 to 2^{15} -1, and then to 0. Again, each decrement instruction is followed by a PUT low register N and PUT high register N instruction to verify each decrement.
- Registers R(2) through R(15) are now read onto the data bus to verify no destructive interaction.
- This process is repeated until registers R(1) through R(15) have been tested.
- 8. A SET P instruction is executed to change the current program counter from R(0) to R(1).
- Register R(0) is stored on the data bus and its present contents verified.

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10. R(0) is loaded to 0 and the same procedure is followed for verification as described above.

X Register

The purpose of the X register is to hold a four bit code used to designate one of the 16 registers of the register array for use in certain load and store instructions. Upon initial reset of the MPU, this register is reset to 0 and then may be loaded to another value by the SET X instruction. Proper verification of the operation of this register is to reset the MPU, and execute a load via X or store via X instruction. The value which will appear on the address bus will be the contents of register R(0) which is also the current contents of the program counter as a reset will clear the P register to 0.

At this point the SET X instruction is executed to designate R(1)and the load via X or store via X instruction executed. This process is repeated until all registers have been designated by the X register. It is important to note that all registers should be loaded to different values in order to prove that the R(X) register is actually present on the address bus.

P Register

The P register is used to hold a four bit code used to designate

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which of the 16 registers of the register array is the current program counter. The verification of the register operation is performed in a similar manner to that of the X register.

The device is reset, which should clear the P register and register R(0) to 0.

The initial portion of this program after reset should load the register array such that each register contains a different value. By doing this, each register can be uniquely identified as it is gated to the address bus. After verification of R(0) as the program counter the SET P instruction should be executed to change the current program counter from R(0) to R(1) and the address bus monitored. All remaining values of the P register are verified in the same manner.

Q Register

The Q register is a 1-bit register which can be set or reset under program control. The Q register bit is also cleared after an initial clear is performed. Also, the status of this bit can be tested by several of the branch instructions. However, this portion of the Q register test will not utilize the branch instruction as a part of the test.

The 1802 is initially cleared and the Q bit tested for the logic O state. The SET Q instruction is executed and then reset, the state of

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the Q bit being tested after each operation. This procedure can be repeated several times to ensure proper operation.

Arithmetic Logic Unit

The test of the arithmetic logic unit is divided into two sections, the logical operations and the arithmetic operations. Also all addressing modes included in this portion of the instruction test are verified together with the operation of the DF flag.

Logical Instruction Test

The purpose of this test is to verify that all logical instructions are operational and that worst case data patterns have no effect on functionality of the device.

For the instructions of OR, Exclusive OR, and AND, worst case data patterns are defined as those patterns that cause each bit in the result to be either set or reset according to the instruction being tested. Examples are illustrated in Figures 18, 19, and 20.

Initially the OR instruction is executed with the data patterns specified. The D register is loaded, the OR instruction executed and the D register stored on the data bus to verify the results. This test is executed twice. The first time the OR instruction is used and the second time the OR IMMEDIATE instruction is used.

Pattern	1	Byte 1	ו	0	1	0	1	0	1	0
		Byte 2	0	1	0	1	0	1	0	1
	· · · ·	Result	1	1	1	1	1	1	1	1
Pattern	2	Byte l	0	1	0	1	0	1	0	1
		Byte 2	1	0	1	0	1	0	٦	0
	· .	Result	1	1	1	1	1	1	1	1
Dattom	2	Ruto 1	1	r	٦	٦	1	1	1	1
rattern	5	Byte 2	0	0	0	0	0	0	0	0
		Result	1	1	1	1	1	1	1	1
	A	Dute 1	0	0	^	^	0	^	0	0
Pattern	4 .	Byte 1	יט	U 1	U 1	U 1	U 1	U 1	U I	U 1
		Byte 2	<u> </u>	<u>ו</u> ז	<u> </u> 	. <u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>
		Result	I	I	i	ļ	I	1	I	Ι.
Pattern	5	Byte 1	0	0	0	0	0	0	0	0.
		Byte 2	0	0	0	0	0	0	0	0
		Result	0	0	0	0	0	0	0	0

FIGURE 18: 1802--OR Data Pattern

Pattern 1	Byte 1 Byte 2 Result	10101010 01010101 11111111
Pattern 2	Byte 1 Byte 2 Result	0 1 0 1 0 1 0 1 1 0 1 0 1 0 1 0 1 1 1 1 1
Pattern 3	Byte 1 Byte 2 Result	$\begin{array}{c}1&1&1&1&1&1&1&1\\1&1&1&1&1&1&1&1\\0&0&0&0&$
Pattern 4	Byte 1 Byte 2 Result	1 1 1 1 1 1 1 1 0 0 0 0 0 0 0 0 1 1 1 1
Pattern 5	Byte 1 Byte 2 Result	0 0 0 0 0 0 0 0 0 1 1 1 1 1 1 1 1 1 1 1 1
Pattern 6	Byte 1 Byte 2 Result	0 0
Pattern 7	Byte 1 Byte 2 Result	1 0 1 0 1 0 1 0 0 0 0 0 0 0 0 0 1 0 1 0
Pattern 8	Byte 1 Byte 2 Result	0 1 0 1 0 1 0 1 0 1 0 0 0 0 0 0 0 0 0 0 1 0 1
Pattern 9	Byte 1 Byte 2 Result	0 0 0 0 0 0 0 0 0 <u>1 0 1 0 1 0 1 0</u> 1 0 1 0 1 0 1 0
Pattern 10	Byte 1 Byte 2 Result	00000000 01010101 01010101

FIGURE 19: 1802--Exclusive OR Data Pattern

Pattern 1	Byte l	1111111
	Byte 2	. <u>11111111</u>
	Result	1111111
Pattern 2	Byte l	
	Byte 2	00000000
	Result	1111111
	· :	
Pattern 3	Byte 1	10101010
:	Byte 2	<u>01010101</u>
	Result	11111111
· · ·		· · · ·
Pattern 4	Byte 1	01010101
	Byte 2	<u>10101010</u>
	Result	1111111
		· .
Pattern 5	Byte 1	00000000
	Byte 2	<u>11111111</u>
	Result	
		· · ·
Pattern 6	Byte 1	00000000
	Byte 2	00000000
	Result	00000000

FIGURE: 20:

1802--AND Data Pattern

The Exclusive OR, EXCLUSIVE or IMMEDIATE, AND and AND IMMEDIATE instructions are executed in the same manner.

The four shift instructions are verified using the same philosophy for worst case data patterns as for the OR and AND instructions. One of the functions of the DF bit will be used and therefore requires verification.

The procedure for verification consists of loading the D register with a test pattern, executing the particular shift instruction eight times, storing the contents of the D register after each instruction execution.

Verification of the proper operation of the DF bit can only be made by designing a test program such that the DF bit is left to an expected known state. This state is then used as a starting point for the next data pattern. For example, if the completion of a shift instruction has put the DF bit to a logic 1, the next shift instruction to be executed would be one that shifted the DF bit to either the least or most significant bit of the D register.

For the shift instructions, the following data patterns can be used as initial values:

Shift Right:	⁵⁵ 16, ^{AA} 16,	FF ₁₆ ,	⁸⁰ 16'	^{ØØ} 16	
Shift Right with Carry:	⁵⁵ 16, ^{AA} 16,	FF ₁₆ ,	^{8ø} 16,	Ø1 ₁₆ ,	ØØ ₁₆

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Shift Left:

Shift Left with Carry:

⁵⁵16, ^{AA}16, ^{FF}16, ⁸⁰16, ⁰¹16 ⁵⁵16, ^{AA}16, ^{FF}16, ⁸⁰16, ⁰¹16, ⁰⁰16

Arithmetic Operations

The object of this portion of the test program on the ALU is to verify that the ALU can add, subtract, with and without a carry or borrow, respectively, detect an overflow or underflow condition via the DF bit, and that the register and immediate addressing modes are functional.

Suggested data patterns for the arithmetic instructions are as follows:

Add, Add Immediate:

FF₁₆ to FF₁₆, 55_{16} to 55_{16} , AA₁₆ to AA₁₆, 00_{16} to 00_{16} , F0 to $0F_{16}$

Add with Carry, Add with Carry Immediate OD_{16} to CC_{16} , FF_{16} to FF_{16} , $FØ_{16}$ to $8Ø_{16}$

Subtract, FF₁₆ from FF₁₆, ⁵⁵₁₆ from AA₁₆, ^{AA}₁₆ Subtract Immediate from ⁵⁵₁₆

Subtract with Borrow, Subtract with Borrow Immediate FF_{16} from $\emptyset P_{16}$, $\emptyset F_{16}$ from $\emptyset F_{16}$, $8\emptyset_{16}$ from 99_{16} , $6\emptyset_{16}$ from $7\emptyset_{16}$ Subtract Memory, FF₁₆ from FF₁₆, ⁵⁵₁₆ from AA₁₆, AA₁₆ from Subtract Memory Immediate ⁵⁵₁₆

Subtract Memory with Borrow, Subtract Memory with Borrow Immediate FF_{16} from $\emptyset I_{16}$, $\emptyset F_{16}$ from $\emptyset F_{16}$, $8\emptyset_{16}$ from 99_{16} , $6\emptyset_{16}$ from $7\emptyset_{16}$

Two methods exist for verifying proper operation of the DF bit during execution of these instructions. The first is to follow each add or subtract instruction by an add with carry or subtract with borrow. This second add or subtract instruction will verify the proper DF bit operation if the results are what is expected as a result of the instruction execution.

The second is to execute a shift right with carry or shift left with carry to put the value of DF into the MSB or LSB of the D register respectively. The contents of the D register are now read and the MSB or LSB verified to reflect the expected state of the DF bit. This is the preferred method for several reasons. First, if a failure occurs using the first method, the cause of the failure could be that the ALU did not detect the original overflow or could not execute the add or subtract with carry. As the shift instructions have previously been verified, this mode of verification pinpoints the cause of failure.

Branch and Skip Instructions (Long & Short)

The branch and skip instructions are verified by causing the condition tested by the particular instruction to occur and then executing

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the associated branch or skip instruction. The address bus is tested for generation of the expected branch address. Alternately, the opposite condition is verified by executing the necessary branch or skip instruction when the branch condition does not exist and verifying that the branch or skip does not execute. The conditions tested for in the branch and skip are the following:

Short Branch if:

 $D = \emptyset$ $D \neq \emptyset$ DF = 1 $DF = \emptyset$ Q = 1 $Q = \emptyset$ EF1 = 1 EF2 = 1 EF2 = 1 EF2 = 0 EF3 = 1 $EF3 = \emptyset$ EF3 = 0 EF4 = 1 $EF4 = \emptyset$

Always, Never

The short branch and long branch are similar with the exception that the long branch provides an absolute branch address, while the short branch provides an address which is 0 to +255 locations from the address containing the short branch instruction. The conditions tested for the long branch instruction is limited to the states of the D register, DF bit, and Q bit. Specifically these are:

Long Branch if: $D = \emptyset$ D≠.Ø DF = 1DF ≠ 1 Q = 1 . Q ≠ 1

Always, Never

The skip instructions are similar to the branch instructions except no branch address is required. The conditions tested are as follows:

Short Skip:	Never .	
Long Skip:	Always	
Long Skip if:	D = Ø	
	D≠Ø	
	DF = 1	
	DF = Ø	
	Q = 1	
	Q = Ø	
	IE = 1	

Interrupt

The response of the 1802 to an asychronous Interrupt is tested by causing the Interrupt input to become active and verifying that the following states occur:

- 1. The instruction in process at the time of interrupt is completed.
- The next machine cycle is a normal fetch except the address gated to the address bus is from register R(1).
- 3. The X register has been set to 2_{10} .
- 4. The state codes indicate Interrupt recognition.
- 5. The IE enable bit has been reset by causing the Interrupt input to indicate additional Interrupts and verifying that they are ignored.
- The values of registers X and P have been saved in the T register.
 (This can be accomplished by execution of a MARK isntruction).
- The Interrupt mode of operation is asynchronous by repeating the test in every clock cycle of instruction execution.

DMA-In-Out

The DMA-In-Out features are tested in a manner similar to that of the Interrupt with all expected activities verified.

DMA In

1. DMA-IN is caused to become active.

- 2. At the completion of the present instruction, verify the state codes indicate $\overline{DMA-In}$, register R(0) is gated to the address bus and \overline{MWR} is active.
- 3. Item 2 is repeated for as long as $\overline{\text{DMA-In}}$ remains active, with register R(0) being incremented after each transfer.
- 4. Normal program execution is resumed when DMA-In becomes in-active.

DMA-Out

- 1. DMA-Out is caused to become active.
- At the completion of the present instruction execution, the state codes indicate DMA-Out, MRD is active, and register R(0) is gated to the address bus.
- 3. Item 2 is repeated for as long as DMA-Out is active.
- 4. Normal program execution is resumed when DMA-Out becomes in-active.

At this point, the priority of the previous tests should be verified such that a DMA and Interrupt request occur simultaneously. The order of priority is DMA-In first, DMA-Out second, and Interrupt last.

Input/Output Transfers

The test to verify the input and output instruction capability of the 1802 is performed separately for proper operation. Each instruction should be executed with all possible combinations of I/O device selections, testing for proper access of the least three significant bits on output pins NO, N1, and N2, and the contents of register R(X) being

VI. DC TEST REQUIREMENTS

Although the major portion of this report has been devoted to testing of the functional characteristics of microprocessor units, the importance of DC testing should not be de-emphasized. As with other semiconductor devices, microprocessor units malfunction as a results of DC characteristics being out of specification. Therefore, it is recommended that any complete test on a microprocessor unit include verification of the manufacturers specified DC characteristics.

The commonly specified DC parameters are input and output voltage levels, input and output currents and leakages, tristate leakage currents, power supply voltages and power supply currents. Proper verification and/or measurement of each parameter should be performed, simulating the necessary condition for accurate test execution. Refer to Attachment I for DC specifications of each device.

VII. SURVEY SUMMARY

A. List of Companies Interviewed

Advanced Micro Devices, Sunnyvale, California American Micro Systems, Incorporated, Cupertino, California Boeing Aerospace, Seattle, Washington Burroughs Corporation, Pasadena, California Chrysler Corporation, Hunstville, Alabama Fairchild Systems & Technology, San Jose, California General Electric Company, Pittsfield, Massachusetts Hewlett Packard, Palo Alto, California Hughes Aircraft Corporation, Culver City, California Intel Corporation, Santa Clara, California Motorola, Austin, Texas Motorola, Phoenix, Arizona National Semiconductor, Santa Clara, California RCA, Sommerville, New Jersey Rockwell International, Anaheim, California Tektronics, Beaverton, Oregon Texas Instruments, Houston, Texas

B. REVIEW OF PRESENT MICROPROCESSOR TEST TECHNIQUES QUESTIONNAIRE

I. TEST EQUIPMENT

A. Tester (Which Device on Which Tester)

B. Clock Speed of Tester

C. Burn-in Equipment

1. Type Used

2. Static

3. Dynamic

4. What Type

II. DC TEST (PRODUCTION)

A. Parameters Tested

1. What DC Parameters Are Tested

2. Are Voltage Measurements Done DC Static or Functional

3. IF DC, How Long Is Sample

4. IF AC, Is VOH and VOL Measured One Pass or Two Pass

B. Execution Time (Delete Overhead)

C. Overhead Time

D. Percentage of Total Test Program

E. Differences Between Wafer and Final Package DC Tests

F. Type of Failures Observed

III. FUNCTIONAL TESTS (PRODUCTION)

A. Test Pattern

1. Method of Generation
2. Instruction Sequence (What Do They Test For)

a. Modular

b. Other

3. Gold Device

a. As A Comparison Test

b. As A Learn Method

c. Self Diagnostic (Board Test)

4. Pattern Length

5. Pattern Sensitivity

6. Frequency of Testing Device Output(s)

a. Each Cycle

b. End of Operation

c. Other

B. Functional Test Conditions

1. Device Timing

2. AC Parameters

a. Rise/Fall Times

b. Minimum Pulses

c. Access Times

3. Execution Time (Delete Overhead)

4. Overhead Time

5. Error Analysis

a. Why Device Failed

b. What Instruction

c. What Data Pattern

d. What Pin(s)

- C. Percentage of Total Test Program
- D. Types of Failures Discovered
- E. Differences Between Wafer and Final Package Functional Test Programs
- IV. CHARACTERIZATION EFFORTS
 - A. Parameters Characterized
 - 1. Functional and AC
 - 2. DC
 - B. Temperature Conditions
 - C. Burn-in Conditions
 - D. Form of Characterization Data Log
 - 1. Histogram
 - 2. Shmoo Plot
 - 3. Other
 - E. Number of Devices Characterized
 - F. Department Responsible for Characterization
 - V. PRODUCTION TESTING
 - A. Temperature Conditions
 - 1. Hold, Cold, Ambient
 - 2. If Not Done, Why
 - B. Burn-in Conditions
 - 1. What Temperature
 - 2. AC or Static
 - 3. What Loads
 - 4. If Not Done, Why

C. Data Logging

1. Bin Classification

2. Hardcopy

a. What Is Obtained

D. Location Performed

E. Percentage of Devices Screened

F. Department Responsible for Production Testing

G. 38510 Specification--Yes/No (If Yes, Who Wrote It)

H. Types of Failures

VI. WHAT TYPE OF PROBLEMS ARE YOU FINDING

VII. RECOMMENDATIONS FOR USER TESTING OF MICROPROCESSORS

C. QUESTIONNAIRE RESPONSES

I. TEST EQUIPMENT

A. Tester

		DEVICE						
RES	PONSE	8080	6800	8008	2901	1802		
1.	Fairchild Sentry II	2	1		1			
2.	Fairchild Sentry 600	2	2					
3.	Macrodata MD-154					1		
4.	Tektronics S-3260	3	1		1			
5.	Teradyne J277	1						
6.	Teradyne J283			· .	1	1		
7.	Teradyne J293				1			
8.	In-House System			1.		1		

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B. Burn-In Equipment

	DEVICE					
RESPONSE	8080	6800	8008	2901	1802	
l. Blue M	1		ï	1		
2. In-house Design	5	1		3		
3. Commercially Available	ר	٦				
4. Not Being Performed					1	

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II. DC TESTS (PRODUCTION)

A. Parameters Tested

			DEVICE		
RESPONSE	8080	6800	8008	2901	1802
1. All Data Sheet Parameters	5	2	1	3	1
2. All Data Sheet Parameters Plus Several Unspecified Parameters		1			

B. Voltage Measurements, Static or Dynamic

		DEVICE				
RESPONSE		8080	6800	8008	2901	1802
1.	Dynami c	4	2			
2.	Static				4	1
3.	Clocked Very Slow (Considered Static)	١		٦		
4.	Static Where Possible Dynamic Otherwise	1	١		-	

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C. Length of Sample Time, If Voltage Measurements are Static

		DEVICE					
RES	PONSE	8080	6800	8008	2901	1802	
1.	5 ms]					
2.	10 ms	1	1	ו	3	ì	
3.	Dependent On Parameter				1		
4.	Don't Know	2					

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D. VOL and VOH Measurements

		DEVICE				
RES	PONSE	8080	6800	8008	2901	1802
1.	AC MeasurementMade In One Pass Using Differential Voltage Comparators.	4	2	2		1
2.	AC MeasurementMade In Two Passes.		1		4	
3.	AC MeasurementMade In Separate Passes.	2				
4.	DC MeasurementMade In Static Mode.				l	

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E. DC Test Execution Time

	· · · · · · · · · · · · · · · · · · ·	DEVICE					
RES	PONSE	8080	6800	8008	2901	1802	
1.	1/4 Seconds Total Test Time, Breakdown Not Available	1					
2.	2 Seconds Total Test Time, Breakdown Not Available	1		ר			
3.	3 Seconds Total Test Time, Breakdown Not Available		1				
4.	3.5 Seconds Total Test Time, Breakdown Not Available				1		
5.	5 Seconds Total Test Time, Breakdown Not Available		1		1		
6.	Up to 9 Seconds Total Test Time, Breakdown Not Available					1	
7.	10 Seconds Total Test Time, Breakdown Not Available		1				
8.	20 Seconds Total Test Time, Breakdown Not Available	1		· .	1		
9.	60 Seconds Total Test Time, Breakdown Not Available	2					
10.	All tests performed are engineering type tests, not production or incoming inspection oriented.	٦		•	1		
h 1.	Full test program not written to date, time undeterminable.	1					

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F. Overhead Time, DC Test Program

		DEVICE				
RESPONSE		8080	6800	8008	2901	1802
1.	10 Seconds For Hardcopy Printout.				1	
2.	1%		1			
3.	Undeterminable	6	2	2	3	1

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G. Percentage of Total Test Program

			DEVICE					
RES	PONSE	8080	6800	8008	2901	1802		
1.	0%			1				
2.	4%				·]			
3.	10%	1						
4.	20%	2	:	1				
5.	20 - 30%		1		· .			
6.	70 - 80%	1			1			
7.	Undeterminable	2	2	· .	2	1		

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H. Differences Between Wafer and Final Package DC Tests

	DE VI CE				
RESPONSE	8080	6800	8008	.2901	1802
 Wafer level tests include a 25 V Stress Test which is not done at final package. 	1				
2. Wafer level DC tests are closely monitored for indications of yield relating to process parameters. Final Package is strictly Go/NoGo.		1			
 Wafer level tests are performed with wider guardbands. 			1	1	
4. None.	1			1	1
5. Undeterminable.	1	2			
6. Not Applicable.	3			2	

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I. Types of Failures

		DEVICE				
RESPONSE		8080	6800	8008	2901	1802
1.	Normal Process Related Failures.	2	2	_	3	
2.	Leakage Current, Temperature Failures.	2	1			1
3.	Undeterminable	1			1	
4.	No Comment	1	1	1		

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III. FUNCTIONAL TEST PROGRAM, PRODUCTION

A. Test Pattern

1. Method of Generation

;			·		·	
				DE VI CE		
RES	PONSE	8080	6800	8008	2901	1802
1.	Functional Computer Simulation.	4	2		۱	1
2.	Manual, Line by Line.	1				
3.	Manual, Line by Line, Generation in Tester Assembly Language.				2	
4.	Half Simulation (Learn Mode).]	1		1	
5.	Gold Device (DUT operates in parallel to known good device.).			1		

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2. Basis For the Order of uP Instruction Test Sequence

	· · · ·			DEVICE		
RES	PONSE	8080	6800	8008	2901	1802
1.	Exercise every node. Verify operation of every instruc- tion within specified timing requirement. Exercise adja- cent nodes in Modular Approach Satisfy large user require- ments.	1]		
2.	Use a Modular Approach to verify device operation. Also utilizes test engi- neer's experience to generate an interactive type test.]				
3.	Modular Approach using worst case instruction and data pattern sequence.	3				
4.	Modular Approach designed to represent worst case operation.		. 2		3	
5.	Test pattern developed by device designer to represent worst case operation.	1	1		1	
6.	Identify all data paths, all instruction operations.					1

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3. Pattern Length

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÷.

			DEVICE				
RES	PONSE	8080	6 <u>.</u> 800	8008	2901	1802	
1.	1К		· ·		.]		
2.	2К	ן	3				
3.	2K Clock Cycles	1.					
4.	5К				1		
5.	8К				1		
6.	12К	1					
7.	16K	1					
8.	7500					1	
9.	Program Incomplete To Date	1			1		
10.	No Comment	1			1		

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4. Pattern Sensitivity

		DEVICE				
RESPONSE		8080	6800	8008	2901	1802
1.	RAM section sensitive to a CHECKERBOARD Pattern. Results are based upon a sample space of five devices.				1	
2.	ALU				1	
3.	None	6	3	Ì	2	1

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5. Frequency of Testing Device Outputs

	. <u> </u>	DEVICE				
RES	SPONSE	8080 _.	6800	8008	2901	1802
1.	Each Cycle, Each Pin	5	3		. 2	1
2.	When Determinable Data Is Expected to Be Present.	1				
3.	Not Every Pin, Every Clock Cycle. The Status of a Pin is Tested Based Upon the Test Engineers Judgement.	1		1		
4.	Several Instructions are Executed, Pins of Interest Are Tested.				1	

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B. FUNCTIONAL TEST CONDITIONS

1. Device Timing, Frequency

				DEVICE		
RE	SPONSE	8080	6800	8008	2901	1802
1.	1 MHz	ŕ	1			
2.	2 MHz	1				
3.	3 MHz				1	
4.	4 MHz	1			1	
5.	100 MHz				1	
6.	500 MHz				1 -	
7.	Minimum and Maxiumum Cycle Time.	1				
8.	Maximum Cycle Time, Minimum Cycle Time, Each Extreme Tested With Guardband.	1	2	2		
9.	Maximum	2				

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2. AC Test Parameters

DEVICE						
RESPONSE		8080	6800	8008	2901	1802
1.	Rise and Fall Times, Minimum Pulse Width, Access Times.	2	1		1	
2.	Minimum Pulse Width's, Access Times.	4	2	1	3	1

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3. Functional Test Execution Times and Overhead

				DEVICE		
RES	PONSE	8080	6800	8008	2901	1802
1.	2 Seconds Total Test Time 1/2 Second Overhead.		٦			
2.	3 Seconds Total Test Time Overhead Undeterminable.		Ĩ			
3.	3 Seconds Total Test Time 1 Second Overhead.			•	١	
4.	3.5 Seconds Total Test Time Overhead Undeterminable.				1	
5.	4 Seconds Total Test Time 1 Second Overhead.	1			-	
6.	5 Seconds Total Test Time Overhead Undeterminable.	1		-	1.	
7.	10 Seconds Total Test Time Overhead Undeterminable.					1
8.	60 Seconds Total Test Time Overhead Undeterminable.	l 1				
9.	63 Seconds Total Test Time 60 Seconds Overhead.	1				
10.	Program Not Completed to Date.	1	1			
lıı.	No Comment.	-1		1	-	

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4. Error Analysis Information Available

		DEVICE				
RES	PONSE	8080	6800	8008	2901	1802
1.	Results indicate what test, what uP instruction, what data pattern, what pin(s), although this information is not used in Go/NoGo testing.	5				
2.	Only Pass/Fail status.	1				
3.	Results indicate what test failed, what uP instruction, what data pattern, and the pin(s) involved.		• 2		1	
4.	Results indicate the uP instruction involved in the failure but not expected data output or what pin(s) involved. The failing test is indicated.		1			
5.	Results indicate what test failed and the data pattern involved. The instructions involved can be determined with a manual.			•••	1	
6.	Off-line analysis, the fail- ing pin is not displayed.				1	
7.	Only RAM section test results indicate what data pattern, input code and failing pin(s) status.				1	
8.	The capability for indicating failing test, uP instruction, data pattern, and pin(s) in- volved exists although it is not used in the Go/NoGo situation.			1		
9.	Parametric test portion indi- cates the test failed, func- tional portion indicates uP instruction which failed.					1

5. Types of Failures Discovered

[· · ·		<u> </u>	DEVICE		<u></u>
RES	PONSE	8080	6800	8008	2901	1802
۱.	Normal, no pattern sensiti- vity found.	٦				
2.	Timing, logic error, temper- ature related failures.	1				
3.	Parts are slow, do not meet timing specifications.	1	÷			
4.	Majority of failures are totally inoperative.	1				
5.	Package devices are mainly functional failures.	1				
6.	Normal type failures of DC and functional.		1			
7.	Normal process related fail- ures.				1	
8.	Mostly functional failures.		1	- ,		
9.	In DC mode, leakage current is the predominant failure mode. Most failures are parts that fail within first 15 instructions.					' 1
10.	Have only tested small amount information inaccurate.				1	
11.	Have not completed in-coming inspection program to date.	1				
12.	Information not available.		1	1	1	

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6. Differences Between Wafer and Final Package Functional Tests

	• .	DEVICE				
RES	PONSE	8080	6800	8008	2901	1802
1.	No Multiple Probes on Wafer.	ר				
2.	Less Functional Tests at Wafer, to Identify Work- ing Parts, do Speed Classification at Final Package.	2				
3.	Final Package Tests Include More Extensive Timing and Voltage Corners To Classify Parts.		2			
4.	Test Pattern Is the Same. Timing and Voltage Corners Are More Extensive to Classify Parts.				1	
5.	Do No Perform Wafer Probe Except Under Special Cir- cumstances. Test Would Be Different But Details Not Available,				1	
6.	None.	ר		ו		1
7.	Not Applicable.	2	1		1	

IV. Characterization Efforts

A. Parameters Characterized

		DEVICE						
RES	RESPONSE		6800	8008	2901	1802		
1.	All AC & DC Parameters.	1		1	3	1		
2.	All AC & DC Parameters Except Rise & Fall Times.	4	2		1			
3.	All AC & DC Parameters Plus Additional Parameters Related to Process Control							
4.	All AC & DC Parameters, Except Rise & Fall Times, Data Patterns and Instruc- tion Sequences.		-			· · · · · · · · · · · · · · · · · · ·		

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B. Temperature & Burn-in Conditions

\int			DEVICE					
RES	PONSE	8080	6800	8008	2901	1802		
1.	-55°C to 125°C temperature, 6-7°C increments, life test evaluation performed in lieu of burn-in.	1		1	1			
2.	At present ambient, expect to go to 80°C case temper- ature, life testing.]						
3.	Military: -55°C, -40°C, 0°C, 25°C, 100°C, 125°C. Commer- cial 0-70°C. Burn-in at 150°C 40 hours minimum, Øl, Ø2 clocked, loaded outputs.	1						
4.	-55°C, -30°C, Ambient, 85°C, 125°C, life testing at 125°C, 1000-2000 hours.	1			· · · ·			
5.	O°C & 7O°C, will go to 85°C, possibly higher, no burn-in.	1						
6.	70°C, no burn-in.	1				ר		
7.	Ambient, no burn-in.		1					
8.	0°C to 70°C, guard banded life test.		. 1					
9.	-55°C to +125°C, burn in at 125°C, 48 hours, outputs loaded, Ø1,Ø2, clocked.		1					
10.	-55, 30°C, Ambient, 85°C, +125°C, life test at 125°C, dynamic, 1000-2000 hours.				1.			
h 1.	-55, 0°C, 25°C, 70°C, +125°C life test at 125°C, dynamic, 5000 hours.				ו			
12.	O°C, 70°C, 125°C, burn-in is static, power supplied, no pattern applied, outputs loaded	1.			1			
13.	Temperature is -65°C to +200°C. Perform burn-in only if contrac specifies. Have capability to perform all burn-in and environ mental tests.	:t -			1			

C. Form of Characterization Data Log

				DEVICE		
RES	PONSE	8080	6800	8008	2901	1802
1.	Statistical analysis, curves, extensive use of shmoo plots, occasionally log to disc or mag tape for off-line evalu- ation.	7				
2.	Shmoo plots, cumulative and individual.	2		-		
3.	Histograms, shmoo plots and statistical analysis.	2	3			
4.	Number charts, might go to histograms in future. Are not performing extensive characterization to date.	1		-		
5.	Tabular output and statis∹ tical analysis.	•			1	
6.	Statistical analysis, curves, and extensive use of shmoo plots.			· .	1	
7.	Graphical pictures, histo- grams, statistical analysis, and some shmoo plots.				1	
8.	Statistical analysis, histo- grams, and shmoo plots.			1 [°]		
9.	Summary.				1	
10.	Shmoo Plots.					1

D. Number of Devices Characterized

		DEVICE				
RESPONSE		8080	6800	8008	2901	1802
1.	6				1	
2.	10	1	1			
3.	12 - 24	1				
4.	20				1	
5.	40				1	
6.	50	1		• •		
7.	100	1				
8.	500	1		1		
9.	1400		ו			
10.	Information Not Available	1	1]]	ו

E. Department Responsible for Characterization

		DEVICE				
RES	PONSE	8080	6800	8008	2901	1802
1.	Product Engineering	2	1	1		
2.	Design Engineering	1				
3.	Production & Design Engineering	1				
4.	Manufacturing Engineering			-	1	
5.	Electronic Design	ŗ				
6.	Components & Evaluation Department	1	1		J .	
7.	Operations Department				1	
8.	Advanced Device Technology Department	· ·			١	-
9.	Production Test Group					1

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F. Method of Processing Characterization Data

	DEVICE				
RESPONSE	8080	6800	8008	2901	1802
1. Automatically	5	3	1	4	1
2. Manually	1		- -		

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V. PRODUCTION TESTING

A. Temperature Conditions

		DEVICE				
RES	PONSE	8080	6800	8008	2901	1802
1.	Ambient	1	2		2 ·	1
2.	-55°C, +125°C Ambient	1	-		1	
3.	0-70°C, 125°C, Ambient	1				
4.	70°C		1			
5.	Commercial parts 70°C, Military, Cold, Ambient, Hot	1		1		
6.	Initial at 70°C, plan to reduce to Ambient.	2				
7.	Wafer at Ambient, final package per MD STD 883, 5004, 5005, Class C.				I	•

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B. Burn-in Conditions

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[, , , , , , , , , , , , , , , , , , ,		:	DEVICE		
RES	PONSE	8080	6800	8008	2901	1802
1.	125°C, dynamic, outputs loaded, performed as part of QA sampling, not normal por- tion of production test.		2			
2.	125°C, dynamic, outputs loaded.	1.			1	
3.	At customers request only, 125°C, static, outputs loaded.	3				
4.	At customers request 125°C to 160°C, dynamic, outputs loaded.				1	
5.	Performed as part of QA sampling, static mode, no pattern applied, outputs loaded, 125°C.				1	
6.	Only performed if contract specifies. Have capability to do full military temperature range and dynamic type burn-in.				1	
7.	Military only, 150°C, 40 Hours minimum, Øl, Ø2, clocked, out- puts loaded.	1		1		
8.	No burn-in.	1				1 .
9.	None at present.		1			

C. Datalog Format and Hardcopy

	· · ·			DEVICE	1	
RES	PONSE	8080	6800	8008	2901	1802
1.	6 Bins, hardcopy of Bin distribution obtained.	1				
2.	Go/NoGo Testing, hard- copy of Bin count.	1		- -	3	
3.	Bin classification, hardcopy of Bin count.	4	3	1	• • •	1
4.	Bin classification: Pass, Fail, DC, Fail Functional, no hardcopy obtained.		-		1	

D. Percentage of Devices Screened

	DEVICE				
RESPONSE	8080	6800	8008	2901	1802
100%	6	3	1	4	1

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Department Responsible for Production Testing Ε.

		DEVICE					
RE	SPONSE	8080	6800	8008	2901	1802	
1.	Production Operations	1		1	•		
2.	Production Control	J					
3.	Production Testing	1				1	
4.	Incoming Inspection	2	1		1		
5.	Product Engineering]	1		·		
6.	Manufacturing Engineering	-	1			·	
7.	Bipolar Microprocessor Department		-		1		
8.	Quality Assurance				1		
9.	Operations Department				1		

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F. Use of 38510 Specification

	······································	DE VI CE								
RES	PONSE	8080	6800	8008	2901	1802				
1.	Are testing to what the 8080, 38510 is antici- pated to contain.	٦								
2.	Are testing to in-house version of 38510, spec- ification for 8080, written by Quality Assurance Department.	1								
3.	Nonean in-house spec- ification is used which parallels a class C military specification.	1			-					
4.	Are using 38510 slash sheet.		٦							
5.	Use in-house version of 38510.			-	1	-				
6.	Will generate in-house version.					1				
7.	None	3	2		1					

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G. Types of Functional Failures

	· · · · · · · · · · · · · · · · · · ·			DEVICE		
RESPONSE		8080	6800	8008	2901	1802
1.	Totally inoperative parts, functionally.	1				
2.	Normal process and packaged related failures.	1			ו	
3.	Package devices are pre- dominantly functional failures.	1	1			
4.	DC tests are predominantly leakage failures; func- tional failures are parts that wholly inoperative.					1
5.	No data available.	2	2		2	
7.	No comment.	1		1	1	

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VI. <u>Types of Problems Encountered in Testing Microprocessors</u>

The problems being encountered in the testing of microprocessors do not reflect upon an individual microprocessor but rather the concept of testing a central processing unit intergrated on one LSI chip. The following is a summary of all comments received.

The range of problems encountered in testing microprocessors is best presented by establishing a categorical list derived from both manufacturer's and user's. These problems are:

1. None

2. Time Involved

3. Money Expenditures

4. Knowledge of Device

5. User Understanding of Device Operation and Application

6. Appreciation of Total Efforts

7. Test Equipment

8. Accurate Technical, Information on Device

Item 1

Four (4) interviewers stated that no one area of testing presented unusual problems or problems considered to approach the limits of present test technology. The time factor encompasses all aspects of testing microprocessors. This includes test time, preparation of the total test program (production and characterization) and analysis of test results.

Item 3

The amount of monies involved in testing includes capital expenditures for equipment and program development.

Item 4 & 8

Before the device can properly be tested complete knowledge of the microprocessor is essential. Users are of the opinion that this effort is hindered by a lack of adequate technical information concerning device operation including accurate timing and instruction operations.

Item 5 & 6

User's who test microprocessors for outside companies and in-house departments are finding that those people responsible for management of these tasks do not appreciate the total effort of testing. The device application is often not fully stated, nor, is the complexity of the test hardware and software requirements understood. Only one interviewer indicated that presently available test equipment posed a problem in testing. This comment concerned the speed of test equipment with respect to test time. However, the time involved in preparing test programs as viewed from an ease of program development standpoint and the actual test time due to test system overhead requirements can also be considered a valid criticism under this heading.

Item 8

All user's except one stated that existing technical information about specific device operation is not sufficient. Additional information is needed which will accurately define total device operation in terms of timing and instruction execution.

VII. Recommendations for User Testing

Recommendations for user testing were found to touch upon just about every aspect of testing, ranging from determining the extent of testing required to tips on test program structure.

Collating all the comments gathered results in the following summary.

First, determine the nature of the MPU testing problem from consideration of such factors as application, reliability requirements, and money available.

The results of this study should then indicate the capabilities of the test system to be used including hardware/software trade-offs, ease of use, DC and AC test capabilities and provision of test result analysis. Test equipment possibilities also include the end product system or a uP development system, in addition to the option of designing a system in-house. Another alternative is to not buy test equipment but use a testing laboratory instead.

Overall test philosophy should be defined as early in the process as possible with the key objective of being as thorough as possible within the confines of times, money, and manpower available.

The actual test program should retain the objective of thoroughness

by functional verification of each module of the device followed by an interactive type test to insure that there is no module-to-module destruction of data. If possible, the test scheme should be designed such that modifications are easily installed at some later time.

Be prepared for the time and money expenditures that will be necessary for the design and implementation of a thorough testing plan. Additional considerations to be included are resources for providing facilities for the test equipment and personnel to operate and maintain these items. The following instruction sequence sensitivities, module weaknesses, or failures were either described during the study conducted and/or detected by Macrodata Corporation during its characterization of the device prior to this contract. All problems described that were verified by Macrodata have been reported to the manufacturer(s). In all cases, parts manufactured after reporting the problem areas did not exhibit these characteristics.

Verified By

Macrodata

Yes

Yes

Yes

Device

8080

Problem

It was detected on some devices that the Øl Yes clock cross couples noise that exceeded the threshold level on the HLDA input 1 ns.

- When running a test similar to the one described for the program counter, certain devices would fail to respond to a reset pulse every time.
- 3. When performing a test similar to the test described for the register array, some devices showed a sensitivity to H----B and H----D transfers when the 5 MSB's, in the data sequence were all 1's.
- Not all manufactured parts operate exactly alike. One 8080 will not execute a program

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Verified By

Device

<u>Problem</u>

Macrodata

instruction identical to that of another manufacturers part. The main differences lies in the execution of arithmetic instructions in that status flag operation is not always identical from one manufacturer to another. This difference between parts produced by different manufacturers still is present.

8008 1. It has been detected that if an instruction Yes sequence which causes the stack registers to perform push and pop operation is repeated multiple times, the device fails to operate. This was not detected on any other area within the device.

2. Some of the fail devices operated correctly No for a short period of time, but after a period of time the devices would fail to operate. This period of time was around 5 to 10 seconds. Once the device failed, it would not ever become operational again, even if power was removed and reapplied. The device became a total failure.

Verified B	y
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Device		Problem	Macrodata
2901	1.	The "A" output latch for the RAM would	Yes
		change state on some devices that were	
		operated at a slightly elevated temperature	
		and voltage (still within specification).	
		The problem was detected by shifting a	
		binary pattern of 1110 into the RAM and	
		holding this pattern and then addressing	
		another location with a pattern of 1111,	
		but not clocking this pattern into the	
		latch. The parts that exhibited this	
		sensitivity showed that the output latch	
		value changed from a 1110 pattern to a	
		1111 pattern.	
	~		

- Some parts that have been tested showed a sensitivity to a CHECKERBOARD pattern on the RAM.
- Not all parts will operate at their rated speed. Newer versions of these devices do not exhibit this problem.
- 4. It has been reported that the ALU section has shown some kind of sensitivity to either data, instruction, or a combination of the two. This sequence was not defined, so this failure could not be verified.

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No

Yes

No

DeviceProblem6800 &No problems were reported on these parts1802other than normal manufacturing processproblems, which were detected by themanufacturers.User's reported noextensive testing on either of thesedevices, therefore, no errors werereported by them.

Verified By

Macrodata

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IX. TEST EQUIPMENT

DC Requirement

1. Voltage/Current Force Function

Voltage Force Range = 0 to + 15 Volts

It is recommended that there should be two ranges within this total range.

Accuracy > .7% of Full Scale

Current Force Range = 500 pa to 50 ma

This range should be divided into at least three ranges.

Accuracy > .7% of Full Scale

2. Voltage/Current Measurement

Voltage Measurement = +15 Volts to -5 Volts

Recommended at least two ranges.

Accuracy > .3% Full Scale

Current Measurement = 500 pa to 300 ma

Recommended ranges: 2 uA Full Scale, 20 uA, 200 uA, 2 ma, 20 ma, 300 ma.

Accuracy - 0.5% Full Scale

Power Supplies

Three Device Bias Supplies Plus Ground

Voltage Range = \pm 15 Volts

Current Range = 300 ma, Minimum

Accuracy = 0.2% of Set Voltage for Testing

AC Voltage Requirements

Logical input voltage swing: +15 Volts to -1.5 Volts, Maximum

This voltage should be variable in 10 mV increments throughout the range.

+15 V -----

-1.5 V _____

Logical output voltage detection: +15 Volts to -1.5 Volts, Maximum This voltage should be variable in 10 mV increments throughout the range.

It is recommended that the output sampling circuit be able to detect both a VOL and VOH voltage simultaneously. This will allow for a functional test measurement in one pass.

Timing Requirements

It should be noted that all timing edges produced for input or output timing are required to be synchronized to one master clock generator.

Input

Clock Frequency = 10 MHz to DC.

Minimum Clock Pulse Width = 20 ns.

Clocks required = 2 Minimum - Device Clocks

1 Minimum - Data Bus Clock

1 Minimum - Data Bus I/O Control

2 Minimum - Control Signals for Setup and Hold Time

Measurements

Timing edge should be capable of being variable in 1 ns increments.

Output

Minimum of one output comparator strobe with both edges variable in 1 ns increments. Strobe positioning should vary over the complete clock input cycle.

With only one comparator strobe it will be required to make more than one functional test on the devices. This is required to verify all output timing of the particular devices.

Tester Configuration

To generate the basic patterns to test the microprocessor that have been previously described the following tester would be required. Figure 21 illustrates the block diagram of a basic tester.

Mass storage, such as disc, or extended RAM or shift register memory is used to store total test patterns.

A high-speed storage media consisting of high-speed RAM or shift register memory (minimum of 1K deep X 48 wide) is used to hold portions of total test pattern. Overlay of this memory is required from the mass storage medium.

The Pattern Control and Sequence control logic allows repetition of the same test pattern or series of patterns to reduce total test pattern size and enable performance of tests that would otherwise not be possible due



Figure 21: Basic Tester Block Diagram

to size of test pattern. The capability to allow real time error interrupt is also provided.

The Interface logic provides the necessary formatting of signals to DUT including voltage and timing levels and signal format in addition to the capability of holding a test pattern on the device while the highspeed storage media is overlayed by the mass memory.

The Error Detect circuit compares the output of the device under test with the previously stored output response pattern, alerting the pattern control and sequencer module of error conditions.

This basic system can be developed by a company whose testing requirements necessitate the use of such a system. Because of the design variations for the different microprocessors, a project of this type can become costly and time consuming. Since at least three test equipment manufacturers produce equipment that can perform the described test, it is recommended that a company consider purchasing this type of system from a commercially available supplier. Companies that produce this type of equipment are:

Fairchild Systems	Macrodata Corporation	Tektronic Systems	
San Jose, CA	Woodland Hills, CA	Beaverton, OR	

Software Requirements

The software requirements for the test system described in the preceding

section can be itemized as follows:

- 1. Disc Operating System
- 2. Test System Executive Program

3. Microprocessor Test Pattern Development Program

Discussion

In order to efficiently store the large quantities of test data necessary to execute the tests previously described, a magnetic disc based computer system was chosen. The use of the disc requires a sophisticated computer program to control storing and retrieval of information to and from the disc. Programs of this type are available from the manufacturer of the computer chosen for use and can be incorporated in the total system software by the manufacturer of the test system. The user also has the option of designing his own program. The test system Executive Program is a custom computer program designed and developed specifically by the manufacturer of the test equipment. The elements of such a program are many. First, a test system language must be developed to allow the user to easily develop test programs for a wide variety of devices. Additional necessary programs are Editor, List, and Assembly programs.

An Editor program is one which allows the user to modify existing programs in source language. List programs output the entire source or object code contents of a test program to a peripheral medium (line printer or video terminal) to allow examination of the contents of a program. The

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Assembly Program converts the source statements of a test program to a binary object code which is understandable by the computer. An Executive Program must be able to initiate to the different modules of the test system for storage and retrieval of information in addition to controlling their activities.

The Microprocessor Test Pattern Development Program is designed to simplify the development of the test patterns previously described. The most desirable and accurate form of this program would be one which would completely simulate the microprocessor from an input string consisting of mnemonics and data patterns. The total output of such a program is a clock cycle by clock cycle definition of all input and output pins of the microprocessor in response to the defined input instructions. This program also includes test system control data such as when to input microprocessor instructions and data patterns and also when to test the output pins. If the test system cannot accomodate testing of all device outputs simultaneously, several versions of the test pattern are necessary to completely verify each device pin. X. QUALIFICATION TEST VERSUS SCREENING TEST

The test required for qualification of the device should include:

- 1. All functional and DC tests as previously described.
- 2. Each functional module test should be verified over the complete voltage operating range of the device. The best means to do this is to generate shmoo plots which plot voltage (VDD, VBB, etc.) versus timing parameters and also voltage versus voltage.
- 3. All AC timings specified in the manufacturers data sheet should be verified. Again, the best method is shmooing voltage versus each individual timing parameter and other voltages. Voltage should be varied over the complete specification range.
- Qualification should consist of testing the device over the manufacturers full temperature range. Recommended temperatures are +125, +70, +25,
 Ø, and -55°C. All manufacturers do not perform this test except for normal AQL sampling.
- 5. An extensive burn-in program should be performed since manufacturers only perform this upon specific request from a customer. A recommended burn-in program should be at least 160 hours at 125°C with elevated voltages. Also, random dynamic signals should be applied continuously during the burn-in cycle. This is only a recommendation since further

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performed on the subject of microprocessor burn-in procedures.

 All DC specifications on the device should also be varied over the complete voltage range of the device. Again, using the shmoo plot method is recommended.

A 100% screening test should be based on the results from the qualification test. This test should include:

- Testing each functional module as previously described at upper and lower power supply limits and all combinations.
- 2. Testing all manufactures DC parameters.
- 3. If the device is to be used over the complete military temperature range, the test should be performed at +125, +25, and -70°C.
- 4. A burn-in conditioning should be conducted as previously recommended.
- Only critical timing should be verified in order to reduce test time. These should include minimum clock pulse width, clock frequency, and access time.

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ATTACHMENT 1

8080A FUNCTIONAL PIN DEFINITION

The following describes the function of all of the B080A I/O pins. Several of the descriptions refer to internal timing periods.

A15.A0 (output three-state)

ADDRESS BUS; the address bus provides the address to memory (up to 64K 8-bit words) or denotes the I/O device number for up to 256 input and 256 output devices. A_0 is the least significant address bit.

D7.D0 (input/output three-state)

DATA BUS; the data bus provides bi-directional communication between the CPU, memory, and I/O devices for instructions and data transfers. Also, during the first clock cycle of each machine cycle, the 8080A outputs a status word on the data bus that describes the current machine cycle. D_0 is the least significant bit.

SYNC (output)

SYNCHRONIZING SIGNAL; the SYNC pin provides a signal to indicate the beginning of each machine cycle.

DBIN (output)

DATA BUS IN; the DBIN signal indicates to external circuits that the data bus is in the input mode. This signal should be used to enable the gating of data onto the 8080A data bus from memory or I/O.

READY (input)

READY; the READY signal indicates to the 8080A that valid memory or input data is available on the 8080A data bus. This signal is used to synchronize the CPU with slower memory or 1/O devices. If after sending an address out the 8080A does not receive a READY input, the 8080A will enter a WAIT state for as long as the READY line is low. READY can also be used to single step the CPU.

WAIT (output)

WAIT; the WAIT signal acknowledges that the CPU is in a WAIT state.

WR (output)

WRITE; the \overline{WR} signal is used for memory WRITE or I/O output control. The data on the data bus is stable while the \overline{WR} signal is active low ($\overline{WR} = 0$).

HOLD (input)

HOLD; the HOLD signal requests the CPU to enter the HOLD state. The HOLD state allows an external device to gain control of the 8080A address and data bus as soon as the 8080A has completed its use of these buses for the current machine cycle. It is recognized under the following conditions:

• the CPU is in the HALT state.

• the CPU is in the T2 or TW state and the READY signal is active. As a result of entering the HOLD state the CPU ADDRESS BUS (A_{15}, A_0) and DATA BUS (D_7, D_0) will be in their high impedance state. The CPU acknowledges its state with the HOLD AC-KNOWLEDGE (HLDA) pin.

HLDA (output)

HOLD ACKNOWLEDGE; the HLDA signal appears in response to the HOLD signal and indicates that the data and address bus



Pin Configuration

will go to the high impedance state. The HLDA signal begins at:

- T3 for READ memory or input.
- The Clock Period following T3 for WRITE memory or OUT-PUT operation.

In either case, the HLDA signal appears after the rising edge of ϕ_1 and high impedance occurs after the rising edge of ϕ_2 .

INTE (output)

INTERRUPT ENABLE; indicates the content of the internal interrupt enable flip/flop. This flip/flop may be set or reset by the Enable and Disable Interrupt instructions and inhibits interrupts from being accepted by the CPU when it is reset. It is automatically reset (disabling further interrupts) at time T1 of the instruction fetch cycle (M1) when an interrupt is accepted and is also reset by the RESET signal.

INT (input)

INTERRUPT REQUEST; the CPU recognizes an interrupt request on this line at the end of the current instruction or while halted. If the CPU is in the HOLD state or if the Interrupt Enable flip/flop is reset it will not honor the request.

RESET (input)[1]

RESET; while the RESET signal is activated, the content of the program counter is cleared. After RESET, the program will start at location 0 in memory. The INTE and HLDA flip/flops are also reset. Note that the flags, accumulator, stack pointer, and registers are not cleared.

Vss Ground Reference.

VDD +12 ± 5% Volts.

V_{CC} +5 ± 5% Volts.

V_{BB} -5 ±5% Volts (substrate bias).

 $\phi_1, \phi_2 = 2$ externally supplied clock phases. (non TTL compatible)

8080A FUNCTIONAL PIN DEFINITION

The following describes the function of all of the 8080A I/O pins. Several of the descriptions refer to internal timing periods.

A15.A0 (output three-state)

ADDRESS BUS; the address bus provides the address to memory (up to 64K 8-bit words) or denotes the I/O device number for up to 256 input and 256 output devices. A_0 is the least significant address bit.

D7-D0 (input/output three-state)

DATA BUS; the data bus provides bi-directional communication between the CPU, memory, and I/O devices for instructions and data transfers. Also, during the first clock cycle of each machine cycle, the 8080A outputs a status word on the data bus that describes the current machine cycle. D_0 is the least significant bit.

SYNC (output)

SYNCHRONIZING SIGNAL; the SYNC pin provides a signal to indicate the beginning of each machine cycle.

DBIN (output)

DATA BUS IN; the DBIN signal indicates to external circuits that the data bus is in the input mode. This signal should be used to enable the gating of data onto the 8080A data bus from memory or I/O.

READY (input)

READY; the READY signal indicates to the 8080A that valid memory or input data is available on the 8080A data bus. This signal is used to synchronize the CPU with slower memory or 1/O devices. If after sending an address out the 8080A does not receive a READY input, the 8080A will enter a WAIT state for as long as the READY line is low. READY can also be used to single step the CPU.

WAIT (output)

WAIT; the WAIT signal acknowledges that the CPU is in a WAIT state.

WR (output)

WRITE; the \overline{WR} signal is used for memory WRITE or I/O output control. The data on the data bus is stable while the \overline{WR} signal is active low ($\overline{WR} = 0$).

HOLD (input)

HOLD; the HOLD signal requests the CPU to enter the HOLD state. The HOLD state allows an external device to gain control of the 8080A address and data bus as soon as the 8080A has completed its use of these buses for the current machine cycle. It is recognized under the following conditions:

• the CPU is in the HALT state.

• the CPU is in the T2 or TW state and the READY signal is active. As a result of entering the HOLD state the CPU ADDRESS BUS (A_{15},A_0) and DATA BUS (D_7,D_0) will be in their high impedance state. The CPU acknowledges its state with the HOLD AC-KNOWLEDGE (HLDA) pin.

HLDA (output)

HOLD ACKNOWLEDGE; the HLDA signal appears in response to the HOLD signal and indicates that the data and address bus



Pin Configuration

will go to the high impedance state. The HLDA signal begins at:
T3 for READ memory or input.

 The Clock Period following T3 for WRITE memory or OUT-PUT operation.

In either case, the HLDA signal appears after the rising edge of ϕ_1 and high impedance occurs after the rising edge of ϕ_2 .

INTE (output)

INTERRUPT ENABLE; indicates the content of the internal interrupt enable flip/flop. This flip/flop may be set or reset by the Enable and Disable Interrupt instructions and inhibits interrupts from being accepted by the CPU when it is reset. It is automatically reset (disabling further interrupts) at time T1 of the instruction fetch cycle (M1) when an interrupt is accepted and is also reset by the RESET signal.

INT (input)

INTERRUPT REQUEST; the CPU recognizes an interrupt request on this line at the end of the current instruction or while halted. If the CPU is in the HOLD state or if the Interrupt Enable flip/flop is reset it will not honor the request.

RESET (input)(1)

RESET; while the RESET signal is activated, the content of the program counter is cleared. After RESET, the program will start at location 0 in memory. The INTE and HLDA flip/flops are also reset. Note that the flags, accumulator, stack pointer, and registers are not cleared.

- Vss Ground Reference.
- VDD +12 ± 5% Volts.
- Vcc +5 ± 5% Volts.
- VBB -5 ±5% Volts (substrate bias).

 $\phi_1, \phi_2 = 2$ externally supplied clock phases. (non TTL compatible)

8080A

ABSOLUTE MAXIMUM RATINGS*

Temperature Under Bias	0°C to +70°C
Storage Temperature	-65°C to +150°C
All Input or Output Voltages	
With Respect to VBB	0.3V to +20V
Veg. Veg. and Veg. With Respect to Veg.	-0.3V to +20V

*COMMENT: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

D.C. CHARACTERISTICS

Power Dissipation . . .

 $T_A = 0^{\circ}C$ to 70°C, $V_{DD} = +12V \pm 5\%$, $V_{CC} = +5V \pm 5\%$, $V_{BB} = -5V \pm 5\%$, $V_{SS} = 0V$, Unless Otherwise Noted.

.... **1**.5W

Symbol	Parameter ·	· Min.	Тур.	Max.	Unit	Test Condition
VILC	Clock Input Low Voltage	V _{SS} -1		V _{SS} +0.8	V	
VIHC	Clock Input High Voltage	9.0		V _{DD} +1	v	}
VIL	Input Low Voltage	V _{SS} -1		V _{SS} +0.8	ν	· ·
VIH	Input High Voltage	3.3	1	V _{CC} +1	v	
VOL	Output Low Voltage			0.45	V	1 $1_{O1} \approx 1.9 \text{mÅ on all outputs},$
VOH	Output High Voltage	3.7			V	6 _H = -150μA.
DD (AV)	Avg. Power Supply Current (V _{DD})		40	70	mA	1
CC (AV)	Avg. Power Supply Current (V _{CC})		60	80	mA	Operation
BB (AV)	Avg. Power Supply Current (V _{BB})		.01	1	mA	1 1CY40 µsec
l _{iL}	Input Leakage			±10	μA	$V_{SS} \leq V_{IN} \leq V_{CC}$
ICL	Clock Leakage			±10	μA	V _{SS} ≤ V _{CLOCK} ≤ V _{DD}
I _{DL} [2]	Data Bus Leakage in Input Mode			-100 -2.0	μA mA	$V_{SS} \leq V_{IN} \leq V_{SS} + 0.8V$ $V_{SS} + 0.8V \leq V_{IN} \leq V_{CC}$
I _{FL}	Address and Data Bus Leakage During HOLD			+10 -100	μA	Vaddr/data = Vcc Vaddr/data = Vss + 0.45V

CAPACITANCE

 $T_{A} = 25^{\circ}C$ $V_{CC} = V_{DD} = V_{SS} = 0V, V_{BB} = -5V$

Symbol Parameter		Typ.	Max.	Unit	Test Condition
C _o	Clock Capacitance	17	25	pf	f _c = 1 MHz
CIN	Input Capacitance	6	10	pf	Unmeasured Pins
COUT	Output Capacitance	10	20	pf	Returned to V _{SS}

NOTES:

1. The RESET signal must be active for a minimum of 3 clock cycles.

2. When DBIN is high and V_{IN} > V_{IH} an internal active pull up will

be switched onto the Data Bus. 3. ΔI supply / $\Delta T_A = -0.45\%/^2C$.







A.C. - CHARACTERISTICS

TA = 0°C to 70°C, VDD = +12V ± 5%, VCC = +5V ± 5%, VBB = -5V ± 5%, VSS = 0V, Unless Otherwise Noted

Symbol	Parameter	Min.	Max.	Unit	Test Condition
1CY[3]	Clock Period	0.48	2.0	μsec	
t _r , t _f	Clock Rise and Fall Time	0	50	nsec	1
t _{ø1}	\$1 Pulse Width	60		nsec	1
102	¢2 Pulse Width	220		n sec	1
t _{D1}	Delay ϕ_1 to ϕ_2	0		n sec	
tD2	Delay ϕ_2 to ϕ_1	70		n sec	1
t _{D3}	Delay ϕ_1 to ϕ_2 Leading Edges	80		n sec	1
t _{DA} [2]	Address Output Delay From ϕ_2		200	n sec	
tDD [2]	Data Output Delay From ϕ_2		220	n sec	
toc [2]	Signal Output Delay From ϕ_1 , or ϕ_2 (SYNC, \overline{WR} , WAIT, HLDA)		120	nsec	
tDF [2]	DBIN Delay From ϕ_2	25	140	n sec	י ד- גן = 50pt
t _{D1} [1]	Delay for Input Bus to Enter Input Mode		tDF	n sec	1-
tDS1	Data Setup Time During ϕ_1 and DBIN	30		nsec]

TIMING WAVEFORMS [14]

(Note: Timing measurements are made at the following reference voltages: CLOCK "1" = 8.0V "0" = 1.0V; INPUTS "1" = 3.3V, "0" = 0.8V; OUTPUTS "1" = 2.0V, "0" = 0.8V.)



A.C. CHARACTERISTICS (Continued)

TA = 0°C to 70°C, VDD = +12V ± 5%, VCC = +5V ± 5%, VBB = -5V ± 5%, VSS = 0V, Unless Otherwise Noted

Symbol	Paramoter	Min.	Max.	Unit	Test Condition
IDS2	Data Setup Time to ϕ_2 During DBIN	150		n sec	
t _{DH} [1]	Data Hold Time From ϕ_2 During DBIN	[1]		n sec	· ·
t _{IE} (2)	INTE Output Delay From ϕ_2		200	n sec	C _L ≖ 50pf
t _{RS}	READY Setup Time During ϕ_2	120	1	n sec	1
t _{HS}	HOLD Setup Time to ϕ_2	140		nsec	1
t _{IS}	INT Setup Time During ϕ_2 (During ϕ_1 in Halt Mode)	120		n sec]
tH	Hold Time From ϕ_2 (READY, INT, HOLD)	0		n sec	
1 _{FD}	Delay to Float During Hold (Address and Data Bus)		.120	n sec	
tAW[2]	Address Stable Prior to WR	. [5]		n sec	רן
tDW[2]	Output Data Stable Prior to WR	(6)		n sec] .
twp[2]	Output Data Stable From WR	[7]		n sec	
twA[2]	Address Stable From WR	[7]		n sec	CL = 100pf: Address, Data
t _{HF} [2]	HLDA to Float Delay	[8]		n sec	
t _{WF} [2]	WR to Float Delay	[9]		n sec	
t _{AH} [2]	Address Hold Time After DBIN During HLDA	-20		n sec	





1. Data input should be enabled with DBIN status. No bus conflict can then occur and data hold time is assured. tDH = 50 ns or tDF, whichever is less.

2. Load Circuit.



3. $t_{CY} = t_{D3} + t_{r\phi2} + t_{\phi2} + t_{f\phi2} + t_{D2} + t_{r\phi1} > 480ns.$



The following are relevant when interfacing the 8080A to devices having VIH = 3.3V: a) Maximum output rise time from .8V to 3.3V = 100ns @ CL = SPEC.
b) Output delay when measured to 3.0V = SPEC +60ns @ CL = SPEC.
c) II CL = SPEC, add .6ns/pF if CL > CSPEC, subtract .3ns/pF ffrom modified delay) if CL < CSPEC.

tAW + 2 (CY - 1D3 - 1₁02 - 140nsec. tDW + 1CY - 1D3 - 1₁02 - 170nsec. H not HLDA, twD + twA + 1D3 + 1₁02 +10ns. H HLDA, twD + twA = twF. 6.

- 7.
- 8. 1HF + 1D3 + 1102 -50ns.
- 9.

5

 $t_{WF} = t_{D2} + t_{r02}$ -10ns Data in must be stable for this period during DBIN 'T3. Both t_{DS1} and t_{DS2} must be satisfied. 10.

- 11. Ready signal must be stable for this period during T2 or Tw, (Must be externally synchronized.)
- Hold signal must be stable for this period during T 2 or T withen entering hold mode, and during T 3, T 4, T 5 and T WH when in hold mode, (External synchronization is not required.) 13. Interrupt signal must be stable during this period of the last clock cycle of any instruction in order to be
- recognized on the following instruction, (External synchronization is not required.) 14. This turning diagram shows suming relationships only; it does not represent any specific mechine cycle

INSTRUCTION SET

The accumulator group instructions include arithmetic and logical operators with direct, indirect, and immediate addressing modes.

Move, load, and store instruction groups provide the ability to move either 8 or 16 bits of data between memory, the six working registers and the accumulator using direct, indirect, and immediate addressing modes.

The ability to branch to different portions of the program is provided with jump, jump conditional, and computed jumps. Also the ability to call to and return from subroutines is provided both conditionally and unconditionally. The RESTART (or single byte call instruction) is useful for interrupt vector operation.

Double precision operators such as stack manipulation and double add instructions extend both the arithmetic and interrupt handling capability of the 8080A. The ability to increment and decrement memory, the six general registers and the accumulator is provided as well as extended increment and decrement instructions to operate on the register pairs and stack pointer. Further capability is provided by the ability to rotate the accumulator left or right through or around the carry bit.

Input and output may be accomplished using memory addresses as I/O ports or the directly addressed I/O provided for in the 8080A instruction set.

The following special instruction group completes the 8080A instruction set: the NOP instruction, HALT to stop processor execution and the DAA instructions provide decimal arithmetic capability. STC allows the carry flag to be directly set, and the CMC instruction allows it to be complemented. CMA complements the contents of the accumulator and XCHG exchanges the contents of two 16-bit register pairs directly.

TYPICAL INSTRUCTIONS

Interrupt instructions

instructions

Register to register, memory reference, arithmetic or logical, rotate, return, push, pop, enable or disable

Immediate mode or I/O instructions

Jump, call or direct load and store

Data and Instruction Formats

Data in the 8080A is stored in the form of 8-bit binary integers. All data transfers to the system data bus will be in the same format.

 $\begin{bmatrix} D_7 & D_6 & D_5 & D_4 & D_3 & D_2 & D_1 & D_0 \end{bmatrix}$ DATA WORD

The program instructions may be one, two, or three bytes in length. Multiple byte instructions must be stored in successive words in program memory. The instruction formats then depend on the particular operation executed.

One Byte Instructions

D7 D6 D5 D4 D3 D2 D1 D0 OP CODE

Two Byte Instructions

D,	D ₆	D_5	D4	03	D2	D_1	Do	OP CODE
D,	D ₆	D5	D4	D ₃	D ₂	D1	Do	OPERAND

Three Byte Instructions

D,	D ₆	D5	D4	D3	D2	D	Do	0
D,	D ₆	D ₅	D4	D3	D ₂	Dı	Do	ι
D,	Dr	Ds	D₄	Da	D2	D,	Dn	н

PCODE

OW ADDRESS OR OPERAND 1

D₂ D₁ D₀ HIGH ADD RESS OR OPERAND 2

For the 8080A a logic "1" is defined as a high level and a logic "0" is defined as a low level.

٠.

INSTRUCTION SET

Summary of Processor Instructions

			Instruction Code[1]		Clock 171						Int	ructi	on C	ode i l	1		Clock (2)				
Maemonit	Description	07	06	05	D.	0	3 0;	0	1 00	Cycles	Mnemonic	Description	D,	D6	D5	1D4	Ð	0,	Ð	00	Cycles
····									·	··											
MOV?	Mave register to register	0	1	0	0	0	S	S	S	5	RZ	Return on tero	1	١	0	0	1	0	0	0	5/11
MOV M. /	Move register to memory	0	1.		1	U N	5	3	5		RNZ OD	Return on no zero		1	•	•	0	0	c	0	5/11
MCVIM	MOA6 WEWOLA ID LAGIZIEL	ň	1	ï	1	0	-	1	Ň	;	HP .	Return on positive			1	-		0	0	0	5/11
MVI	Move immediate register	õ	ò	ò	ò	Ď	i	÷	ň	5	R PE	Return on Oblity even	-	- 1 -	-	ò	-	ň	ň	Ň	5/11
MVIM	Move immediate memory	õ	ō	ĩ	ī	õ	i	i	ō	10	RPO	Return on parity odd	÷		÷	ň	ò	ŏ	ŏ	ŏ	5/11
INR	Increment register	0	0	D	D	0	1	0	Ō	5	RST	Restart	i	i.	Å	Ă	Ă	ī	ī	i i	11
DCRr	Decrement register	0	0	D	D	0	1	0	1	5	IN	Input	1	1	0	1	1	0	1	1	10
INR M	Increment memory	0	0	1	1	0	ł	0	0	10	OUT	Output	1	1	0	1	0	0	1	1	10
DCR M	Decrement memory	0	0	1	1	0	1	0	1	10	LXIB	Load immediate register	Q	0	Q	0	0	0	0	1	10
ADD r	Add register to A		0	0	0	0	S	S	S	4		Pair B & C								•	
AUCI	Add register to A with carry		0	ů	ů		5	\$	S	4	LXID	Load immediate register	0	0	0	1	0	٥	0	1	10
50Br	Subtract register from A		0	0	4	U 1	2	5	5	:	1	Pair O & E									
3087	subtract register from A			•	•		3	3	3	•		Load immediate register	0	0	1	U	U	U	U	1	10
ANA	And register with A	1	0	1	٥	0	s	5	s	4	1 1 1 60		•	•		1	•	•	٨	1	10
XRA I	Exclusive Or register with A	1	ā	1	ō	ĩ	s	ŝ	s	4	PUSHR	Push reporter Pair 8 & C op	Ň	1		6	6	ï	ő	i	
0 FA r	Or register with A	1	0	1	1	0	S	S	S	4		stack	•	•	v		v	•	•	•	
CMP r	Compare register with A	1	0	1	1	1	S	\$	5	4	PUSH D	Push register Pair D & E on	t	1	0	1	0	1	0	1	11
ADD M	Add memory to A	1	0	0	0	0	1	1	0	7		stack									
ADC M	Add memory to A with carry	1	0	0	0	1	1	1	0	7	PUSH H	Push register Pair H & L on	1	1	1	0	0	1	0	1	11
SUB M	Subtract memory from A	1	0	0	1	0	1	1	0	7		stack									
SBB M	Subtract memory from A	1	0	0	1	1	Ŧ	1	0	7	PUSH PSW	Push A and Flags	1	Ŧ	1	1	0	1	0	1	11
	with borrow		•		•	•				•		on stack	•								_
	And memory with A	-	0		0	4		1	0		POP B	Pop register pair B & C off	1	١.	0	0	0	0	0	1	10
ARA M	Dr. mamory with A	- 1	ň	-	ĩ		-	;	~	,		stack			~			~	•		
CHPM	Compare memory with A	i	ň	;	÷	ï		÷	ň	;	FUF D	Pop register pair U & E oll	1	ł	0	I	U	U	U	1	10
	Add immediate to A	i	ĭ	ò	ò	ò	÷	÷	ŏ	÷	POPH	Statts Pon register main H.S. L. off	,		,	n	0	•	٥	1	10
ACI	Add immediate to A with	1	1	ō	ō	ī	1	i	ō	;	1	stack	•	•		v	•	•	Ċ	•	
	Carry										POP PSW	Pop A and Flags	1	1	1	1	0	0	ò	1	10
SUI	Subtract immediate from A	1	1	0	1	0	1	ł	0	7	1	off stack	•								
\$BI	Subtract immediate from A	1	1	ø	1	1	1	1	0	7	⁻ STA	Store A direct	0	0	1	1	0	0	1	0	13
	with borrow										LDA	Load A direct	0	0	1	1	1	0	1	0	13
ANI	And immediate with A		!	1	0	0	1	1	0	1	ХСНС	Exchange D & E, H & L	t	1	ł	0	1	0	1	1	4
X KI	Exclusive Or immediate with			•	U		'		U	'		Registers					~			•	
0.81	P. immediate with A		1	5	1	۵	۱	1	n	,	CONT	Exchange top of stack, H & L		-	-		4	0		-	18
CPI	Compare immediate with A	i	i	i	i	ī	÷	i	ŏ	, ·	PCHI		÷	÷.	÷		;	ů.	0	÷	6
RLC	Rotate A left	ò	Ó	ò	0	0	i	1	1	4	DADB		ò	ò	ò	ŏ	i	ñ	õ	i	10
RAC	Rotate A right	0	0	0	อ	1	1	١	1	4	DADD	Add D & E to H & L	ō	ō	ō	ĩ	i	D	0	1	10
BAL	Rotate A left through carry	0	0	0	1	0	1	1	1	4	DADH	Add H & L to H & L	Ö	ō	1	0	۱	ō	0	1	10
RAR	Rotate A right through	0	0	0	1	ł	1	1	1	4	DAD SP	Add stack pointer to H & L	0	0	1	1	1	0	0	1	10
	Callà										STAX B	Store A indirect	D	0	0	0	0	0	1	0	7
JWb	Jump unconditional	1	1	0	0	0	0	1	1	10	STAX D	Store A indirect	0	0	0	1	0	0	1	0	1
JC	Jump on carry	.!	1	0	2	}	0	1	0	10	LDAX B	Load A indirect	0	0	0	0	1	0	1.	0	1
JNL JZ	Jump on no carry	:	:	0		1	0	:	ů n	10	LDAXD	Load A indirect	0	0	0	1	1	0	1	0	1
J4 NU 7	bump on zero	-	÷	0	ň	'n	ň	í	ň	10	INXB	Increment B & C registers	0	0	0	0	0	0	!		2
10	home an accelerat		÷	š	Ň	õ	ň	÷	õ	10	INXU	Increment D & E registers	0	0	0	1	0	0		!	
ar HA	humo on munut	÷	;	÷	÷	ĭ	ň	÷	ň	10	INXH	Increment H & L registers	0	Ű			0	0	1		2
JPF	Jump on parity EVED	i	i	1	ò	1	ō	i.	Ď	10	DCYR	Decrement Stack pointer	~	ŭ .	•		ň	Ň	-	-	2
170	Jump on parity odd	i	1	1	õ	٥	ō	1	ō	10	0000	Decrement D & F	ñ	ň	ň	ň	÷	ñ	÷.	5	2
CALL	Call unconditional	1	1	0	0	1	1	0	1	17	ОСХН	Decrement H & L	ŏ	õ	ň	ō.	i	õ	i	i	
CC 33	Call on carry	1	1	0	1	1	1	0	0	11/17	OCX SP	Decrement stack pointer	ō	õ	i	ĩ	i	ō	i	i	š
CNC	Call on no carry	1	1	0	١	0	1	0	0	11/17	CMA	Complement A	D	Ó	1	D	1	î.	1	1	4
C2	Call on zero	1	1	0	0	1	1	0	0	11/17	STC	Set carry	0	0	1	1	0	I.	1	1	4
CNZ	Cell on no zero	1	1	0	0	0	1	0	0	13/17	СМС	Complement carry	0	0	1	t	1	1	1	1	4
CP	Cell on positive	1	1	1	1	0	1	0	0	14/17	DAA	Decimal adjust A	0	0	1	0	0	1	1	1	4
CM	Call on minus	1	1	1	1	1	1	0	0	11/17	SHLD	Store H & L direct	0	0	Ŧ	0	0	0	1	0	16
CPE	Lali on parity even	1	1	1	U O			5	0	11/17	LHLO	Load H & L direct	0	0	!	0	!	0	!	0	16
047	Cell on perity 000	1			0	0	5	0	0	1017		Enable interrupts	2	1	2	1	1	0	2		4
80	Return on celly	-	÷	0	ĭ	i	ň	õ		5/11		Disable interrupt				0	v A	0		0	;
RNC	Return on on Certy	i	i	õ	1	å	ŏ	ŏ	å	5/11	1 ""	no operation	v	•	U	•	v	U	v	9	•
		•		-		-	-	-	-		1	•									
											1										

NOTES: 1. DDD or SSS ~ 000 B ~ 001 C ~ 010 D ~ 011 E ~ 100 H ~ 101 L ~ 110 Memory ~ 111 A. 2. Two possible cycle times, (5/11) indicate instruction cycles dependent on condition flags.

8008/8008-1

EIGHT-BIT MICROPROCESSOR

- Instruction Cycle Time 12.5 µs with 8008-1 or 20 µs with 8008
- Directly addresses 16K x 8 bits of memory (RAM, ROM, or S.R.)

- 48 Instructions, Data Oriented
- Address stack contains eight 14-bit registers (including program counter) which permit nesting of subroutines up to seven levels

Interrupt Capability

The 8008 is a single chip MOS 8-bit parallel central processor unit for the MCS-8 microcomputer system.

This CPU contains six 8-bit data registers, an 8-bit accumulator, two 8-bit temporary registers, four flag bits (carry, zero, sign, parity), and an 8-bit parallel binary arithmetic unit which implements addition, subtraction, and logical operations. A memory stack containing a 14-bit program counter and seven 14-bit words is used internally to store program and subroutine addresses. The 14-bit address permits the direct addressing of 16K words of memory (any mix of RAM, ROM or S.R.).

The instruction set of the 8008 consists of 48 instructions including data manipulation, binary arithmetic, and jump to subroutine.

The normal program flow of the 8008 may be interrupted through the use of the INTERRUPT control line. This allows the servicing of slow I/O peripheral devices while also executing the main program.

The READY command line synchronizes the 8008 to the memory cycle allowing any type or speed of semiconductor memory to be used.



ORIGINAL PAGE IS OF POOR QUALITY



8008 PHOTOMICROGRAPH

-208-

8008 FUNCTIONAL PIN DESCRIPTION



D0-D7

BI-DIRECTIONAL DATA BUS. All address and data communication between the processor and the program memory, data memory, and 1/O devices occurs on these 8 lines. Cycle control information is also available.

INT

INTERRUPT input. A logic "1" level at this input causes the processor to enter the INTERRUPT mode.

READY

READY input. This command line is used to synchronize the 8008 to the memory cycle allowing any speed memory to be used.

SYNC

SYNC output. Synchronization signal generated by the processor. It indicates the beginning of a machine cycle.

ϕ_1, ϕ_2

Two phase clock inputs.

S_0, S_1, S_2

MACHINE STATE OUTPUTS. The processor controls the use of the data bus and determines whether it will be sending or receiving data. State signals S_0 , S_1 , and S_2 , along with SYNC inform the peripheral circuitry of the state of the processor.

V_{CC} +5V ±5% V_{DD} -9V ±5%

BASIC INSTRUCTION SET

Data and Instruction Formats

Data in the 8008 is stored in the form of 8 bit binary integers. All data transfers to the system data bus will be in the same format,

0,	D ₆	D ₅	D4	D3	D.2	01	0 ₀				
DATA WORD											

The program instructions may be one, two, or three bytes in length. Multiple byte instructions must be stored in successive words in program memory. The instruction formats then depend on the particular operation executed.

One Byte Instructions		TYPICAL INSTRUCTIONS
0, 06 05 04 03 07 01 00	OP CODE	Register to registur, memory reference, 1/0 arithmetic or logical, rotate or
Two Byte Instructions		seture instructions
D, D6 05 D4 D3 02 D1 00	OP CODE	
0, 0 ₆ 0 ₅ 0 ₄ 0 ₃ 0 ₂ 0 ₁ 0 ₀	OPERAND	Immediate mode instructions
Three Byle Instructions		
D, D6 D5 D4 D3 D7 C, D0	OP CODE	•
D, D6 D5 04 D3 D7 D1 00	LOW ADDRESS	, JUMP or CALL instructions
× × 05 04 03 02 01 00	HIGH ADDRESS*	*For the third byte of this instruction, D_6 and D_7 are "don't care" bits,

For the MCS-8 $\stackrel{\text{TM}}{\text{a}}$ logic "1" is defined as a high level and a logic "0" is defined as a low level.

Index Register Instructions

The load instructions do not affect the flag flip flops. The increment and decrement instructions affect all flipflops except the carry.

	MINIMUM	INSTRUCTION CODE										
MNEMONIC	STATES REQUIRED	0	ס ל	; (50	4 D 3		D ₂ D ₁ D ₀			DESCRIPTION OF OPERATION	
(1) MOV (1. 12	(5)	ī	1		D	D	s	s	5	S	Load index register ry with the content of index register r2.	
12) MOV F. M	(8)	1	1		D	D	1	1	1	1	Load index register i with the content of memory register M.	
MOV M, r	(7)	1	1	1	1	1	\$	\$		S	Load memory register M with the content of index register r.	
(3) MVI .	(8)	0	0	0	D	0	1	1	0	0	Load index register r with data B B	
		8	8	8	B	в	в	8	<u>ا</u> و	в		
MVIM	(9)	0	0	1	1	1	1	1	(0	Load memory register M with data 8 B	
		в	8	Ð	В	в	в	Ø	E	в		
INR /	(5)	0	0	C	D	D	0	0) (0	Increment the content of index register r (r f A).	
DCR	(5)	0	0	C	D	D	0	0	1	1	Decrement the content of index register r (r # A).	

Accumulator Group Instructions

The result of the ALU instructions affect all of the flag flip-flops. The rotate instructions affect only the carry flip-flop.

						_		_	_		
ADD	(5)	11	0	0	0	0	5	5	5	S	Add the content of index register r, memory register M, or data
ADD M	(8)	11	0	0	0	0	1	1		1	BB to the accumulator, An overflow (carry) sets the carry
ADI	(8)	0	0	0	0	0	1	C)	0	the-liop.
1		6	8	8	в	8	в	E	3	8	
ADC /	(5)	1	0	0	0	١	5	S	5	s	Add the content of index register r, memory register M, or data
ADC M	(8)	T1	0	0	0	1	١	1		1	B.,, B from the accumulator with carry. An overflow (carry)
ACI	(8)	0	0	0	0	1	1	C	,	0	sets the carry flip-flop,
Į į		B	8	6	в	6	8	E	8	8	
SUB r	(5)	1	0	0	1	0	5	5		S	Subtract the content of index register r, memory register M, or
SUB M	(8)	1	0	0	1	0	1	1		1	data B B from the accumulator. An underflow (borrow)
SUI	(8)	0	0	0	1	0	1	C	,	0	sets the carry flip-flop.
		8	8	8	ø	8	B	e	۱	8	
\$8B /	(5)	1	0	0	1	1	5	S		\$	Subtract the content of index register r, memory register M, or data
588 M	(8)	1	0	0	1	1	1	1		1	data B , , , B from the accumulator with borrow. An underflow
581	(8)	0	0	0	1	1	1	C)	0	lborrow) sets the carry hip-hop.
		8	8	8	8	8	8	E	3	8	
		-	_	_	_		_	_	_	_	

BASIC INSTRUCTION SET

[MINIMUM	1.01	STRUCTION	CODF	· ·····
MNEMONIC	STATES	0.0.	n. n. n.	h. n. n.	
	BEOURED	0,06	50403	20140	
ANA	(5)	1 0	1 0 0	555	Computer the logical AND of the content of index register -
ANAM	(8)	10	100	1 1 1	memory register M, or data B B with the accumulator.
ANI	(8)	0 0	100	1.0 0	
		<u> 8 8</u>	<u> </u>	888	
XRAI	(5)	10	101	<u>555</u>	Compute the EXCLUSIVE OR of the content of index register
XRAM	(8)	10	101	1 1 1	r, memory register M, or data B B with the accumulator,
XRI	(8)	0 0	101	100	
		BB	<u>B B 8</u>	<u> 8 8 8</u>	
ORAN	(5)	10	1 1 0	<u> </u>	Compute the INCLUSIVE OF of the content of index register
ORI	181	0 0	1 1 0	100	r, memory register m, or data d , B with the accumulator .
0	(0)	88	8 8 8	BBB	
CMP r	(5)	10	1 1 1	S S S	Compare the content of index register r, memory register M.
CMP M	(8)	1 0	1 1 1	1 1 1	or data B B with the accumulator. The content of the
CPI	(8)	0 0	1 1 1	100	accumulator is unchanged.
		BB	8 B B	888	
RLC	(5)	0 0	000	0 1 0	Rotate the content of the accumulator left,
RRC	(5)	00	001	0 1 0	Rotate the content of the accumulator right.
RAL	(5)	0 0	0 1 0	010	Rotate the content of the accumulator left through the carry,
RAR	(5)	0 0	0 1 1	0 1 0	Rotate the content of the accumulator right through the carry.
Program Count	ter and Stack	Control Ir	ostructions		
(4) JMP	(11)	0 1	xxx	100	Unconditionally jump to memory address B3' B3B2 B2.
		82 82	B2 B2 B2	B2 B2 B2	
	<u> </u>	<u> </u>	838383	838383	
SNL ONL (5)	(9 or 11)	0 1	0 C4 C3	000	Jump to memory address B3B3B2B2 if the condition
		B2B2	B ₂ B ₂ B ₂	B2 B2 B2	flip-flop is false. Otherwise, execute the next intraction in sequence.
	(0 11)	<u>^</u>	1 6 6	0,0,0	
JC, JZ JM, JPE	19 07 117	82.82	81 81 81	83 83 83	flightan is true. Otherwise, execute the next instruction in sequence
		xx	83 83 83	B3 B3 B3	
CALL	(11)	0 1	XXX	1 1 0	Unconditionally call the subroutine at memory address B3
		82 B2	82 82 82	B2 B2 B2	B3B2B2. Save the current address (up one level in the stack).
	·	хx	83 83 83	83 83 83	
CNC, CNZ	(9 or 11)	0 1	0 C4C3	0 1 0	Call the subroutine at memory address B3B3B2B2 if the
Cr. Cr 0		82 82	B2 B2 B2	82 82 82	condition flip-flop is false, and save the current address (up one
	(0	- <u>-</u>	03 03 03	030303	level in the stack, otherwise, execute the next instruction in sequence.
CM, CPE	(90/11)	Bo Bo	7 U4 U3 Ba Ba Ba	Ba 8a Ba	condition flip-flop is true, and save the current address (up one
		xx	83 83 83	838383	level in the stack). Otherwise, execute the next instruction in sequence.
RET	(5)	0 0	xxx	1 1 1	Unconditionally return (down one level in the stack).
RNC, RNZ,	(3 or 5)	0 0 .	0 C4 C2	0 1 1	Return (down one level in the stack) if the condition flip-flop is
RP, RPO			4-3		false. Otherwise, execute the next instruction in sequence.
RC. AZ	(3 or 5)	0 0	1 64 62	0 1 1	Return (down one level in the stack) if the condition flip-flop is
RM, RPE			4 - 3		true. Otherwise, execute the next instruction in sequence.
RST	(5)	0 0	A A A	1 0 1	Call the subroutine at memory address AAA000 (up one level in the stack)
	Instructions				David the enclose of the relevant operation and (MAMA) and the
IN	(8)	01	0 U M	M M 1	nead the content of the selected input port (MMMM) into the
	(6)	0 1	RRM	M M 1	Write the content of the accumulator into the selected output
	(0)				port (RRMMM, RR / 00).
Machine Install	l				
wachine instru	(1)				Environment of OPPED years and remain there until intermined
HL I	(4)	1 1		1 1 1	Enter the STOTED state and remain there until interfubled,
L	(4)		- <u>-</u>		<u></u>

(1)

ES SSS Source Index Register DDD - Destination Index Register BIO011, C(0101, D(0111, E(1001, H(1011, L(110), Memory registers are addressed by the contents of registers H & L. Additional bytes of instruction are designated by BBBBBBB, X - "Don't Care". Flag flip-flops are defined by C4C3 carry 100 overflow or underflow1, zero (01-result is zero), sign (10 MSB of result is "1"), parity (11-parity is even). (2) (3) (4) (5)

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ABSOLUTE MAXIMUM RATINGS*

Ambient Temperature Under Bias	. 0°C to +70°C
Storage Temperature	-55°C to +150°C
Input Voltages and Supply Voltage With Respect	
to V _{CC}	+0.5 to −20V
Power Dissipation	1.0 W @ 25°C

COMMENT

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other condition above those indicated in the operational sections of this specification is not implied.

D.C. AND OPERATING CHARACTERISTICS

 $T_{A} = 0^{\circ}C \text{ to } 70^{\circ}C, V_{CC} = +5V \pm 5\%, V_{DO} = -9V \pm 5\% \text{ unless otherwise specified, Logic "1" is defined as the more positive level {V_{H}, V_{OH}}. Logic "0" is defined as the more negative level {V_{H}, V_{OH}}.$

CYUROL	BADAMETER		LIMITS			TEST		
STMBOL	FARAMETER	MIN.	TYP.	MAX.		CONDITIONS		
100	AVERAGE SUPPLY CURRENT- OUTPUTS LOADED*		30	60	mA	T _A = 25°C		
1,,	INPUT LEAKAGE CURRENT			10	μA	V _{IN} = 0V		
V _{IL}	INPUT LOW VOLTAGE (INCLUDING CLOCKS)	V _{DD}		V _{cc} -4.2	v			
V _{IH}	INPUT HIGH VOLTAGE (INCLUDING CLOCKS)	V _{cc} -1.5		V _{cc} +0.3	v			
VOL	OUTPUT LOW VOLTAGE			0.4	v	I _{OL} = 0.44mA C _L = 200 pF		
V _{oH}	OUTPUT HIGH VOLTAGE	V _{cc} - 1.5			v	l _{он} = 0.2mA		

*Measurements are made while the 8008 is executing a typical sequence of instructions. The test load is selected such that at $V_{OL} = 0.4V$, $I_{OL} = 0.44$ mA on each output.

A.C. CHARACTERISTICS

 $T_A = 0^{\circ}C$ to 70°C; $V_{CC} = +5V \pm 5\%$, $V_{DD} = -9V \pm 5\%$. All measurements are referenced to 1.5V levels.

		80	08	800)8-1			
		LIN	AITS	LIN	IITS		TEST CONDITIONS	
STMBUL	PARAMETER	MIN.	MAX.	MIN.	MAX.	UNIT	TEST CONDITIONS	
tcy	CLOCK PERIOD	2	3	1.25	3	μs	t _R ,t _F = 50ns	
t _R ,t _F	CLOCK RISE AND FALL TIMES		50		50	ns		
tợi	PULSE WIDTH OF ϕ_1	.70		.35		μs		
tợ2	PULSE WIDTH OF \$\$2	.55		.35		μs		
t _{D1}	CLOCK DELAY FROM FALLING EDGE OF ϕ_1 TO FALLING EDGE OF ϕ_2	.90	1.1		1.1	μs		
1 _{D2}	CLOCK DELAY FROM ϕ_2 TO ϕ_1	.40		.35		μs		
t ₀₃	CLOCK DELAY FROM ϕ_1 TO ϕ_2	.20		.20		μs .		
t _{DD}	DATA OUT DELAY		1.0		1.0	μs	C _L = 100pF	
¹ ОН	HOLD TIME FOR DATA BUS OUT	.10		.10		μs		
t _{IH}	HOLD TIME FOR DATA IN	[1]		[1]		μs		
t _{SD}	SYNC OUT DELAY		.70		.70	μs	C _L = 100pF	
^t S1	STATE OUT DELAY (ALL STATES EXCEPT T1 AND T11) ¹²¹		1.1		1.1	μs	C _L = 100pF	
1 ₅₂	STATE OUT DELAY (STATES T1 AND T11)		1.0		1.0	μs	C _L = 100pF	
^t RW	PULSE WIDTH OF READY DURING ϕ_{22} TO ENTER T3 STATE	.35		.35		μs		
t _{RD}	READY DELAY TO ENTER WAIT STATE	.20		.20		μs		

11 IN MIN 2 ISD

 121 If the INTERRUPT is not used, all states have the same output delay, $\mathrm{t_{S1}}$

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1. READY line must be at "0" prior to ϕ_{22} of T_2 to guarantee entry, into the WAIT state. 2. INTERRUPT line must not change levels within 200ns (max.) of falling edge of ϕ_1 .









TYPICAL A.C. CHARACTERISTICS



CAPACITANCE f = 1MHz; $T_A = 25^{\circ}C$; Unmeasured Pins Grounded

C1440001	× / / /	LIMIT (pF)					
STMBUL	1621	TYP.	MAX.				
C _{IN}	INPUT CAPACITANCE	5	10				
C _{D8}	DATA BUS I/O CAPACITANCE	5	10				
Cout	OUTPUT CAPACITANCE	6	10				
Am2901

Four-Bit Bipolar Microprocessor Slice

DISTINCTIVE CHARACTERISTICS GENERAL DESCRIPTION • Two-address architecture --The four-bit bipolar microprocessor slice is designed as a Independent simultaneous access to two working high-speed cascadable element intended for use in CPU's, registers saves machine cycles. peripheral controllers, programmable microprocessors and Eight-function ALU – numerous other applications. The microinstruction flexibi-Performs addition, two subtraction operations, and lity of the Am2901 will allow efficient emulation of almost five logic functions on two source operands. any digital computing machine. Flexible data source selection – The device, as shown in the block diagram below, consists ALU data is selected from five source ports for a of a 16-word by 4-bit two-port RAM, a high-speed ALU, total of 203 source operand pairs for every ALU and the associated shifting, decoding and multiplexing function. circuitry. The nine-bit microinstruction word is organized Left/right shift independent of ALU -into three groups of three bits each and selects the ALU Add and shift operations take only one cycle. source operands, the ALU function, and the ALU destina-Four status flags tion register. The microprocessor is cascadable with full Carry, overflow, zero, and negative. look-ahead or with ripple carry, has three-state outputs, and Expandable provides various status flag outputs from the ALU. Ad-Connect any number of Am2901's together for longer vanced low-power Schottky processing is used to fabricate word lengths. this 40-lead LSI chip. Microprogrammable – Three groups of three bits each for source operand, ALU function, and destination control. TABLE OF CONTENTS MICROPROCESSOR SLICE BLOCK DIAGRAM Block Diagram 3 4 Package Outlines..... 6 FUR soc Connection Diagram 7 7 8 8 DC Characteristics 9 c: 0CI 10 Switching Waveforms..... 11 A' IREADI 13 7 ADDRESS DIRECT DATA IN . OVERILIM OUTPUT A P OUIPUT DATA SELECTUR U DATA DUT

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ARCHITECTURE

A detailed block diagram of the bipolar microprogrammable microprocessor structure is shown in Figure 1. The circuit is a four-bit slice cascadable to any number of bits. Therefore, all data paths within the circuit are four bits wide. The two key elements in the Figure 1 block diagram are the 16-word by 4-bit 2-port RAM and the high-speed ALU.

Data in any of the 16 words of the Random Access Memory (RAM) can be read from the A-port of the RAM as controlled by the 4-bit A address field input. Likewise, data in any of the 16 words of the RAM as defined by the B address field input can be simultaneously read from the B-port of the RAM. The same code can be applied to the A select field and B select field in which case the identical file data will appear at both the RAM A-port and B-port outputs simultaneously.

When enabled by the RAM write enable (RAM EN), new data is always written into the file (word) defined by the B address field of the RAM. The RAM data input field is driven by a 3-input multiplexer. This configuration is used to shift the ALU output data (F) if desired. This three-input multiplexer scheme allows the data to be shifted up one bit position, shifted down one bit position, or not shifted in either direction.

The RAM A-port data outputs and RAM B-port data outputs drive separate 4-bit latches. These latches hold the RAM data while the clock input is LOW. This eliminates any possible race conditions that could occur while new data is being written into the RAM.

The high-speed Arithmetic Logic Unit (ALU) can perform three binary arithmetic and five logic operations on the two 4-bit input words R and S. The R input field is driven from a 2-input multiplexer, while the S input field is driven from a 3-input multiplexer. Both multiplexers also have an inhibit capability; that is, no data is passed. This is equivalent to a "zero" source operand.

Referring to Figure 1, the ALU R-input multiplexer has the RAM A-port and the direct data inputs (D) connected as inputs. Likewise, the ALU S-input multiplexer has the RAM A-port, the RAM B-port and the Q register connected as inputs.

This multiplexer scheme gives the capability of selecting various pairs of the A, B, D, Q and "O" inputs as source operands to the ALU. These five inputs, when taken two at a time, result in ten possible combinations of source operand pairs. These combinations include AB, AD, AQ, AO, BD, BQ, BO, DQ, DO and QO. It is apparent that AD, AQ and AQ are somewhat redundant with BD, BQ and BO in that if the A address and B address are the same, the identical function results. Thus, there are only seven completely non-redundant source operand pairs for the ALU. The Am2901 microprocessor implements eight of these pairs. The microinstruction inputs used to select the ALU source operands are the IQ, 11, and 12 inputs. The definition of IQ, 11, and 12 for the eight source operand combinations are as shown in Figure 2. Also shown is the octal code for each selection.

The two source operands not fully described as yet are the D input and Q input. The D input is the four-bit wide direct data field input. This port is used to insert all data into the working registers inside the device. Likewise, this input can be used in the ALU to modify any of the internal data files. The Q register is a separate 4-bit file intended primarily for multiplication and division routines but it can also be used as an accumulator or holding register for some applications.

The ALU itself is a high-speed arithmetic/logic operator capable of performing three binary arithmetic and five logic functions. The I_3 , I_4 , and I_5 microinstruction inputs are used to select the

ALU function. The definition of these inputs is shown in Figure 3. The octal code is also shown for reference. The normal technique for cascading the ALU of several devices is in a look-ahead carry mode. Carry generate, \vec{G} , and carry propagate, \vec{P} , are outputs of the device for use with a carry-look-ahead-generator such as the Am2902 ('182). A carry-out, C_{n+4} , is also generated and is available as an output for use as the carry flag in a status register. Both carry-in (C_n) and carry-out (C_{n+4}) are active HIGH.

The ALU has three other status-oriented outputs. These are F₃, F = 0, and overflow (OVR). The F₃ output is the most significant (sign) bit of the ALU and can be used to determine positive or negative results without enabling the three-state data outputs. F₃ is non-inverted with respect to the sign bit output Y₃. The F = 0 output is used for zero detect. It is an open-collector output and can be wire OR'ed between microprocessor slices. F = 0 is HIGH when all F outputs are LOW. The overflow output (OVR) is used to flag arithmetic operations that exceed the available two's complement number range. The overflow output (OVR) is HIGH when overflow exists. That is, when C_{n+3} and C_{n+4} are not the same polarity.

The ALU data output is routed to several destinations. It can be a data output of the device and it can also be stored in the RAM or the Q register. Eight possible combinations of ALU destination functions are available as defined by the I_6 , I_7 , and I_8 micro-instruction inputs. These combinations are shown in Figure 4.

The four-bit data output field (Y) features three-state outputs and can be directly bus organized. An output control (\overline{OE}) is used to enable the three-state outputs. When \overline{OE} is HIGH, the Y outputs are in the high-impedance state.

A two-input multiplexer is also used at the data output such that either the A-port of the RAM or the ALU outputs (F) are selected at the device Y outputs. This selection is controlled by the 1_6 , 1_7 , and 1_8 microinstruction inputs. Refer to Figure 4 for the selected output for each microinstruction code combination.

As was discussed previously, the RAM inputs are driven from a three-input multiplexer. This allows the ALU outputs to be entered non-shifted, shifted up one position (X2) or shifted down one position (\div 2). The shifter has two ports; one is labeled RAM₀ and the other is labeled RAM₃. Both of these ports consist of a buffer-driver with a three-state output and an input to the multiplexer. Thus, in the shift up mode, the RAM₃ buffer is enabled and the RAM₀ multiplexer input is enabled. Likewise, in the shift down mode, the RAM₀ buffer and RAM₃ input are enabled. In the no-shift mode, both buffers are in the high-impedance state and the multiplexer inputs are not selected. This shifter is controlled from the I₆, I₇ and I₈ microinstruction inputs as defined in Figure 4.

Similarly, the Q register is driven from a 3-input multiplexer. In the no-shift mode, the multiplexer enters the ALU data into the Q register. In either the shift-up or shift-down mode, the multiplexer selects the Q register data appropriately shifted up or down. The Q shifter also has two ports; one is labeled Q_0 and the other is Q_3 . The operation of these two ports is similar to the RAM shifter and is also controlled from I_6 , I_7 , and I_8 as shown in Figure 4.

The clock input to the Am2901 controls the RAM, the Q register, and the A and B data latches. When enabled, data is clocked into the Q register on the LOW-to-HIGH transition of the clock. When the clock input is HIGH, the A and B latches are open and will pass whatever data is present at the RAM outputs. When the clock input is LOW, the latches are closed and will retain the last data entered. If the RAM-EN is enabled, new data will be written into the RAM file (word) defined by the B address field when the clock input is LOW.



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	MICA	0 000	E	ALU S OPER	OURCE ANDS
12	1	'0	Octal Code	R	5
ε	L	ι	0		٥
L	L	н	1	•	8
ι	н	L	2	0	۵
L	н	н	3	0	B
н	L	L	4	0	A
н	L	н	5	D	A
н	н	L	6	D	0
н	н	н	1 7	D	0

	MICI	10 COD	ALU			
1 ₈	14	13	Octal Code	Function	Symbol	
ι	L	ι	0	R Plus S	R + \$	
L	ι	н	1	S Minus R	S A	
L	н	L	2	R Minus S	R – \$	
ι	н	н	3	RORS	RV\$	
н	L	L	- 4	RANDS	RA 5	
н	ι	н	5	RANDS	គី^ \$	
н	н	ι	6	R EX-OR S	R¥\$	
н н н 7		A EX-NOR S	RYS			

Figure 2. ALU Source Operand Control.

Figure 3. ALU Function Control.

	місі	RO COD	E	RAM FUNCTION		Q-REG. FUNCTION		Y	RAM SHIFTER		Q SHIFTER	
ł8	17	¹ 6	Octal Code	Shift	Load	Shift	Losd	Ουτρυτ	RAM0	RAM3	00	Q3
ι	L	L	0	×	NONE	NONE	F→Q	F	x	x	×	x
L	L	н	1	×	NONE	x	NONE	F	x	×	×	×
L	н	L	2	NONE	F → B	×	NONE	A	x	×	×	x
ι	н	н	3	NONE	F → 8	×	NONE	F	x	x	x	×
н	L	L	4	DOWN	F/2 → B	DOWN	Q/2 → Q	F	Fo	1N3	٩	IN3
н	L	н	5	DOWN	F/2 → B	×	NONE	F	۶ ₀	IN3	0 0	x
н	н	L	6	UP	2F → B	UP	20 → 0	F	IN _O	F3	INO	03
н	н	н	7	UP	2F → B	x	NONE	F.	INQ	F3	x	Q3

X= Don't care. Electrically, the shift pin is a TTL input internally connected to a three-state output which is in the high-impedance state. B = Register Addressed by B inputs. Up is toward MSB, Down is toward LSB.

.

Figure 4. ALU Destination Control.

	210 OCTAL	0	1	2	3	4	5	6	7	
CI T5 A4 L3	ALU Source ALU Function	Α, Ω	А, В	ο, α	О, В	0, A	D, A	D, Q	D, 0	
0	C _n = L R Plus S	A+Q	A+8	Q	B	A	D+A	D+Q	D	
	C _n ≈H	A+Q+1	A+B+1	Q+1 ·	B+1	A+1	D+A+1	D+Q+1	D+1	
1	Cn = L S Minus R	Q-A-1	B-A-1	Q-1	8-1	A_1	A-D-1	Q-D-1	-D-1	
_	C _n ≖H	Q-A	8-A	Q	8	A	A-D	Q-D	D	
2	Cn = L R Minus S	A-Q-1	A-8-1	-0-1	-B-1	-A-1	D-A-1	0-0-1	D-1	
	C _n = H	AQ	A-B	-O	-8	~A	D-A	D~Q	D	
3	RORS	AVQ.	A V B	۵	. 8	A	DVA.	DVQ	D	
4	R AND S	A A Q	A ^ B	0	0	0	DAA	0^0	0	
5	R AND S	⊼∧۵	Ā∧ B	٥	B	A	Ō∧A	ō∧o	0	
6	R EX-OR S	AVQ	A¥ B	0	8	•	DVA	DYQ	D	
7	REXNORS	A VQ	ĀVŪ	, Ó	Ĩ	X	· DV A	0+0	ō	
+ = P	/ • Plus; • Minus; V = OR; Λ = AND; γ = EX-OR									

Figure 5. Source Operand and ALU Function Matrix.

SOURCE OPERANDS AND ALU FUNCTIONS

There are eight source operand pairs available to the ALU as selected by the I_0 , I_1 , and I_2 instruction inputs. The ALU can perform eight functions; five logic and three arithmetic. The I_3 , I_4 , and I_5 instruction inputs control this function selection. The carry input, C_n , also affects the ALU results when in the arithmetic mode. The C_n input has no effect in the logic mode. When I_0 through I_5 and C_n are viewed together, the matrix of

Figure 5 results. This matrix fully defines the ALU/source operand function for each state.

The ALU functions can also be examined on a "task" basis, i.e., add, subtract, AND, OR, etc. In the arithmetic mode, the carry will affect the function performed while in the logic mode, the carry will have no bearing on the ALU output. Figure 6 defines the various logic operations that the Am2901 can perform and Figure 7 shows the arithmetic functions of the device. Both carry in LOW ($C_n = 0$) and carry in HIGH ($C_n = 1$) are defined in these operations.

	•	
Octal 1543, 1210	Group	Function
4 0 4 1 4 5 4 6	AND	A^Q A^B D^A D^Q
30 31 35 36	OR	AVQ AVB DVA DVQ
60 61 65	EX-OR	A∀Q A∀B D∀A
66		D∀Q
70 71 75 76	EX-NOR	AVO AVB DVA DVQ
72 73 74 77	INVERT	Ŭ BIĂ Ŭ
62 63 64 67	PASS	Q B A D
32 33 34 37	PASS	Q B A D
42 43 44 47	"ZERO"	0 0 0
50 51 55 56	MASK	Ā∧Q Ā∧B D∧A D∧Q

Figure 6. ALU Logic Mode Functions. (Cn Irrelevant) Figure 7. ALU Arithmetic Mode Functions.

LOGIC FUNCTIONS FOR G, P, Cn+4, AND OVR

The four signals G, P, C_{n+4} , and OVR are designed to indicate carry and overflow conditions when the Am2901 is in the add or subtract mode. The table below indicates the logic equations for these four signals for each of the eight ALU functions. The R and S inputs are the two inputs selected according to Figure 2.

Definitions (+ = OR)

$P_0 = R_0 + S_0$	G ₀ ≈ R ₀ S ₀
$P_1 = R_1 + S_1$	$G_1 = R_1 S_1$
P2 = R2 + S2	$G_2 = R_2S_2$
$P_3 = R_3 + S_3$	G3 = R3S1

 $C_4 = G_3 + P_3G_2 + P_3P_2G_1 + P_3P_2P_1G_0 + P_3P_2P_1P_0C_n$

 $C_3 = G_2 + P_2G_1 + P_2P_1G_0 + P_2P_1P_0C_n$

1543	Function	P	Ğ	C _{n+4}	OVR
0	R + S	P3P2P1P0	$G_3 + P_3G_2 + P_3P_2G_1 + P_3P_2P_1G_0$	• C4	C3 ∀ C4
1	S – R			titute $\overline{R_i}$ for R_i in definitions	······································
2	R – S			titute Si for Si in definitions	· · · · · · · · · · · · · · · · · · ·
3	R∨S	LOW P3P2P1P0		$\overline{P_3P_2P_1P_0} + C_n$	$\overline{P_3P_2P_1P_0} + C_n$
4	R∧S	LOW	$\overline{G_3 + G_2 + G_1 + G_0}$	G ₃ + G ₂ + G ₁ + G ₀ + C _n	G ₃ + G ₂ + G ₁ + G ₀ + C _n
5	R⊼S	LOW	■ Same as R ∧ S equation	is, but substitute $\overline{R_i}$ for R_i in defi	nitions
6	R∀S		Same as $\overline{R \forall S}$, but substitute	R _i for R _i in definitions	
7	R∀S	G ₃ + G ₂ + G ₁ + G ₀	G3+P3G2+P3P2G1+P3P2P1G0	$\frac{\overline{G_3 + P_3G_2 + P_3P_2G_1}}{+ P_3P_2P_1P_0 (G_0 + \overline{C_n})}$	See note

 $\mathsf{Note:} \left[\overline{\mathsf{P}}_2 + \overline{\mathsf{G}}_2 \overline{\mathsf{P}}_1 + \overline{\mathsf{G}}_2 \overline{\mathsf{G}}_1 \overline{\mathsf{P}}_0 + \overline{\mathsf{G}}_2 \overline{\mathsf{G}}_1 \overline{\mathsf{G}}_0 \mathsf{Cn} \right] \forall \left[\overline{\mathsf{P}}_3 + \overline{\mathsf{G}}_3 \overline{\mathsf{P}}_2 + \overline{\mathsf{G}}_3 \overline{\mathsf{G}}_2 \overline{\mathsf{P}}_1 + \overline{\mathsf{G}}_3 \overline{\mathsf{G}}_2 \overline{\mathsf{G}}_1 \overline{\mathsf{P}}_0 + \overline{\mathsf{G}}_3 \overline{\mathsf{G}}_2 \overline{\mathsf{G}}_1 \overline{\mathsf{G}}_0 \mathsf{Cn} \right]$

+ = OR

Figure 8.



Figure 9.





PIN DEFINITIONS

A₀₋₃ The four address inputs to the register stack used to select one register whose contents are displayed through the A-port.

B₀₋₃ The four address inputs to the register stack used to select one register whose contents are displayed through the B-port and into which new data can be written when the clock goes LOW.

 I_{0-8} The nine instruction control lines to the Am2901, used to determine what data sources will be applied to the ALU (I_{012}), what function the ALU will perform (I_{345}), and what data is to be deposited in the Q-register or the register stack (I_{678}).

Q₃ A shift line at the MSB of the Q register (Q₃) and the register stack (RAM₃). Electrically these lines are three-state outputs connected to TTL inputs internal to the Am2901. When the destination code on I₆₇₈ indicates an up shift (octal 6 or 7) the three-state outputs are enabled and the MSB of the Q register is available on the Q₃ pin and the MSB of the ALU output is available on the RAM₃ pin. Otherwise, the three-state outputs are electrically LS-TTL inputs. When the destination code calls for a down shift, the pins are used as the data inputs to the MSB of the Q register (octal 4) and RAM (octal 4 or 5).

Q0Shift lines like Q3 and RAM3, but at the LSB of the
Q register and RAM. These pins are tied to the Q3
and RAM3 pins of the adjacent device to transfer
data between devices for up and down shifts of the
Q register and ALU data.

 D_{0-3} Direct data inputs. A four-bit data field which may be selected as one of the ALU data sources for entering data into the Am2901. D₀ is the LSB.

- Y₀₋₃ The four data outputs of the Am2901. These are three-state output lines. When enabled, they display either the four outputs of the ALU or the data on the A-port of the register stack, as determined by the destination code I₆₇₈.
- \overline{OE} Output Enable. When \overline{OE} is HIGH, the Y outputs are OFF; when \overline{OE} is LOW, the Y outputs are active (HIGH or LOW).
- P, G The carry generate and propagate outputs of the Am2901's ALU. These signals are used with the Am2902 for carry-lookahead. See Figure 8 for the logic equations.
- OVR Overflow. This pin is logically the Exclusive-OR of the carry-in and carry-out of the MSB of the ALU. At the most significant end of the word, this pin indicates that the result of an arithmetic two's complement operation has overflowed into the sign-bit. See Figure 8 for logic equation.
- F = 0 This is an open collector output which goes HIGH (OFF) if the data on the four ALU outputs F_{0-3} are all LOW. In positive logic, it indicates the result of an ALU operation is zero.
- Cn The carry-in to the Am2901's ALU.
- Cn+4 The carry-out of the Am2901's ALU. See Figure 8 for equations.
- CP The clock to the Am2901. The Q register and register stack outputs change on the clock LOW to HIGH transition. The clock LOW time is internally the write enable to the 16 x 4 RAM which comprises the "master" latches of the register stack. While the clock is LOW, the "slave" latches on the RAM outputs are closed, storing the data previously on the RAM outputs. This allows synchronous master slave operation of the register stack.

MAXIMUM RATINGS (Above which the useful life may be impaired)

Storage Temperature	-65°C to +150°C
Temperature (Ambient) Under Bias	~55°C to +125°C
Supply Voltage to Ground Potential	-0.5 V to +6.3 V
DC Voltage Applied to Outputs for HIGH Output State	-0.5 V to +V _{CC} max.
DC Input Voltage	0.5 V to +5.5 V
DC Output Current, Into Outputs	30 mA

-30 mA to +5.0 mA

DC Input Current

1				OPEF	AT	ING F	RANGE	:			
}		P/	'N	Ambie	ent T	emper	ature		Vcc		
{		Am29	OIPC, DO)"C 10	o +70°C	· · ·	4.75	V to 5.25 V		
ļ .		Am290	01DM, F	M -5	5°Cι	o +125	°C	4.50	V to 5.50 V		
]				~				~			
	_		1Conto	STAND/	ARL U.S	7 D. 88'	EENIN 3 for Cla		Parte)	•	
	r		ALL O	CTD 993	T					aval	
	Step	,	Me	sthod		Con	ditions		Am2901PC, D0	Am2901DM, FM	
	Pre-Seal Visual	Inspection	21	010	В				100%	100%	
	Stabilization B	ake	1(008	с	24-hour 150°C			100%	100%	
	Temperature C	çcle	1(010	с	-65°C 10 cycle	to +150°C es		100%	100%	
	Centrifuge		20	001	В	10,000	G		100% *	100%	
	Fine Leak		10	014	A	5 x 10 -	8 atm-cc/c	cm3	100% *	100%	
	Gross Leak		1(014	C2	Fluoroc	arbon		100% *	100%	
	Electrical Test Subgroups	and 7	50	004	See defi	below finitions	or of subgrou	ıps	100%	100%	•
	Insert Addition	nal Screening h	ere for C	ass B Parts							
	Group A Samp	le Tests									
	Subgroup 1				ļ –			!	LTPD = 5	LTPD = 5	
	Subgroup 2				I				LTPD = 7	LTPD = 7	
	Subgroup 3	(50	005	See	below f	or	.	LTPD = 7	LTPD = 7	
	Subgroup 7				defi	initions (of subgrou	ps	LTPD = 7	LTPD = 7	
	Subgroup 8				1.				LTPD = 7	LTPD = 7	
	Subgroup 9								LTPD = 7	LTPD = 7	
•Not applicable	for Am2901PC	ADDI	ΓΙΟΝΑ	L SCRE	ENI	ING F	ORCL	.AS	S B PARTS		
		[1	MIL STD.8	83	<u> </u>			Level	7	
		Step		Method		Co	onditions	F	Am2901DMB, FM	/B	
		Burn-In		1015		D 16	125°C 50 hours m	nin.	100%	7	
		Electrical T	est	5004							
		Subgrou	p1			ł			100%	}	
		Subgrou	63	-		!			100%	1	
	1	Subgrou	07					}	100%		
		Subgroup	p.a.			Ļ			100%		
		Return to C	FOUP A 1	ests in Star	ndard	Screenin	ng				
C	RDERING	INFORMA	TION						GROUP A S	UBGROUPS	
					•		(as			D-883, method 50	105}
Package	· T	emperature		Order			Subgroup	<u>-</u> +-	Parameter	Temperature	
Type		Range		Number			1 			25 C Maximum rated tom	
		°					2 3		DC	Minimum rated tem	perature
Molded C	0 NR	$C to +70^{\circ}C$		AM2901P	C NC		7	- }	Function	25°C	
Hermetic	ע אוע הו_ מוח	□ L 10 +/U L 5°C 10 → 126	°c '	AM2001E)M		8	ļ	Function	Maximum and minim	num rated
Hermetic Fla	t Pack -5	$5^{\circ}C$ to +125	č	AM2901F	M			· 1		temperature	
Dice	0	°C 10 +70°C	· ·	AM2901X	(C		9		Switching	25°C	
1						1 1	10		awritering	maximum nated [cf	neperatur

Switching Switching Switching

9 10 11

Maximum Rated Temperature Minimum Rated Temperature

ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE (Unless Otherwise Noted) (Group A, Subgroups 1, 2 and 3)

Parameters	Description	Test Conditions (Note 1)		Min.	Τγρ. (Note 2)	Max.	Units		
			¹ Он •1. Yo, Y1, Y	6mA 2. ¥3	2.4				
			10н = −1.	0mA, Cn+4	2.4				
		Vcc = MIN.	104 = -8004A. OVR. P		2.4			Volts	
∨он	Output HIGH Voltage	VIN - VIH OF VIL	IOH = -60	10H = -600HA Fa					
			Юн = -60 ВАМо 3.	 ΟμΑ Ομ. 3	2.4				
			1он = -1.		2.4				
ICEX	Output Leakage Current for F = 0 Output	V _{CC} = MIN., V _{OH} = V _{IN} = V _{IH} or V _{IL}	5.5V				250	Α	
		• .	¹ ОL = 16п Yo, Y1, Y	nA 2, Y2, G			0.5		
			101 = 10	A. C			0.5		
VOL	Output LOW Voltage	VIN = VIH or VIL	101 = 8.01	nA. OVR. P	-		0.5	Volts	
			IOL = 6.0mA, OVK, P IOL = 6.0mA, F3 RAM0 3, Q0 3				0.5		
VIH	Input HIGH Level	Guaranteed input log voltage for all inputs	ical HIGH		2.0			Volts	
VIL	Input LOW Level	Guaranteed input log	ical LOW Military Commercial				0.7	Volts	
		voltage for all inputs			·		0.8		
	Input Clamp Voltage		18mA				-1.5	Volts	
			Clock, OE				-0.36	6 6 2 5 mA	
			Bo Bi Ba Ba				-0.36		
			0, 81, 82, 83				-0.36		
կլ	Input LOW Current	V _{CC} = MAX.	10, 11, 12, 16, 19				-0.72		
		• IN - 0.5 V	10, 11, 12,	<u>'6, '8</u>	· ·		-0.30		
			RAM ₀ , 3, Q ₀ , 3 (Note 4)				-0.72		
							-0.8		
							-3.0	-	
		•	Clock, OE A0, A1, A2, A3 B0, B1, B2, B3 D0, D1, D2, D3 VIN = 2.7V I3, I4, I5, I7				20	•	
	•						20	А ц	
							40		
чн	Input HIGH Current	VCC = MAX.					20		
		V _{IN} = 2.7V					40		
			BAMO 3, 00 3 (Note 4)		100		100		
			Cn				200		
4	Input HIGH Current	VCC = MAX., VIN =	5.5V				1.0	mA	
	<u>}</u>		Yo. Y1.	Vo = 2.4V			50		
			¥2, ¥3	Vo = 0.5V			-50		
IOZH IOZL	Off State (High Impedance) Output Current	V _{CC} = MAX.	RAM0, 3,	V _O = 2.4V (Note 4)			100	μA	
			Q _{0,3}	VO = 0.5V (Note 4)			-800	1	
	<u> </u>		Y0. Y1. Y	2, Y3, Ĝ	-15		-40		
		Vec 5 35V	C _{n+4} OVR, P F3		-15		-40	mA	
los	Output Short Circuit Current	VCC = 0.75V			-15		- 40		
		10 0.07			-15		- 40		
			RAM0, 3. 00, 3		-15		40		
1cc	Power Supply Current	V _{CC} - MAX.	Military			185	280	mA	
	1		Commercial			100	780	_	

Notes: 1. For conditions shown as MIN. or MAX., use the appropriate value specified under Electrical Characteristics for the applicable device type.
2. Typical limits are at V_{CC} = 5.0V, 25°C amblent and maximum loading.
3. Not more than one output should be shorted at a time. Duration of the short circuit test should not exceed one second.
4. These are three state outputs internally connected to TTL inputs. Input characteristics are measured with I_{G78} in a state such that the three state output is OFF.

GUARANTEED OPERATING CONDITIONS OVER TEMPERATURE AND VOLTAGE

Tables I, II, and III below define the timing requirements of the Am2901 in a system. The Am2901 is guaranteed to function correctly over the operating range when used within the delay and set-up time constraints of these tables for the appropriate device type. The tables are divided into three types of parameters; clock characteristics, combinational delays from inputs to outputs, and set-up and hold time requirements. The latter table defines the time prior to the end of the cycle (i.e., clock LOW-to-HIGH transition) that each input must be stable to guarantee that the correct data is written into one of the internal registers.

The performance of the Am2901 within the limits of these tables is guaranteed by the testing defined as "Group A, Subgroup 9" Electrical Testing. For a copy of the tests and limits used for subgroup 9, contact Advanced Micro Devices' Product Marketing.

TABLE

CYCLE TIME AND CLOCK CHARACTERISTICS

TIME	Am2901DC,PC	Am2901DM, FM
Read-Modify-Write Cycle (time from selection of A, B registers to end of cycle)	105ns	120ns
Maximum Clock Frequency to Shift Q Register (50% duty cycle)	9.5MHz	8.3MHz
Minimum Clock LOW Time	30ns	30ns
Minimum Clock HIGH Time	30ns	30ns
Minimum Clock Period	105ns	120ns

		•	
MAXIMUM COMBINATIONAL	PROPAGATION DELAYS	(all in ns, CL	≤15pF)

		Am290	DIDC, F	°C (0°0	C to +7	0°C; 5	V ±5%)	Am	29010	M, FM	(-55°	C to +	125°C;	5V ±1	0%)
To Output		F .		~ •	F=0	01/17	Sh Out	ift puts		-		~ ~	F=0	o) / D	Sh Outj	ift outs
From Input	Ť	r3	Cn+4	<u></u> , г	н <u>г</u> = 470	UVR	RAM ₀ RAM ₃	0 ₀ 03	Y	F 3	С _{п+4}	G, P	н∟= 470	OVR	RAM0 RAM3	0 ₀ 0 ₃
A, B	110	85	80	80	110	75	110	-	120	95	90	90	120	85	120	-
D (arithmetic mode)	100	70	70	70	100	60	95	-	110	80	75	75	110	65	105	-
D(I = X37) (Note 5)	60	50	-	-	60	-	60	-	65	55	-	-	65	-	65	-
Cn	55	35	30	1	50	40	55	-	60	40	30	-	55	45	60	-
I012	85	65	65	65	80	65	80	- .	90	70	70	70	85	70	85	-
1345	70	55	60	60	70	60	65	-	75	60	65	65	75	65	70	-
1678	55	_	-	-	-	-	45	45	60	. <u> </u>		-		_	50	50
OE Enable/Disable	40/25	-	-	·	-	-	-	-	40/25	-	-	-	-	-	-	-
A bypassing ALU (I = 2xx)	60	-	_	-	-	-	-	-	65	-	-	-	-	-	-	-
Clock _ (Note 6)	115	85	100	100	110	95	105	60	125	95	110	110	120	105	115	65

TABLE II

SET-UP AND HOLD TIMES (all in ns) (Note 1)

TABLE III

F	N	Am2901DC, PC (0°C	C to +70°C, 5V ±5%)	Am2901DM, FM(-55	°C to +125°C, 5V ±10%)
From input	ivotes	Set-Up Time	Hold Time	Set Up Time	Hold Time
A, B Source	2,4 3,5	105 t _{pw} L + 30	0	120 t _{pw} L + 30	0
B Dest,	2,4	tpwL + 15	0	tpwL +15	0
D (arithmetic mode)		100	0	110	0
D(I = X37) (Note 5)		60	0	65	0
C _n		55	0	60	0
I ₀₁₂		85	0	90	0
1 ₃₄₅		70	0	75	0
I ₆₇₈	4	tpwL + 15	0	t _{pw} L + 15	0
RAM0 3, Q0 3		30	0	30	0

Notes: 1. See Figure 11 and 12.

2. If the B address is used as a source operand, allow for the "A, B source" set-up time; if it is used only for the destination address, use the "B dest." set-up time,

Where two numbers are shown, both must be met.
 "tpwL" is the clock LOW time.
 DVO is the fastest way to load the RAM from the D inputs. This function is obtained with 1 = 337.

6. Using Q register as source operand in arithmetic mode, Clock is not normally in critical speed path when Q is not a source,

SET-UP AND HOLD TIMES (minimum cycles from each input)

time prior to the clock until the hold time after the clock. The set-up times allow sufficient time to perform the correct operation on the correct data so that the correct ALU data can be written into one of the registers.

Set-up and hold times are defined relative to the clock LOW-to-HIGH edge. Inputs must be steady at all times from the set-up $% A^{\prime}$



Figure 11. Minimum Cycle Times from Inputs. Numbers Shown are Minimum Data Stable Times for Am2901DC, in ns. See Table III for Detailed Information.







MICROPROCESSING UNIT (MPU)

The MC6800 is a monolithic 8-bit microprocessor forming the central control function for Motorola's M6800 family. Compatible with TTL, the MC6800 as with all M6800 system parts, requires only one +5.0-volt power supply, and no external TTL devices for bus interface.

The MC6800 is capable of addressing 65K bytes of memory with its 16-bit address lines. The 8-bit data bus is bidirectional as well as 3-state, making direct memory addressing and multiprocessing applications realizable.

- Eight-Bit Parallel Processing
- Bi-Directional Data Bus
- Sixteen-Bit Address Bus 65K Bytes of Addressing
- 72 Instructions Variable Length
- Seven Addressing Modes Direct, Relative, Immediate, Indexed, Extended, Implied and Accumulator
- Variable Length Stack
- Vectored Restart
- Maskable Interrupt Vector
- Separate Non-Maskable Interrupt Internal Registers Saved In Stack
- Six Internal Registers Two Accumulators, Index Register, Program Counter, Stack Pointer and Condition Code Register
- Direct Memory Addressing (DMA) and Multiple Processor Capability
- Clock Rates as High as 1 MHz
- Simple Bus Interface Without TTL
- Halt and Single Instruction Execution Capability





Characteristic		Symbol	Min	Тур	Max	Unit
Input High Voltage	Logic ø1,ø2	V _{IH} V _{IHC}	V _{SS} + 2.0 V _{CC} - 0.3	-	V _{CC} V _{CC} + 0.1	Vdc
Input Low Voltage	Logic φ1,φ2	VIĽ. VILC	$V_{SS} = 0.3$ $V_{SS} = 0.1$		V _{SS} + 0.8 V _{SS} + 0.3	Vdc
Clock Overshoot/Undershoot Input High Input Low	Level Level	VOS	V _{CC} 0.5 V _{SS} 0.5		V _{CC} + 0.5 V _{SS} + 0.5	Vdc
Input Leakage Current (V _{in} = 0 to 5.25 V, V _{CC} = max) (V _{in} = 0 to 5.25 V, V _{CC} = 0.0 V)	Logic* ¢1,¢2	lin		1.0	2.5 100	μAdc
Three-State (Off State) Input Current (V _{in} 0.4 to 2.4 V, V _{CC} = max)	D0-D7 A0-A15,R/W	ITSI		2.0	10 100	μAdc
Output High Voltage $(I_{Load} = -205 \mu \text{Adc}, \text{V}_{CC} = \text{min})$ $(I_{Load} = -145 \mu \text{Adc}, \text{V}_{CC} = \text{min})$ $(I_{Load} = -100 \mu \text{Adc}, \text{V}_{CC} = \text{min})$	D0-D7 A0-A15,R/W,VMA -BA	Vон	V _{SS} + 2.4 V _{SS} + 2.4 V _{SS} + 2.4	- 		Vdc
Output Low Voltage {I _{Load} = 1.6 mAdc, V _{CC} = min}		VOL	-		V _{SS} + 0.4	Vdc
Power Dissipation		РĎ	-	0.600	1.2	W
Capacitance [#] (V _{in} = 0, T _A = 25 ⁰ C, f = 1.0 MHz)	φ1,φ2 TSC DBE D0-D7 Logic Inputs	C _{in}	80 	120 7.0 10 6.5	160 15 10 12.5 8.5	ρF
	A0-A15,R/W,VMA	Cout	-		12	pF
Frequency of Operation		f	0.1	<u> </u>	1.0	MHz
Clock Timing (Figure 1) Cycle Time		t _{cyc}	1.0	_	10	μs
Clock Pulse Width (Measured at V _{CC} - 0.3 V)	φ1 φ2	Р₩ _{¢H}	430 450		4500 4500	ns
Total ϕ 1 and ϕ 2 Up Time		tut	940	_		ns
Rise and Fall Times (Measured between VSS + 0.3 V and	φ1,φ2 V _{CC} – 0.3 V <u>)</u>	^t ør, ^t øf	5.0		50	ns
Delay Time or Clock Separation (Measured at VOV = VSS + 0.5 V)		td	0		9100	ns
Overshoot Duration		tos	0		40	ns

*Except \overline{IRQ} and \overline{NMI} , which require 3 k Ω pullup load resistors for wire-OR capability at optimum operation. *Capacitances are periodically sampled rather than 100% tested.



MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Supply Voltage	Vcc	-0.3 to +7.0	Vdc
Input Voltage	Vin	0.3 to +7.0	Vdc
Operating Temperature Bange	TA	0 to +70	°C
Storage Temperature Hange	T _{stg}	·-55 to +150	°C
Thermal Resistance	AL	70	°C/W

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions he taken to avoid application of any voltage higher than maximum rated voltages to this high impedance circuit.

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READ/WRITE TIMING Figures 2 and 3, f = 1.0 MHz, Load Circuit of Figure 6.

Characteristic	Symbol	Min	. Тур	' Max	Unit
Address Delay	t _{AD}	-	220	300	ns
Peripheral Read Access Time i _{acc} = t _{ut} - (t _{AD} + t _{DSR})	tacc	-	-	540	ns
Data Setup Time (Read)	tDSR	100	-	-	ns
Input Data Hold Time	tH .	10	_	-	ns
Output Data Hold Time	tН	10	25	-	ńs
Address Hold Time (Address, R/W, VMA)	₹ан	50	75	-	រាទ
Enable High Time for DBE Input	^t EH	450	-	-	ns
Data Delay Time (Write)	^t DDW		165	225	ns
Processor Controls*					
Processor Control Setup Time	^t PCS	200	-	-	ns
Processor Control Rise and Fall Time	^t PCr ^{, t} PCf	-	-	100	ns
Bus Available Delay	^t BA		-	300	ns
Three State Enable	tTSE	-	-	40	∩s
Three State Delay	ttsd	— ,	-	700	ns
Data Bus Enable Down Time During ϕ 1 Up Time (Figure 3)	^t DBE	150	-	-	ns
Data Bus Enable Delay (Figure 3)	^t DBED	300	-	-	ns
Data Bus Enable Rise and Fall Times (Figure 3)	^t DBEr, ^t DBEf	-	-	25	ns

*Additional information is given in Figures 12 through 16 of the Family Characteristics - see pages 17 through 20.



FIGURE 3 - WRITE IN MEMORY OR PERIPHERALS





FIGURE 5 – TYPICAL READ/WRITE, VMA, AND ADDRESS OUTPUT DELAY versus CAPACITIVE LOADING



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FIGURE 6 - BUS TIMING TEST LOAD



TYPICAL POWER SUPPLY CURRENT



TA, AMBIENT TEMPERATURE (°C)

60

80

40

100

120

20

a

EXPANDED BLOCK DIAGRAM



Proper operation of the MPU requires that certain control and timing signals be provided to accomplish specific functions and that other signal lines be monitored to determine the state of the processor.

Clocks Phase One and Phase Two $(\phi 1, \phi 2)$ -- Two pins are used for a two-phase non-overlapping clock that runs at the V_{CC} voltage level.

Address Bus (A0-A15) – Sixteen pins are used for the address bus. The outputs are three-state bus drivers capable of driving one standard TTL load and 130 pF. When the output is turned off, it is essentially an open circuit. This permits the MPU to be used in DMA applications.

Data Bus (D0-D7) – Eight pins are used for the data bus. It is bi-directional, transferring data to and from the memory and peripheral devices. It also has three-state output buffers capable of driving one standard TTL load and 130 pF.

Halt — When this input is in the low state, all activity in the machine will be halted. This input is level sensitive. In the halt mode, the machine will stop at the end of an instruction, Bus Available will be at a one level, Valid Memory Address will be at a zero, and all other three-state lines will be in the three-state mode.

Transition of the Halt line must not occur during the last 250 ns of phase one. To insure single instruction operation, the Halt line must go high for one Clock cycle.

Three-State Control (TSC) – This input causes all of the address lines and the Read/Write line to go into the off or high impedance state. This state will occur 700 ns after TSC = 2.0 V. The Valid Memory Address and Bus Available signals will be forced low. The data bus is not affected by TSC and has its own enable (Data Bus Enable). In DMA applications, the Three-State Control line should be brought high on the leading edge of the Phase One Clock. The ϕ 1 clock must be held in the high state and the ϕ 2 in the low state for this function to operate properly. The address bus will then be available for other devices to directly address memory. Since the MPU is a dynamic device, it can be held in this state for only 4.5 μ s or destruction of data will occur in the MPU.

Read/Write (R/W) – This TTL compatible output signals the peripherals and memory devices whether the MPU is in a Read (high) or Write (low) state. The normal standby state of this signal is Read (high). Three State Control going high will turn Read/Write to the off (high impedance) state. Also, when the processor is halted, it will be in the off state. This output is capable of driving one standard TTL load and 90 pF.

Valid Memory Address (VMA) -- This output indicates to peripheral devices that there is a valid address on the address bus. In normal operation, this signal should be utilized for enabling peripheral interfaces such as the PIA and ACIA. This signal is not three-state. One standard TTL load and 90 pF may be directly driven by this active high signal. Data Bus Enable (DBE) — This input is the three-state control signal for the MPU data bus and will enable the bus drivers when in the high state. This input is TTL compatible; however in normal operation, it would be driven by the phase two clock. During an MPU read cycle, the data bus drivers will be disabled internally. When it is desired that another device control the data bus such as in Direct Memory Access (DMA) applications, DBE should be held low.

Bus Available (BA) — The Bus Available signal will normally be in the low state; when activated, it will go to the high state indicating that the microprocessor has stopped and that the address bus is available. This will occur if the Halt line is in the low state or the processor is in the WAIT state as a result of the execution of a WAIT instruction. At such time, all three-state output drivers will go to their off state and other outputs to their normally inactive level. The processor is removed from the WAIT state by the occurrence of a maskable (mask bit I = 0) or nonmaskable interrupt. This output is capable of driving one standard TTL load and 30 pF.

Interrupt Request (IRQ) - This level sensitive input requests that an interrupt sequence be generated within the machine. The processor will wait until it completes the current instruction that is being executed before it recognizes the request. At that time, if the interrupt mask bit in the Condition Code Register is not set, the machine will begin an interrupt sequence. The Index Register, Program Counter, Accumulators, and Condition Code Register are stored away on the stack. Next the MPU will respond to the interrupt request by setting the interrupt mask bit high so that no further interrupts may occur. At the end of the cycle, a 16-bit address will be loaded that points to a vectoring address which is located in memory locations FFF8 and FFF9. An address loaded at these locations causes. the MPU to branch to an interrupt routine in memory.

The Halt line must be in the high state for interrupts to be serviced. Interrupts will be latched internally while Halt is low.

The \overline{IRQ} has a high impedance pullup device internal to the chip; however a 3 k Ω external resistor to V_{CC} should be used for wire-OR and optimum control of interrupts.

Reset — This input is used to reset and start the MPU from a power down condition, resulting from a power failure or an initial start-up of the processor. If a high level is detected on the input, this will signal the MPU to begin the restart sequence. This will start execution of a routine to initialize the processor from its reset condition. All the higher order address lines will be forced high. For the restart, the last two (FFFE, FFFF) locations in memory will be used to load the program that is addressed by the program counter. During the restart routine, the interrupt mask bit is set and must be reset before the MPU can be interrupted by IRO. Figure 9 shows the initialization of the microprocessor after restart. Reset must be held low for at least eight clock periods after V_{CC}'reaches 4.75 volts. If Reset goes high prior to the leading edge of ϕ 2, on the next ϕ 1 the first restart memory vector address (FFFE) will appear on the address lines. This location should contain the higher order eight bits to be stored into the program counter. Following, the next address FFFF should contain the lower order eight bits to be stored into the program counter.

Non-Maskable Interrupt (NMI) – A low-going edge on this input requests that a non-mask-interrupt sequence be generated within the processor. As with the Interrupt Request signal, the processor will complete the current instruction that is being executed before it recognizes the NMI signal. The interrupt mask bit in the Condition Code Register has no effect on NMI. The Index Register, Program Counter, Accumulators, and Condition Code Register are stored away on the stack. At the end of the cycle, a 16-bit address will be loaded that points to a vectoring address which is located in memory locations FFFC and FFFD. An address loaded at these locations causes the MPU to branch to a nonmaskable interrupt routine in memory.

NMI has a high impedance pullup resistor internal to the chip; however a 3 k Ω external resistor to VCC should be used for wire OR and optimum control of interrupts.

Inputs IRQ and NMI are hardware interrupt lines that are sampled during ϕ^2 and will start the interrupt routine on the ϕ^1 following the completion of an instruction.

Figure 10 is a flow chart describing the major decision paths and interrupt vectors of the microprocessor. Table 1 gives the memory map for interrupt vectors.



Vector	Description	
MS LS		
FFFE FFFF	Restart	
FFFC FFFD	Non-maskable Interrupt	
FFFA FFFB	Software Interrupt	
FFF8 FFF9	Interrupt Request	



MPU REGISTERS

The MPU has three 16-bit registers and three 8-bit registers available for use by the programmer (Figure 11).

Program Counter – The program counter is a two byte (16-bits) register that points to the current program address.

Stack Pointer – The stack pointer is a two byte register that contains the address of the next available location in an external push-down/pop-up stack. This stack is normally a random access Read/Write memory that may have any location (address) that is convenient. In those applications that require storage of information in the stack when power is lost, the stack must be non-volatile.

Index Register -- The index register is a two byte register that is used to store data or a sixteen bit memory address for the Indexed mode of memory addressing.

Accumulators – The MPU contains two 8-bit accumulators that are used to hold operands and results from an arithmetic logic unit (ALU).



CC = Condition Codes (Also called the Processor Status Byte)

ACCB = Accumulator B

ACCA = Accumulator A

IXH = Index Register, Higher Order 8 Bits

- IXL = Index Register, Lower Order 8 Bits
- PCH ≈ Program Counter, Higher Order 8 Bits





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Condition Code Register – The condition code register indicates the results of an Arithmetic Logic Unit operation: Negative (N), Zero (Z), Overflow (V), Carry from bit 7 (C), and half carry from bit 3 (H). These bits of the Condition Code Register are used as testable conditions for the conditional branch instructions. Bit 4 is the interrupt mask bit (I). The unused bits of the Condition Code Register (b6 and b7) are ones.

Figure 12 shows the order of saving the microprocessor status within the stack.

MPU INSTRUCTION SET

The MC6800 has a set of 72 different instructions. Included are binary and decimal arithmetic, logical, shift, rotate, load, store, conditional or unconditional branch, interrupt and stack manipulation instructions (Tables 2 thru 6).

MPU ADDRESSING MODES

The MC6800 eight-bit microprocessing unit has seven address modes that can be used by a programmer, with the addressing mode a function of both the type of instruction and the coding within the instruction. A summary of the addressing modes for a particular instruction can be found in Table 7 along with the associated instruction execution time that is given in machine cycles. With a clock frequency of 1 MHz, these times would be microseconds.

Accumulator (ACCX) Addressing – In accumulator only addressing, either accumulator A or accumulator B is specified. These are one-byte instructions.

Immediate Addressing – In immediate addressing, the operand is contained in the second byte of the instruction except LDS and LDX which have the operand in the second and third bytes of the instruction. The MPU addresses

this location when it fetches the immediate instruction for execution. These are two or three-byte instructions.

Direct Addressing – In direct addressing, the address of the operand is contained in the second byte of the instruction. Direct addressing allows the user to directly address the lowest 256 bytes in the machine i.e., locations zero through 255. Enhanced execution times are achieved by storing data in these locations. In most configurations, it should be a random access memory. These are two-byte instructions.

Extended Addressing – In extended addressing, the address contained in the second byte of the instruction is used as the higher eight-bits of the address of the operand. The third byte of the instruction is used as the lower eight-bits of the address for the operand. This is an absolute address in memory. These are three-byte instructions.

Indexed Addressing – In indexed addressing, the address contained in the second byte of the instruction is added to the index register's lowest eight bits in the MPU. The carry is then added to the higher order eight bits of the index register. This result is then used to address memory. The modified address is held in a temporary address register so there is no change to the index register. These are two-byte instructions.

Implied Addressing – In the implied addressing mode the instruction gives the address (i.e., stack pointer, index register, etc.). These are one-byte instructions.

Relative Addressing – In relative addressing, the address contained in the second byte of the instruction is added to the program counter's lowest eight bits plus two. The carry or borrow is then added to the high eight bits. This allows the user to address data within a range of -125 to +129 bytes of the present instruction. These are twobyte instructions.

TABLE 2 - MICROPROCESSO	R INSTRUCTION SET -	- ALPHABETIC SEQUENCE
-------------------------	---------------------	-----------------------

ABA ADC ADD AND ASL ASR BCC BCS BCS BCC BCS BCS BCC BCS BCT BHI BIT BLE BLS	Add Accumulators Add with Carry Add Logical And Arithmetic Shift Left Arithmetic Shift Right Branch if Carry Clear Branch if Carry Set Branch if Equal to Zero Branch if Greater or Equal Zero Branch if Greater than Zero Branch if Higher Bit Test Branch if Less or Equal Branch if Lower or Same	CLR CLV CMP COM CPX DAA DEC DES DEX EOR INC INS INX	Clear Clear Overflow Compare Complement Compare Index Register Decimal Adjust Decrement Decrement Stack Pointer Decrement Index Register Exclusive OR Increment Increment Stack Pointer Increment Index Register	PUL ROL ROR RTI RTS SBA SBC SEC SEI SEV STA STS STX SUB	Pull Data Rotate Left Rotate Right Return from Interrupt Return from Subroutine Subtract Accumulators Subtract with Carry Set Carry Set Carry Set Interrupt Mask Set Overflow Store Accumulator Store Stack Register Store Index Register Subtract Software Interrupt
BLT BMI BNE BPL BRA BSR BVC BVS	Branch if Less than Zero Branch if Minus Branch if Not Equal to Zero Branch if Plus Branch Always Branch to Subroutine Branch if Overflow Clear Branch if Overflow Set	JMP JSR LDA LDS LDX LSR NEG NOP	Jump Jump to Subroutine Load Accumulator Load Stack Pointer Load Index Register Logical Shift Right Negate No Operation	TAB TAP TBA TPA TST TSX TXS	Transfer Accumulators Transfer Accumulators to Condition Code Reg Transfer Accumulators Transfer Condition Code Reg. to Accumulator Test Transfer Stack Pointer to Index Register Transfer Index Register to Stack Pointer Wait for Interrupt
CBA CLC CLI	Compare Accumulators Clear Carry Clear Interrupt Mask	ORA PSH	Inclusive OR Accumulator Push Data	••••••••••••••••••••••••••••••••••••••	wait for interrupt

TABLE 3 - ACCUMULATOR AND MEMORY INSTRUCTIONS

							AD	DRES	SINC	5 M(015						BOOLEAN/ARITHMETIC OPERATION	¢0	ND	. CO	101	REC
		11	MME	0	D	IREC	T		NDE	x	E	XTN	0	15	IPE I	r D	(All register labels	5	4	3	2	10
OPERATIONS	MNEMONIC	02	~	:	OP	~	:	٥P	•	::	09	-	:	OP	~	Ľ	refer to contents)	н	1	N	2	V C
Add	ADDA	38	2	2	9H	3	2	ÅΒ	5	2	88	4	3				A + M + A	1	•	:		1 1
	ADDB	CB	2	2	08	3	2	EB	5	2	FB	4	3				B + M - B	1	•	11	Ľ	1 1
Add Acmitrs	ABA		•	,		,	2			,	00		2	18	2	1			!		11	
Add with Larry	ADCA	63	;	2	01	3	;	F 9	5	5	19	4	3	i i			8 + M + C - R	l.		1:1	H	
And	ANDA	84	2	2	94	ž	ż	A4	5	ż	84	4	3				A · M - A	•			Ш	R
	ANDB	C4	2	2	D4	3	2	E4	5	2	F4	4	3				B • M - • B	•	•	I	1	R .
Bit Test	BITA	85	2	2	95	3	2	A5	. 5	2	85	4	3	1			A · M	•	•	:	T	R •
	BITB	C5	2	2	05	3	2	£5	5	?	F5	4	3				8 · M	•	•	!	1	R
Clear	CLR							6F	1	2	"	ь	3	46	2		00 M			L, H	s	R F
	CIRR													SF	2		00 - 8			B	s	ALF
Compare	CMPA	81	2	2	91	3	2	AI	5	2	81	4	3	1	-		A M		•	1		1
	СМРВ	C1	2	2	D1	3	2	El	5	2	FI	4	3				8 - M	•	•	11	1	1 1
Compare Acmitrs	CBA										1			11	2	1	A 8	•	•	11	T	1
Complement, 1's	COM	1			ļ			63	1	2	13	6	3				M M	!	•	11	Ш	R
	COMA													43	2		A → A Ēe	1.				R S
Complement 2's	NEG							0.0	,	,	20	6	٦	33	-	•	00 - M → M			i	ile	no
(Negate)	NEGA	1						1		•	1	•	•	40	2	1	00 - A → A	•	•	1		<u> </u>
•	NEGB													50	2	t	00 - B - B	•	•	:[: 6	DQ
Decimal Adjust, A	DAA													19	2	1	Converts Binary Add. of BCD Characters into BCD Format	•	•	:	:	:0
Decrement	DEC							6A	7	2	7A	6	3				M – 1 → M	•	•	11		4 •
	DECA	1												4A	2	1	A - 1 → A	•	•	1	1	4 •
e . ·	DECB				1	•	-			-			•	5A	2	1			•			4
Exclusive UH	EURA	88	2	2	98	2	2	88 58	5	2	58 F8	4	2				A⊕M → A B⊕M → B			;]		R
Increment	INC	1	2	-	00	5	2	60	7	2	70	6	3				M+1→M				ik	5)
	INCA									-		-	-	4C	2	1	A + 1 - A	•	•	:	:	Š.
	INCB					·								5C	2	1	B+1→B .	•	•		1	Ĵ.
Load Acmitr	LDAA	86	2	2	96	3	2	A6	5	2	B6	4	3				M→A	•	٠	1	1	R
	LDAB	C6	2	2	D6	3	2	E6	5	2	F6	4	3				M → B	•	•	1	1	R
Or, Inclusive	ORAA	8A	2	2	94	3	2		5	Z	BA	4	3				A+M→A		•	1	1	R
Purb Data	PSHA		2	4		3	2	EA	2	2	1	4	3	36	4	1	$A \rightarrow M_{CO} SP = 1 \rightarrow SP$					× I
	PSHB												•	37	4	i	$B \rightarrow M_{SP}, SP \rightarrow 1 \rightarrow SP$		•	•	•	•
Puli Data	PULA													32	4	1	SP + 1 - SP. MSP - A	•	•	•	•	• •
	PULB	}												33	4	1	$SP + 1 \rightarrow SP, M_{SP} \rightarrow B$	•	•	•	•	• •
Rotate Left	ROL							69	1	2	79	6	3				M	•	٠		: [<u>e</u> l :
	ROLA													49	2			•	•			<u>뙰</u> :
Rotate Right	ROR							66	1	2	76	6	3	33	"	.'	M)					ปี:
	RORA			1						-		•	-	46	2	- 1		•	•		ik	ē :
	RORB													56	2	١.	B C b7 - b0	•	•		1	: (ā
Shift Left, Arithmetic	ASL	I I						68	1	2	78	6	3				M]	•	•	1	٦K	<u>6</u> :
	ASLA													48	2	1		•	•		: (Ð!
Ch (1) D - ha Austana	ASLB	Î							,	•		ç	,	58	2	1	B) C 87 00		•			ឡ
Shill Right, Anthmetic	ASRA							6/	'	4	l″	0	3	47	,	1						約;
	ASRB	ł			1						1			57	2	1	B b7 b0 C				ił	ปี:
Shift Right, Logic	LSR	1						64	7	2	74	6	3				M)		•	R	ik	i (3
	LSRA													44	2	1	A 0-00000 - 0	•	٠	R	: K	: (ð
	LSAB	1									1			54	2	1	8 b7 b0 C	•	٠	R	10	i (ā
Store Acmitr.	STAA				97	4	2	A7	6	2	87	5	3				A M	•	٠	T	1	R
¢	STAB		•		07	4	2	ET	6	2	F7	2	3				B · M	•	•		1	R .
JUUITALI	SUBA		;	2	00	3	;	50	5	2	Fn	4	2				B = M + B					;[;
Subtract Acmites.	SBA	1	•	•	1		•			•	1.	•	-	10	2	1	A B A					ili
Subtr. with Carry	SBCA	82	2	2	92	3	2	AZ	5	2	82	4	3				A - M - C - A	•	•	1	1	i
	SBCB	C2	2	2	02	3	2	E2	5	2	F2	4	3				8 - M - C · B	•	•		1	1 1
Transfer Acriditis	TAB	í			ĺ									16	2	1	A ** B	•	•	4	1	R •
Total Trees of House	TBA						ļ	60	,		10	c		17	2	1	B · A	•	•		1	8
TEM, ZETO OF MINUS	151 7574							60	'	4	10	D	3	40	,	,	N - UU A - 00					ЫR
	TSIB													50	2	i	B - 00	1.				RIA
		J			L			L			l		<i>ل</i> ے		-			+-		-	-+-	+-

LEGEND:

0P Operation Code (He cadeconal), Bootean Inclusive OH, Ó Number of MPU Cycles, Boulean Exclusive O.H. :: Number of Program Bytes, M Complement of M, Arithmetic Plus, . Transfer Intu, ٠ Anthinetic Minus, 0 Bit Zero, Boulean AND, 00 Byle - Zeiu,

MSP - Contents of memory toration pointed to be Stack Pointer,

Note — Accumulator addressing mode instructions are included in the column for IMPLIED addressing

CONDITION CODE SYMBOLS:

H Half carry from bit 3,

- 1 Interrupt musk
- N Negative (sign bit)
- 2 Zria (byte)
- V Overflow, 7's complement
- C Carry from lot 7
- R Reset Always
- S Set Always
- 1 Test and set of true, cleared otherwise
- Nus Affected

TABLE 4 - INDEX REGISTER AND STACK MANIPULATION INSTRUCTIONS

																		CO	ND	. CC) D E	RE	G.
		50	AME	D	Ø	IREC	:1	. 1	NDE	x	E	XTN	0	IN	PLI	ED		5	4	3	2	3	0
POINTER OPERATIONS	MNEMONIC	OP	~	::	OP	~	"	OP	~	::	OP	~	"	OP	~	=	BOOLEAN/ARITHMETIC OPERATION	н	1	N	z	۷	C
Compare Index Reg	CPX	8C	3	3	9C	4	2	AC	6	2	ec	5	3		[_		XH - M, XL - (M + 1)	•	•		:	(8)	•
Decrement Index Reg	DEX		1				1	{	ł	l l	ł	1	ł	09	4	1	X – 1 → X	•	•	•		•	•
Decrement Stack Potr	DES)		j				34	4	1	SP – 1 -• SP	•	•	•	•	•	•
Increment Index Reg	INX								i		1	1	•	08	4	1	X + 1 - X	•	•	٠	:	•	•
Increment Stack Potr	INS						1					Į		31	4	1	SP + 1 - + SP	•	•	٠	•	•	•
Load Index Reg	LOX	ÇE	3	3	DE	4	2	EE	6	2	FE	5	3			1	M -+ X _H , (M + 1) → X _L	•	•	(9)	11	R	•
Load Stack Pntr	LDS	8E	3	3	9E	4	2	AE	6	2	BE	5	3			1.	M -+ SPH, (M + 1) -+ SPL	•	•	(9)	:	R	•
Store Index Reg	STX				DF	5	2	EF	.1	2	FF	6	3				X _H → M, X _L → (M + 1)	•	•	<u>(</u>)	1:1	R	•
Store Stack Pntr	·STS				9F	5	2	AF	1	2	8F	6	3				SPH M, SPL (M + 1)	•	•	9	1:1	R	٠
Indx Reg Stack Patr	TXS													35	4	11	$X = 1 \rightarrow SP$	•	•	٠	•	•	٠
Stack Pntr -+ Indx Reg	TSX													30	4	1	SP + 1 → X	•	•	٠	•	٠	•

TABLE 5 - JUMP AND BRANCH INSTRUCTIONS

														_			CON	D. C	ODE	REG	
		RE	LAT	IVE	1	NDE	x	E	XTN	D	IN	PLIE	D]		5	4	3	2	1	0
OPERATIONS	MNEMONIC	OP	~	=	OP	~	#	OP	~	=	OP	~	ź]	BRANCH TEST	н	I	N	z	V	C
Branch Always	BRA	20	4	2						i –	1		Γ		None	•	•	•	•	•	•
Branch If Carry Clear	BCC	24	4	2							Į	ļ].		C = 0	•	•	•	•	•	•
Branch If Carry Set	BCS	25	4	2											C = 1	•	٠	•	•	•	•
Branch If = Zero	BEQ	27	4	2											Z = 1	•	٠	•	•	•	•
Branch II ≥ Zero	BGE	20	4	2										· ·	N ⊕ V ≈ 0	•	٠	•	•	•	•
Branch If > Zero	BGT	2E	4	2	1					ſ	Í	[[[Z + (N ⊕ V) = 0	•	•	•	•	•	•
Branch If Higher	вні	22	4	2						ļ)			Į	C + Z = 0	•	•	•	•	•	•
Branch If ≤ Zero	BLE	28	4	2				; 1							Z + (N ④ V) = 1	•	•	•	•	٠	•
Branch If Lower Or Same	BLS	23	4	2											C + Z = 1	•	•	٠	•	٠	•
Branch If < Zero	BLT	2D	4	2											N	•	•	٠	•	٠	•
Branch If Minus	BMI	28	4	2									(·		N = 1	•	•	•	•	•	•
Branch If Not Equal Zero	BNE	26	4	2										Į	Z = 0	•	•	•	•	•	•
Branch If Overflow Clear	BVC	28	4	2	1										V = 0	•	•	٠	•	٠	•
Branch If Overflow Set	BVS	29	4	2											V = 1	•	•	٠	•	•	•
Branch If Plus	BPL	2A	4	2		i									N = 0	•	٠	٠	•	٠	•
. Branch To Subroutine	BSR	8D	8	2	()								[•	•	•	•	٠	•
Jump	JMP				6E	4	2	7E	3	3				}	See Special Operations	•	٠	٠	•	٠	•
Juinp To Subroutine	JSR				AÐ	8	2	BD	9	3						•	٠	٠	•	٠	•
No Operation	NOP										01	2	11		Advances Prog. Cntr. Only	•	•	•	•	٠	•
Return From Interrupt	RTI										3B	10	1					- (<u>)</u> -		
Return From Subroutine	RTS					ļ		[39	5	1			•	•	٠	•	٠	•
Software Interrupt	SWI					į		ļ			3F	12	1	}	See Special Operations	•	•	٠	•	٠	•
Wait for Interrupt •	WAI										3E	9	1			•	\bigcirc	٠	٠	•	•

"WAI puts Address Bus, RAV, and Data Bus in the three-state mode while VMA is held low.

SPECIAL OPERATIONS JSR, JUMP TO SUBROUTINE:



TABLE 6 – CONDITION CODE REGISTER MANIPULATION INSTRUCTIONS

•							CON	D. C(DDE	REG	•
		IN	IPLIE	D		5	4	3	2	1	0
OPERATIONS	MNEMONIC	OP	~	#	BOOLEAN OPERATION	н	1	N	Z	v	C
Clear Carry	CLC	00	2	1	0 → C	٠	•	•	•	•	R
Clear Interrupt Mask	CLI	OE	2	1	0-+1	•	R	•	•	•	•
Clear Overflow	CLV	0A	2	1	0 → V	٠	•	•	•	R	•
Set Carry	SEC	00	2	1	1-+C	٠	•	•	•	•	S
Set Interrupt Mask	SEI	٥F	2	1	1-+1	٠	s	•	•	•	•
Set Overflow	SEV	08	2	1	1 -+ V	٠	•	•	•	l s	•
Acmltr A + CCR	ΤΑΡ	06	2	1	A CCR			-6	2)-		
CCR - • Acmitr A	TPA	07	2	1	CCR · A	٠	•	•	•	•	•

CONDITION CODE REGISTER NOTES: (Bit set if test is true and cleared otherwise)

		•	
1	(8a V)	Test Result 100000007	
2	(Bit C)	Test: Result - 00000000?	
3	(Bit C)	Test. Decidal value of most significant BCD. Character greater than nine? (Not cleared if previously set.)	
4	(Bit V)	Test Operand 10000000 prior to execution?	
5	(Bit V)	Test Operand _ 01111111 prove to execution?	
6	- (Bit V)	Test. Set equal to result of NOC after shift bas orcurred.	

		•
7	(Bit N)	Test: Sign bit of most significant (MS) byte = 1?
8	(Bit V)	Test: 2's complement overflow from subtraction of MS bytes?
9	(Bit N)	Test, Result less than zero? (Bit 15 - 1)
10	(All) .	Load Condition Code Register from Stack. (See Special Operations
11	(Bit I)	Set when interrupt occurs. If previously set, a Non-Maskable Interrupt is required to exit the wait state.
12	(AII)	Set according to the contents of Accoundator A.

TABLE 7 - INSTRUCTION ADDRESSING MODES AND ASSOCIATED EXECUTION TIMES (Timos in Machino Cyclos)

	- (Dual Operand)	ACCX	Immediate	Dwect	Extended	Indexed	Impled	R elative	· · ·	(Dual Operand)	ACCX	Immediate	Drect	Extended	Indexed	Implied
ABA		٠	٠		•	•	2		INC		2	٠	•	6	7	•
ADC	x	•	2	3	4	5	•	•	INS		•	•	•	•	•	4
ADD	x	•	2	3	4	5	٠	•	INX		٠	•	•		•	4
AND	x	٠	2	Э	4	5		•	JMP			٠		3	4	•
ASL		2	٠	٠	6	7	•	•	JSR					9	8	•
ASR	-	2	٠	•	6	7			LDA	x		2	3	4	5	• '
BCC		•	٠	•	٠	٠		4	LDS		•	3	4	5	6	•
BCS		•	٠	٠	٠	•	٠	4	LDX		•	З	4	5	6	• !
BEA		٠	٠	٠	٠	• •	٠	4	LSR		2	٠	•	6	7	•
BGE		٠	٠	٠		٠	٠	4	NEG		2	•	•	6	7	•
BGT		•	•	•	•	٠	•	4	NOP		•	٠	•	٠		2
BHI		٠	٠	٠	٠		٠	4	- ORA	X	٠	2	3	4	5	•
BIT	x	٠	2	3	4	5	٠	٠	PSH	•	•	٠	٠	٠	٠	4
BLE		٠	٠	٠	•	٠	٠	4	PUL	•	٠	٠	٠	٠	•	4
BLS		٠	٠	•	٠	٠	٠	4	RÖL		2	٠	٠	6	7	•
BLT		٠	٠	٠	٠	٠	٠	4	ROR		2	٠	•	6	7	•
BMI		٠	٠	•	•	٠	٠	4	RTI		٠	٠	٠	٠	•	10
BNE		٠	•	•	•	٠	٠	4	RTS		٠	٠	٠	٠	•	5
BPL		٠	•	٠	٠	٠	•	4	SBA		٠	٠	•	٠	٠	2
BRA			٠	٠	٠	٠	٠	4	SBC	x	٠	2	3	4	5	•
BSR		٠	٠	•	٠	٠	٠	8	SEC		٠	٠	•	٠	٠	2
BVC		•	٠	٠	٠	٠	٠	4	SEI		٠	٠	•	•	•	2
BVS		٠	٠	٠	٠	•	٠	4	SEV		٠	•	٠	•	٠	2
CBA		٠	٠	•	٠	٠	2	٠	STA	×	٠	•	4	5	6	•
CLC		٠	٠	٠	٠	٠	2	•	STS		٠	٠	5	6	7	٠
CLI		•	٠	•	•	•	2	٠	STX		٠	•	5	6	7	٠
CLR		2	٠	٠	6	7	•	٠	SUB	x	٠	2	3	4	5	•
CLV		٠	•	•	•	•	2	٠	SWI		٠	٠	٠	٠	•	12
CMP	x	•	2	3	4	5	٠	٠	TAB		٠	٠	•	•	٠	2
COM		2	•	•	6	7	•	٠	TAP		٠	٠	٠	٠	•	2
CPX		٠	3	4	5	6	•	٠	TBA		٠	•	٠	٠	٠	2
DAA		•	٠	• `	•	•	2	٠	TPA		•	٠	٠	.•	•	2
DEC		2	٠	. •	6	7	•	•	TST		2	٠	٠	6	7	•
DES		٠	٠	•	٠	٠	4	٠	TSX		٠	•	٠	٠	• '	4
DEX		٠	•	•	•	•	4	٠	TSX		٠	٠	٠	٠	٠	4
EOR	X		2	3	4	5			WAI						•	9

NOTE: Interrupt time is 12 cycles from the end of the instruction being executed, except following a WA1 instruction. Then it is 4 cycles.

an shirter an	PIN ASSIGNMI	ENT	PACKAGE DIMENSIONS
1 C	0 V _{SS} Res	et 1 40	
2 0	Halt TS	sch 39	B See Page 165 for
3 0	φ1 N.	C. 1 38	Plastic Package dimensions.
4 C	IRO ORI	2 37	
5 C	VMA DE	ер 36	A
6 D	NMI N.	c. p 35 👘	
7 0	BA R/	w 🛛 34	
8 0	Vcc c	oo 1 33	
9 C	A0 C	1 32	H-I-I D SEATING PLANE
10 0	A1 C	2 2 31	
11 0	A2 C	30 30	MILLIMETERS INCHES
12 [A3 D	4 2 29	DIM MIN MAX MIN MAX
13 d	A4 C	5 28	A 50.29 51.31 1.980 2.020
14 0	A5 D	6 27	$\begin{array}{c c c c c c c c c c c c c c c c c c c $
15 C	A6 ¹ r	7 1 26	D 0.38 0.53 0.015 0.021 NOTE:
16 [A7 . A1	50 25	F 0.76 1.40 0.030 0.055 1. LEADS, TRUE POSITIONED WITHIN
17 0	A8 61	AT 24	$\begin{array}{c c c c c c c c c c c c c c c c c c c $
18 [A9 A1	ah 23	J 0.20 0.33 0.008 0.013 CONDITION.
19 1	A10 A1	20.22	K 2.54 4.19 0.100 0.165
20 1	A11 Vo	-h 21	$\frac{L}{M} = \frac{14.60}{10^3} = \frac{15.37}{-10^3} = \frac{100}{10^3}$
	• 5		N 0.51 1.52 0.020 0.060

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SUMMARY OF CYCLE BY CYCLE OPERATION

Table 8 provides a detailed description of the information present on the Address Bus, Data Bus, Valid Memory Address line (VMA), and the Read/Write line (R/W) during each cycle for each instruction.

This information is useful in comparing actual with expected results during debug of both software and hard-

ware as the control program is executed. The information is categorized in groups according to Addressing Mode and Number of Cycles per instruction. (In general, instructions with the same Addressing Mode and Number of Cycles execute in the same manner; exceptions are indicated in the table.)

Address Mode and Instructions	Cycles	Cycle #	VMA Line	Address Bus		Data Bus		
IMMEDIATE								
ADC EOR ADD LDA AND ORA BIT SBC CMP SUB	2	1 2	1	Op Code Address Op Code Address + 1	1	Op Code Operand Data		
CPX LDS LDX	3	1 2 2	1 1	Op Code Address Op Code Address + 1 Op Code Address + 2	1 1 1	Op Code Operand Data (High Order Byte)		
	l			Op Code Address + 2	l ' l			
ADC EOR ADD LDA AND ORA BIT SBC CMP SUB	3	1 2 3	1 1 1	Op Code Address Op Code Address + 1 Address of Operand	1 1 1	Op Code Address of Operand Operand Data		
CPX LDS LDX	4	11Op Code Address21Op Code Address + 131Address of Operand41Operand Address + 1		1 1 1 1	Op Code Address of Operand Operand Data (High Order Byte) Operand Data (Low Order Byte)			
STA	4	1 2 3 4	1 1 0 1	Op Code Address Op Code Address + 1 Destination Address Destination Address	1 1 1 0	Op Code Destination Address Irrelevant Data (Note 1) Data from Accumulator		
STS STX	5	1 2 3 4 5	1 1 0 1 1	Op Code Address Op Code Address + 1 Address of Operand Address of Operand Address of Operand + 1	1 1 1 0 0	Op Code Address of Operand Irrelevant Data (Note 1) Register Data (High Order Byte) Register Data (Low Order Byte)		
INDEXED								
JMP	4	1 2 3 4	1 1 0 0	Op Code Address Op Code Address + 1 Index Register Index Register Plus Offset (w/o Carry)	1 1 1 1	Op Code Offset Irrelevant Data (Note 1) Irrelevant Data (Note 1)		
ADC EOR ADD LDA AND ORA BIT SBC CMP SUB	5	1 2 3 4 5	1 1 0 0 1	Op Code Address Op Code Address + 1 Index Register Index Register Plus Offset (w/o Carry) Index Register Plus Offset	1 1 1 1	Op Code Offset Irrelevant Data (Note 1) Irrelevant Data (Note 1) Operand Data		
CPX LDS LDX	6	1 2 3 4 5 6	1 1 0 0 1	Op Code Address Op Code Address + 1 Index Register Index Register Plus Offsut (w/o Carry) Index Register Plus Offset Index Register Plus Offset + 1	1 1 1 1 1 1	Op Code Offset Irrelevant Data (Note 1) Irrelevant Data (Note 1) Operand Data (High Order Byte) Operand Data (Low Order Byte)		

TABLE 8 - OPERATION SUMMARY

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TABLE 8 - OPERATION SUMMARY (Continued)

Address Mode	· ·	Çyele	VMA	······	R/W	
and Instructions	Cyclos	11	Line	Address Bus	Lino	Data Bus
INDEXED (Continued)	r		·			
SIA				Op Code Address		Up Code
		2		Op Code Address + 1		Offset
	6.	3		Index Hegister		Irrelevant Data (Note 1)
				Index Register Plus Offset (W/o Carry)		Irrelevant Data (Note 1)
		5	0	Index Register Plus Offset		Irrelevant Data (Note 1)
		6	-	Index Register Plus Offset	0	Operand Data
ASL LSR ASB NEG		1		Op Code Address		Op Code
CLR ROL		2	1	Op Code Address + 1		Offset
COM ROR DEC IST	7	3	0	Index Register		Irrelevant Data (Note 1)
INC		4	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)
	1	5		Index Register Plus Offset		Current Operand Data
		6	0	Index Register Plus Offset	1	Irrelevant Data (Note 1)
		7	1/0 (Note 3)	Index Register Plus Offset	0	New Operand Data (Note 3)
STS		1	1	Op Code Address	1	Op Code
STX	1	· 2	1	Op Code Address + 1	1	Offset
		3	0	Index Register	1	Irrelevant Data (Note 1)
	'	4	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)
		5	0	Index Register Plus Offset	1	Irrelevant Data (Note 1)
		6	1	Index Register Plus Offset	0	Operand Data (High Order Byte)
		7	1	Index Register Plus Offset + 1	0	Operand Data (Low Order Byte)
JSR		1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Offset
		3	0	Index Register	1	Irrelevant Data (Note 1)
		4	1	Stack Pointer	0	Return Address (Low Order Byte)
	o	5	1	Stack Pointer - 1	o	Return Address (High Order Byte)
		6	0	Stack Pointer – 2	1	Irrelevant Data (Note 1)
		7	0	Index Begister	1	Irrelevant Data (Note 1)
		8	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)
EXTENDED	<u> </u>					
JMP		1	1	Op Code Address	1	Op Code
	3	2	1	Op Code Address + 1	1	Jump Address (High Order Byte)
		3	1	Op Code Address + 2	1	Jump Address (Low Order Byte)
ADC EOR		1	1	Op Code Address	1	Op Code
ADD LDA		2	1	Op Code Address + 1	1	Address of Operand (High Order Byte
BIT SBC	4	3	1	Op Code Address + 2	1	Address of Operand (Low Order Byte
CMP SUB		4	1	Address of Operand	1	Operand Data
CPX		1	1	Op Code Address	1	Op Code
LDS		2	1	Op Code Address + 1	1	Address of Operand (High Order Byte
LDX	5	3	1	Op Code Address + 2	1	Address of Operand (Low Order Byte)
	•	4	1	Address of Operand	1	Operand Data (High Order Byte)
		5	1	Address of Operand + 1	1	Operand Data (Low Order Byte)
STA A		1	1	Op Code Address	1	Op Code
STA B		2	1	On Code Address + 1		Destination Address (High Order Byte
	5	3	1	Op Code Address + 2		Destination Address (Low Order Ryte
		4	0	Operand Destination Address		Irrelevant Data (Note 1)
		5	1	Operand Destination Address	0	Data from Accumulator
ASL LSR		1	1	Op Code Address	1	Op Code
ASR NEG		, ,		Oo Code Address + 1	1	Address of Operand (High Order Byte
CLR ROL COM BOR		2		On Code Address + 7		Address of Operand II ow Order Byte
DEC TST	6			Address of Operand		Current Operand Data
INC		- "		Address of Operand		Irrelevant Data (Note 1)
		с с	1/0	Address of Operand	0	New Operand Data (Note 3)
			(Note		, , , , , , , , , , , , , , , , , , ,	New Operation Data (NOTE 5)

·····	TABLE 8 – OPERATION SUMMARY (Continued)							
Address Mode	Custa	Cyclo	VMA	Address Due	R/W	Data Rus		
EXTENDED (Continued)	Cycles	1"	Luia	Address Bus				
STS	[1	1	Op Code Address	1	Op Code		
STX		2	1	Op Code Address + 1	1	Address of Operand (High Order Byte)		
		3	1	Op Code Address + 2	1	Address of Operand (Low Order Byte)		
	6	- 4	0	Address of Operand	1	Irrelevant Data (Note 1)		
	ł	5		Address of Operand	0	Operand Data (High Order Byte)		
	}	6	1	Address of Operand + 1	0	Operand Data (Low Order Byte)		
JSR		1	1	Op Code Address	1	Op Code		
	[2	1	Op Code Address + 1	1	Address of Subroutine (High Order Byte)		
	1	3	1	Op Code Address + 2	1	Address of Subroutine (Low Order Byte)		
		4	1	Subroutine Starting Address	1	Op Code of Next Instruction		
	9	5	1	Stack Pointer	0	Return Address (Low Order Byte)		
		6	1	Stack Pointer – 1	0	Return Address (High Order Byte)		
		7	0	Stack Pointer - 2	1	Irrelevant Data (Note 1)		
		8	0	Op Code Address + 2	1	Irrelevant Data (Note 1)		
		9	1	Op Code Address + 2	1	Address of Subroutine (Low Order Byte)		
INHERENT		I	I	i	LI			
ABA DAA SEC		1	1	Op Code Address	1	Op Code		
ASL DEC SEI	2	2	1	Op Code Address + 1	1	Op Code of Next Instruction		
CBA LSR TAB								
CLC NEG TAP		·						
CLR ROL TPA						· · ·		
CLV ROR TST								
DES		1	1	Op Code Address	1	Op Code		
DEX		2	1	Op Code Address + 1	1.	Op Code of Next Instruction		
	4	3	0	Previous Register Contents	1	Irrelevant Data (Note 1)		
		4	0	New Register Contents	1	Irrelevant Data (Note 1)		
PSH		1	1	Op Code Address	1	Op Code		
		.2	1	Op Code Address + 1	1.	Op Code of Next Instruction		
	4	3	1	Stack Pointer	0	Accumulator Data		
		4	0	Stack Pointer – 1	1	Accumulator Data		
PUL		1	1	Op Code Address	1	Op Code		
		2	1	Op Code Address + 1	1	Op Code of Next Instruction		
	4	3	0	Stack Pointer	1	Irrelevant Data (Note 1)		
		4	1	Stack Pointer + 1	1	Operand Data from Stack		
тѕх		1	1	Op Code Address	1	Op Code		
		2	1	Op Code Address + 1	. 1	Op Code of Next Instruction		
	4	3	0.	Stack Pointer	1	Irrelevant Data (Note 1)		
		4	0	New Index Register	1	Irrelevant Data (Note 1)		
TXS		1	1	Op Code Address	1	Op Code		
		2	1	Op Code Address + 1	1	Op Code of Next Instruction		
	4	3	0	Index Register	1	Irrelevant Data		
		4	0	New Stack Pointer	1	Irrelevant Data		
RTS		1	1	Op Code Address	1	Op Code		
		2	1	Op Code Address + 1	1	Irrelevant Data (Note 2)		
	5	3	0	Stack Pointer	1	Irrelevant Data (Note 1)		
		4	1	Stack Pointer + 1	1	Address of Next Instruction (High		
		5	1	Stack Pointer + 2	1	Address of Next Instruction (Low Order Byte)		

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t ODE D ION SUMMA -11 ADV IC

Address Mode and Instructions	Cycles	Ċycte #	VMA Line	Addross Bus	R/W Line	Data Bus
INHERENT (Continued)	·····					
WAI		1	1 1	Op Code Address	1	Op Code
	·	2	1	Op Code Address + 1	1	Op Code of Next Instruction
		3	1	Stack Pointer	0	Return Address (Low Order Byte)
		4	1	Stack Pointer – 1	0	Return Address (High Order Byte)
	9	5	1	Stack Pointer - 2	0	Index Register (Low Order Byte)
		6	1	Stack Pointer – 3	0	Index Register (High Order Byte)
		7	1	Stack Pointer 4	0	Contents of Accumulator A
	1	8	1	Stack Pointer – 5	0	Contents of Accumulator B
		9	1	Stack Pointer – 6 (Note 4)	1	Contents of Cond. Code Register
RTI		1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Irrelevant Data (Note 2)
		3	0	Stack Pointer	1	Irrelevant Data (Note 1)
		4	1	Stack Pointer + 1	1	Contents of Cond. Code Register from
• .		l	l	•		Stack
	10	5	1	Stack Pointer + 2	1	Contents of Accumulator B from Stack
	1	6	1	Stack Pointer + 3	1	Contents of Accumulator A from Stac
		7	1	Stack Pointer + 4	1	Index Register from Stack (High Order Byte)
		8	1	Stack Pointer + 5	1	Index Register from Stack (Low Order Byte)
		9	1	Stack Pointer + 6	1	Next Instruction Address from Stack (High Order Byte)
		10	1	Stack Pointer + 7	1	Next Instruction Address from Stack (Low Order Byte)
SWI .		1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Irrelevant Data (Note 1)
		3	1	Stack Pointer	0	Return Address (Low Order Byte)
		4	1	Stack Pointer - 1	0	Return Address (High Order Byte)
	1	5	1	Stack Pointer – 2	0	Index Register (Low Order Byte)
· .		6	1	Stack Pointer – 3	0	Index Register (High Order Byte)
•	12	7	1	Stack Pointer – 4	0	Contents of Accumulator A
		8	1	Stack Pointer – 5	0	Contents of Accumulator B
		9	1	Stack Pointer – 6	0	Contents of Cond. Code Register
		10	0	Stack Pointer – 7	1	Irrelevant Data (Note 1)
		11	1	Vector Address FFFA (Hex)	1	Address of Subroutine (High Order Byte)
		12	1	Vector Address FFFB (Hex)	1	Address of Subroutine (Low Order Byte)
RELATIVE	.	•	•		.	
BCC BHI BNE	T	1	1	Op Code Address	1	Op Code
BCS BLE BPL		2	1	Op Code Address + 1		Branch Offset
BEQ BLS BRA	4	3	0	Op Code Address + 2	1	Irrelevant Data (Note 1)
BGT BMI BVS		4		Branch Address		Irrelevant Data (Note 1)
	1	1	1	Op Code Address		Op Code
		2		Op Code Address + 1		Branch Offset
		2		Return Address of Main Program		Irrelevant Data (Note 1)
•				Stack Pointor		Return Address (Low Order Pute)
	8			Stack Pointer		Return Address (Low Order Byle)
	1	5		Stack Pointer - 1		neturn Address (mign Urder Byte)
		6	0	Stack Pointer – 2	!	Irrelevant Data (Note 1)
		7	0	Return Address of Main Program	'	Irrelevant Data (Note 1)
	1	8	0	Subroutine Address	1	frrelevant Data (Note 1)

If device which is addressed during this cycle uses VMA, then the Data Bus will go to the high impedance three-state condition. Note 1.

Note 2. Note 3.

Depending on bus capacitance, data from the previous cycle may be retained on the Data Bus. Data is ignored by the MPU. For TST, VMA = 0 and Operand data does not change. While the MPU is waiting for the interrupt, Bus Available will go high indicating the following states of the control lines: VMA is low: Address Bus, R/W, and Data Bus are all in the high impedance state. Note 4.



(CPU) designed for use as a general-purpose computing or control element in a wide range of stored-program systems or products.

It has the same basic COSMAC architecture as the CDP1801 microprocessor (see Fig. 5), but has an expanded instruction set, including a more powerful set of branch and ALU instructions, and enhanced hardware and performance features. The CDP1802 incorporates both the register and control chips of the CDP1801 on a single chip in a 40-lead hermetic dual-in-line ceramic package.

The CDP1802D is functionally identical to the CDP1802CD. The CDP1802D has a recommended operating voltage range of 3-12 volts; the CDP1802CD, a recommended operating voltage range of 4-6 volts.

- Flexible programmed I/O mode
- Program interrupt mode
- -
- On-chip DMA Four I/O flag inputs directly tested by branch instructions
- Programmable output port
- 91 easy-to-use instructions
- 16 x 16 matrix of registers for use as multiple program counters, data pointers, or data registers



The Pretiminary Data are intended for guidance purposes in evaluating the device for equipment design. The device is nuw being designed for inclusion in our standard line of commercially available products. For current information on the status of please contact your RCA Sales Office, s program,

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CDP1802D, CDP1802CD COSMAC Microprocesso

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Fig. 3-Typical instruction time vs. memory system access time,

ARCHITECTURE

The COSMAC block diagram is shown in Fig. 5. The principal feature of this system is a register array (R) consisting of sixteen 16bit scratchpad registers. Individual registers in the array (R) are designated (selected) by a 4-bit binary code from one of the 4-bit registers labeled N, P, and X. The contents of any register can be directed to any one of the following three paths:

- 1. the external memory (multiplexed, higher-order byte first, on to 8 memory address lines);
- 2. the D register (either of the two bytes can be gated to D);
- the increment/decrement circuit where it is increased or decreased by one and stored back in the selected 16-bit register.

The three paths, depending on the nature of the instruction, may operate independently or in various combinations in the same machine cycle.

With two exceptions, COSMAC instructions consist of two 8-clock-pulse machine cycles. The first cycle is the fetch cycle, and the second-and third, if necessary-are execute cycles. During the fetch cycle the four bits in the P designator select one of the 16 registers R(P) as the current program counter. The selected register R(P) contains the address of the memory location from which the instruction is to be fetched. When the instruction is read out from the memory, the higher-order 4 bits of the instruction byte are loaded into the I register and the lower-order 4 bits into the Niregister. The content of the program counter is automatically incremented by one so that R(P) is now "pointing" to the next byte in the memory.

The X designator selects one of the 16 registers R(X) to "point" to the memory for an operand (or data) in certain ALU or I/O operations.

The N designator can perform the following five functions depending on the type of instruction fetched:

 designate one of the 16 registers in R to be acted upon during register operations;



Fig. 4-Typical total power dissipation vs. clock input frequency.

- indicate to the I/O devices a command code or device-selection code for perioberals:
- indicate the specific operation to be executed during the ALU instructions, types of tests to be performed during the Branch instructions, or the specific operation required in a class of miscellaneous instructions (70-73 and 78-78);
- indicate the value to be loaded into P to designate a new register to be used as the program counter R(P);
- indicate the value to be loaded into X to designate a new register to be used as data pointer R(X).

The registers in R can be assigned by a programmer in three different ways: as program counters, as data pointers, or as scratchpad locations (data registers) to hold two bytes of data.

Program Counters

Any register can be the main program counter; the address of the selected register is held in the P designator. Other registers in R can be used as subroutine program counters. By a single instruction the contents of the P register can be changed to effect a "call" to a subroutine. When interrupts are being serviced, register R(1) is used as the program counter for the interrupt servicing routine. At all other times the register designated as program counter is at the discretion of the user.

Data Pointers

The registers in R may be used as data pointers to indicate a location in memory. The register designated by X (i.e., R(X)) points to memory for the following instructions (see Table 1):

- 1. ALU operations F0-F5, F7, 74, 75, 77;
- 2. output instructions 61 through 67;
- 3. input instluctions 69 through 6F;
- 4. certain miscellaneous instructions-70-73, 78.

The register designated by N (i.e., R(N)) points to memory for the "load D from memory" instructions ON and 4N and the "Store D" instruction **B**N. The register designated by P (i.e., the program counter) is

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used as the data pointer for ALU instructions F8-FD, FF, 7C, 7D, 7F. During these instruction executions the operation is referred to as "data immediate".

Another important use of R as a data pointer supports the built-in Direct-Memory-Access (DMA) function. When a DMA-In or DMA-Out request is received, one machine cycle is "stolen". This operation occurs at the end of the execute machine cycle in the current instruction. Register R(0) is always used as the data pointer during the DMA operation. The data is read from (DMA-Out) or written into (DMA-In) the memory location pointed to by the R(0) register. At the end of the transfer, R(0) is incremented by one so that the processor is ready to act upon the next DMA byte transfer request. This feature in the COSMAC architecture saves a substantial amount of logic when fast exchanges of blocks of data are required, such as with magnetic discs or during CRT-display-refresh cycles.

A program load facility, using the DMA-In channel, is provided to enable users to load programs into the memory. This facility provides a simple, one-step means for initially entering programs into the microprocessor system and eliminates the requirement for specialized "bootstrap" ROM's.

Data Registers

When registers in R are used to store bytes of data, four instructions are provided which allow D to receive from or write into either the higher-order- or lower-order-byte portions of the register designated by N. By this mechanism (together with loading by data immediate) program pointer and data pointer designations are initialized. Also, this technique allows scratchpad registers in R to be used to hold general data. By employing increment or decrement instructions, such registers may be used as loop counters.

The Q Flip Flop

An internal flip flop, Q, can be set or reset by instruction and can be sensed by conditional branch instructions. The output of Q is also available as a microprocessor output.

Interrupt Servicing

Register R(1) is always used as the program counter whenever interrupt servicing is initiated. When an interrupt request comes in and the interrupt is allowed by the program (again, nothing takes place until the completion of the current instruction) the contents of the X and P registers are stored in the temporary register T, and X and P are set to new values; hex digit 2 in X and hex digit 1 in P. Interrupt enable is automatically deactivated to inhibit further interruptions. The interrupt routine is now in control; the contents of T are saved by means of a single instruction (78) in the memory location pointed to by R(X). At the conclusion of the interrupt, the routine restores the pre-interrupted values of X and P with a single instruction (70 or 71). The interrupt enable flip-flop can be activated to permit further interrupts or can be disabled to prevent them.

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_		COSMAC Reg	ister	Summar	Y
D	8 Bits	Data Register (Accumulator)	N	4 Bits	Holds Low-Order Instr. Digit
DF	1 Bit	Data Flag (ALU Carry)	T	4 Bits	Holds High Order Instr. Digit
R	16 Bits	1 of 16 Scratchpad Registers		8 Bits	Holds old X, P after Interrupt
Ρ	4 Bits	Designates which register is			(X is high byte)
		Program Counter	ΙE	1 Bit	Interrupt Enable
×	4 Bits	Designates which register is Data Pointer	٥	1 Bit	Output Flip Flop

INSTRUCTION SET

The COSMAC instruction summary is given in Table I. Hexadecimal notation is used to refer to the 4-bit binary codes.

In all registers bits are numbered from the least significant bit (LSB) to the most significant bit (MSB) starting with 0.

R(W): Register designated by W, where W=N or X, or P

R(W).0: Lower-order byte of R(W) R(W).1: Higher-order byte of R(W) . NO = Least significant Bit of N Register Operation Notation M(R(N)) +D; R(N) + 1

This notation means: The memory byte pointed to by R(N) is loaded into D, and R(N) is incremented by 1.

TABLE I –	INSTRUCTION SUMMARY
(Fo	r Notes see nage 9)

INSTRUCTION	MNEMONIC	OP CODE	OPERATION
MEMORY REFERENCE		ľ	
LOAD VIA N	LDN	ON	M(R(N))+D; FOR N NOT 0
LOAD ADVANCE	LDA	4N	M(R(N))+D; R(N) +1
LOAD VIA X	LDX	F0	M(R(X))+D
LOAD VIA X AND ADVANCE	LDXA	72	M(R(X))+D; R(X) +1
LOAD IMMEDIATE	LDI	F8	M(R(P))+D; R(P) +1
STORE VIA N	STR	5N ·	D+M(R(N)) -
STORE VIA X AND	STXD	73	D+M(R(X)); R(X) –1
DECREMENT	l]	l
REGISTER OPERATIONS			
INCREMENT REG N	INC	1N	R(N) +1
DECREMENT REG N	DEC	2N	R(N) = 1
INCREMENT REG X	IRX	60	R(X) +1
GET LOW REG N	GLO	8N	R(N).0+D
PUT LOW REG N	PLO	AN	D+R(N).0
GET HIGH REG N	GHI	9N	R(N).1+D
PUT HIGH REG N			D+R(N).1
LOGIC OPERATIONS			
OR	OR .		
OR IMMEDIATE	ORI	F9	
EXCLUSIVE OR	XOR	F3	
EXCLUSIVE OR IMMEDIATE	XRI	FB	
AND	AND	F2	
AND IMMEDIATE		FA	SULET D RIGHT I SB(D)+DE
SHIFT RIGHT	SHR		SHIFT DINIGHT, LODIOFUT,
SULLET DIGUT WITH		724	SHIET D BIGHT I SB(D)+DF
		/°	DE+MSB(D)
		}	DI MISULUI
	CHI CHI	FF	SHIET DIFET MSB(D)+DF.
		1	0+1 SB(D)
SHIET I FET WITH	SHLC)	7E	SHIFT D LEFT, MSB(D)+DF.
CARRY		l	DF+LSB(D)
RING SHIFT LEFT	RSHL)		

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/	INSTRUCTION	301011017							
INSTRUCTION	MNEMONIC	CODE	OPERATION						
ARITHMETIC OPERATIONS **									
ADD ADD IMMEDIATE ADD WITH CARRY ADD WITH CARRY, IMMEDIATE	ADD AD1 ADC ADC1	F4 FC 74 7C	M(R(X)) + D+DF, D M(R(P)) + D+DF, D, R(P) + 1 M(R(X)) + D + DF+DF, D M(R(P)) + D + DF+DF, D						
SUBTRACT D SUBTRACT D IMMEDIATE SUBTRACT D WITH BOR BOW	SD SDI SDB	F5 FD 75	M(R(X))-D+DF, D M(R(P))-D+DF, D; R(P) +1 M(R(X))-D-(NOT DF)+DF, D						
SUBTRACT D WITH BORROW, IMMEDIATE	SDBI	7D	M(R(P))-D-(NOT DF)+DF, D; R(P) +1						
SUBTRACT MEMORY SUBTRACT MEMORY IMMEDIATE	SM SMI	F7 FF 77	D-M(R(X))+DF, D D-M(R(P))+DF, D; R(P) +1 D_M(R(X)) (NOT DE)+DE D						
BORROW SUBTRACT MEMORY WITH	SMBI	7F	D=M(R(P))=(NOT DF)+DF, D						
BORROW, IMMEDIATE			R(P) +1						
BRANCH INSTRUCTIONS-SHO	DRT BRANCH	· · · ·	1						
SHORT BRANCH NO SHORT BRANCH	BR NBR	30 38 [♦]	M{R(P)}≁R(P).0 R(P) +1						
SHORT BRANCH IF D=0	BZ	32	IF D≈0, M(R(P))+R(P).0 ELSE R(P) +1						
SHORT BRANCH IF D NOT 0	BNZ	ЗА	IF D NOT 0, M(R(P))+R(P).0 ELSE R(P) +1						
SHORT BRANCH IF DF=1 SHORT BRANCH IF POS OR ZERO	BDF BPZ	33•	IF DF=1, M(R(P))+R(P).0 ELSE R(P) +1						
OR GREATER SHORT BRANCH IF DF=0 SHORT BRANCH IF MINUS	BNF BM	3B [♦]	IF DF=0, M(R(P))+R(P).0 ELSE R(P) +1						
SHORT BRANCH IF LESS SHORT BRANCH IF Q=1	BL) BQ	31	IF Q=1, M(R(P))→R(P).0						
SHORT BRANCH IF Q=0	BNQ	39	ELSE R(P) +1 IF Q=0, M(R(P))+R(P).0						
SHORT BRANCH IF EF1=1	B1	34	IF EF1=1, M(R(P))+R(P).0						
SHORT BRANCH IF EF1=0	BN1	зc	IF EF1=0, M(R(P))+R(P).0 ELSE R(P) +1						
SHORT BRANCH IF EF2=1	82	35	IF EF2=1, M(R(P))→R(P).0 ELSE B(P) +1						
SHORT BRANCH IF EF2=0	BN2	3D	IF EF2=0, M(R(P))+R(P).0 ELSE R(P) +1						
SHORT BRANCH IF EF3=1	B3	36	IF EF3=1, M(R(P))+R(P).0 ELSE R(P) +1						
SHORT BRANCH IF EF3=0	BN3	3E	IF EF3=0, M(R(P))+R(P).0 ELSE R(P) +1						
SHORT BRANCH IF EF4=1	84	37	IF EF4=1, M(R(P))+R(P).0 ELSE R(P) +1						
SHORT BRANCH IF EF4=0	BN4	3F	IF EF4=0, M(R(P))+R(P).0 ELSE R(P) +1						

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 #NOTE: THIS INSTRUCTION IS ASSOCIATED WITH MORE THAN ONE MNEMONIC: EACH MNEMONIC IS INDIVIDUALEY LISTED

 #NOTE: THE ARITHMETIC OPERATIONS AND THE SHIFT INSTRUCTIONS ARE THE ONLY INSTRUCTIONS THAT CAN ALTER THE DF.

 #FTER AN ADD INSTRUCTION: DF + D DENOTES A CARRY HAS OCCURRED

 DF + 0 DENOTES A CARRY HAS NOT OCCURRED

 AFTER AN SUBTRACT INSTRUCTION: DF + 0 DENOTES A CARRY HAS NOT OCCURRED

 AFTER AN SUBTRACT INSTRUCTION: DF + 0 DENOTES A CARRY HAS NOT OCCURRED

 AFTER A SUBTRACT INSTRUCTION: DF + 0 DENOTES A CARRY HAS NOT OCCURRED

 AFTER A SUBTRACT INSTRUCTION: DF + 0 DENOTES A CARRY HAS NOT OCCURRED

 AFTER A SUBTRACT INSTRUCTION: DF + 0 DENOTES A CARRY HAS NOT OCCURRED

 AFTER A SUBTRACT INSTRUCTION: DF + 0 DENOTES A CARRY HAS NOT OCCURRED

 AFTER A SUBTRACT INSTRUCTION: DF + 0 DENOTES A CARRY HAS NOT OCCURRED

 AFTER A SUBTRACT INSTRUCTION: DF + 0 DENOTES A BORROW, D IS TRUCTOON OF THE BORROW

 THE SYNTAX '- (NUT DF)'' DENOTES THE SUBTRACTION OF THE BORROW

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INSTRUCTION SUMMARY (CONT'D)			
INSTRUCTION	MNEMONIC	OP CODE	OPERATION
BRANCH INSTRUCTIONS-LONG BRANCH			
LONG BRANCH	LBR	СО	M(R(P))+R(P),1
· · ·			M(R(P) +1)+R(P).0
NO LONG BRANCH (SEE LSKP)	NLBR	C8 [●]	R(P) +2
LONG BRANCH IF D=0	LBZ	C2	IF D=0. M(R(P))·R(P).1
			M(R(P) +1)+R(P).0
			ELSE R(P) +2
LONG BRANCH IF D NOT 0	LBNZ	CA	IF D NOT 0, M(R(P))+R(P).1
			M(R(P) +1)+R(P).0
LONG BRANCH IE DE=1	IRDE	<u></u>	ELSE H(P) +2
Long Branch in Dr-1	LOUP	5	M(R(P) + 1) + R(P) = 0
			ELSE R(P) +2
LONG BRANCH IF DF=0	LBNF	СВ	IF DF=0. M(R(P))+R(P).1
			M(R(P) +1)+R(P).0
			ELSE R(P) +2
LONG BRANCH IF Q=1	LBQ	C1	IF Q=1, M(R(P))+R(P).1
			M(R(P) + 1) + R(P).0
LONG PRANCH IS 0-0		0	
LONG BRANCH IF Q-0	LDING	L9	$M(R(P) + 1) + R(P) \cap$
			ELSE R(P) +2
SKIP INSTRUCTIONS			
SHORT SKIP	SKP	38	R(P) +1
(SEE NBR)			
LONG SKIP	LSKP	C8•	R(P) +2
(SEE NLBR)		0.5	
LONG SKIP IF D=0	LSZ	CE	
LONG SKIP LE D NOT 0	L SNZ	C6	IF D NOT 0 $B(P) + 2$
	20112		ELSE CONTINUE
LONG SKIP IF DF=1	LSDF	CF	1F DF=1, R(P) +2
			ELSE CONTINUE
LONG SKIP IF DF=0	LSNF	C7	IF DF=0, R(P) +2
LUNG SKIP IF U=1	Lau		FLSE CONTINUE
I ONG SKIP IF O=0	LSNO	CS	IF Q=0, R(P) +2
		•	ELSE CONTINUE
LONG SKIP IF IE=1	LSIE	CC	IF IE=1, R(P) +2
· · · · · · · · · · · · · · · · · · ·	L	L	ELSE CONTINUE
CONTROL INSTRUCTIONS			
IDLE	IDL	007	WAIT FOR DMA OR
			INTERRUPT; M(R(U))+BUS
NO OPERATION	NOP		
	SEY	FN	N+X
SET O	SEQ	7B	1+0
RESET Q	REQ	7A	0+Q ·
SAVE	SAV	78	T+M(R(X))
PUSH X,P TO STACK	MARK	79	(X,P)+T; (X,P)+M(R(2))
			THEN P+X; R(2)-1
RETURN	RET	70	M(K(X)P(X,P); K(X) +1
DISARIE	nis	71	M(R(X)) + (X P): R(X) + 1
DISABLE	013		0+1E

#An idle instruction initiates a repeating S1 cycle. The processor will continue to idle until an I/O request (INTERRUPT, DMA-IN, or DMA-OUT) is activated. When the request is acknowledged, the IDLE cycle is terminated and the I/O request is serviced, and then normal operation is resumed.

ONOTE: THIS INSTRUCTION IS ASSOCIATED WITH MORE THAN ONE MNEMONIC. EACH MNEMONIC IS INDIVIDUALLY LISTED.

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| INSTRUCTION SUMMARY (CONT'D) | | | | | | | |
|------------------------------|----------|------------|---------------------------------------|--|--|--|--|
| INSTRUCTION | MNEMONIC | OP
CODE | OPERATION | | | | |
| INPUT-OUTPUT BYTE TRA | NSFER | | · · · · · · · · · · · · · · · · · · · | | | | |
| OUTPUT 1 | OUT 1 | 61 | [M(R(X))+BUS: R(X) +1: N LINES = 1 | | | | |
| OUTPUT 2 | OUT 2 | 62 | M(R(X))+BUS; R(X) +1; N LINES = 2 | | | | |
| OUTPUT 3 | OUT 3 | 63 | M(R(X))+BUS; R(X) +1; N LINES = 3 | | | | |
| OUTPUT 4 | OUT 4 | 64 | M(R(X))+BUS; R(X) +1; N LINES = 4 | | | | |
| OUTPUT 5 | OUT 5 | 65 | M(R(X))+BUS; R(X) +1; N LINES = 5 | | | | |
| OUTPUT 6 | OUT 6 | 66 | M(R(X))+BUS; R(X) +1; N LINES = 6 | | | | |
| OUTPUT 7 | OUT 7 | 67. | M(R(X))+BUS; $R(X)$ +1; N LINES = 7 | | | | |
| INPUT 1 | INP 1 | 69 | BUS+M(R(X)); BUS+D; N LINES = 1 | | | | |
| INPUT 2 | INP 2 | 6A | BUS+M(R(X)); BUS+D; N LINES = 2 | | | | |
| INPUT 3 | INP 3 | 6B | BUS+M(R(X)); BUS+D; N LINES = 3 | | | | |
| INPUT 4 | INP 4 | 6C | BUS+M(R(X)); BUS+D; N LINES = 4 | | | | |
| INPUT 5 | INP 5 | 6D | BUS+M(R(X)); BUS+D; N LINES = 5 | | | | |
| INPUT 6 | INP 6 | 6E - | BUS+M(R(X)); BUS+D; N LINES = 6 | | | | |
| INPUT 7 | INP 7 | _6F | BUS+M(R(X)); BUS+D; N LINES = 7 | | | | |

Long-Branch, Long-Skip and No Op instructions are the only instructions that require

three cycles to complete (1 fetch + 2 execute).

Long-Branch instructions are three bytes long. The first byte specifies the condition to be tested; and the second and third byte, the branching address.

The long-branch instructions can:

a) Branch unconditionally

b) Test for D=0 or D≠0

c) Test for DF=0 or DF=1

d) Test for Q=0 or Q=1

e) effect an unconditional no branch

If the tested condition is met, then branching takes place; the branching address bytes are loaded in the high-and-low-order bytes of the current program counter, respectively. This operation effects a branch to any memory location.

If the tested condition is not met, the branching address bytes are skipped over, and the next instruction in sequence is fetched and executed. This operation is taken for the case of unconditional no branch.

2. The short-branch instructions are two bytes long. The first byte specifies the condition to be tested, and the second specifies the branching address.

The short-branch instructions can:

a) Branch unconditionally

b) Test for D=0 or D≠0 c) Test for DF=0 or DF=1

c)

d) Test for Q=0 or Q=1

Test the status (1 or 0) of the four EF flags

e) Test the status (1 or 0) or the f) Effect an unconditional no branch

If the tested condition is met, then branching takes place; the branching address byte is loaded into the low-order byte position of the current program counter. This effects a branch with the current 256 byte page of the memory, i.e., the page which holds the branching address. If the tested condition is not met, the branching address byte is skipped over, and the next instruction in sequence is fetched and executed. This same action is taken in the case of unconditional no branch.

3. The skip instructions are one byte long. There is one Unconditional Short-Skip (SKP) and eight Long-Skip instructions.

The Unconditional Short-Skip instruction takes 2 cycles to complete (1 fetch + 1 execute). Its action is to skip over the byte following it. Then the next instruction in sequence is fetched and executed. This SKP instruction is identical to the unconditional no-branch instruction (NBR) except that the skipped-over byte is not considered part of the program. The Long-Skip instructions take three cycles to complete (1 fetch + 2 execute).

They can:

a) Skip unconditionally

b) Test for D=0 or D≠0

c) Test for DF=0 or DF=1 d)

Test for Q=0 or Q=1

e) Test for IE=1

If the tested condition is met, then Long Skip takes place; the current program counter is incremented twice. Thus two bytes are skipped over and the next instruction in sequence is fetched and executed. If the tested condition is not met, then no action is taken. Execution is continued by fetching the next instruction in sequence.

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SIGNAL DESCRIPTIONS

BUS 0 to BUS 7 (Data Bus)

N0 to N2 (I/O Command)

8-bit directional DATA BUS lines. These lines are used for transferring data between the memory, the microprocessor, and I/O devices.

Issued by an 1/O instruction to signal the 1/O control logic of a data transfer between memory and 1/O interface. These lines can be used to issue command codes or device selection codes to the 1/O devices (independently or combined with the memory byte on the data bus when an 1/O instruction is being executed). The N bits are low at all times except when an 1/O instruction is being executed. During this time their state is the same as the corresponding bits in the N register.

The direction of data flow is defined in the I/O instruction by bit N3 and is indicated by the level of the MRD signal.

MRD = V_{CC}: Data from I/O to CPU and Memory

MRD = VSS: Data from Memory to I/O

EF1 to EF4 (4 Flags)

INTERRUPT, DMA-IN, DMA-OUT (3 I/O Requests)

SCO, SC1, (2 State Code Lines)

TPA, TPB (2 Timing Pulses)

MAD to MA7 (8 Memory Address Lines) These levels enable the I/O controllers to transfer status information to the processor. The levels can be tested by the conditional branch instructions. They can be used in conjunction with the INTERRUPT request line to establish interrupt priorities. These flags can also be used by I/O devices to "call the attention" of the processor, in which case the program must routinely test the status of these flag(s). The flag(s) are sampled at the beginning of every S1 cycle.

These signals are sampled by the CDP1802 during the interval between the leading edge of TPB and the leading edge of TPA.

Interrupt Action: X and P are stored in T after executing current instruction; designator X is set to 2; designator P is set to 1; interrupt enable is reset to 0 (inhibit); and instruction execution is resumed.

DMA Action: Finish executing current instruction; R(0) points to memory area for data transfer; data is loaded into or read out of memory; and increment R(0).

Note: In the event of concurrent DMA and INTERRUPT requests, DMA-IN has priority followed by DMA-OUT and then INTERRUPT.

These lines indicate that the CPU is: 1) fetching an instruction, or 2) executing an instruction, or 3) processing a DMA request, or 4) acknowledging an interrupt request. The levels of state code are tabulated below. All states are valid at TPA. $H = V_{CC}$, $L = V_{SS}$.

Contra Tura	State Code Lines		
State Type	SC1	SC0	
SO (Fetch)	L	L	
S1 (Execute)	L	н	
S2 (DMA)	н	L	
S3 (Interrupt)	н	Н	

Positive pulses that occur once in each machine cycle (TPB follows TPA). They are used by I/O controllers to interpret codes and to time interaction with the data bus. The trailing edge of TPA is used by the memory system to latch the higher-order byte of the 16-bit memory address. TPA is suppressed in IDLE when the CPU is in the load mode.

The higher-order byte of a 16-bit COSMAC memory address appears on the memory address lines MA0-7 first. Those bits required by the memory system are strobed into external address taiches by timing pulse TPA. The low-order byte of the 16-bit address appears on the address lines after the termination of TPA. Latching of all 8 higher-order address bits would permit a memory system of 64K bytes.

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	Preliminary CDP1802D, CDP1802CD					
MWR (Write Pulse)	A negative pulse appearing in a memory-write cycle, after the address lines have stabilized.					
MRD (Read Level)	A low level on MRD indicates a memory read cycle. It can be used to control three-state outputs from the arddressed memory which may have a common data input and output bus. If a memory does not have a three-state high-impedance output, MRD is useful for driving memory/bus separator gates. It is also used to indicate the direction of data trans- fer during an I/O instruction: MRD = V _{CC} : Data from I/O to CPU and Memory					
	MRD = V _{SS} : Data from Memory to I/O					
Q	Single bit output from the CPU which can be set or reset under program control. During SEQ or REQ instruction execution, Q is set or reset between the trailing edge of TPA and the leading edge of TPB.					
CLOCK	Input for externally generated single-phase clock. A typical clock frequency is 6.4 MHz at V_{CC} = V_{DD} = 10 volts.					
	The clock is counted down internally to 8 clock pulses per machine cycle.					
XTAL	Connection to be used with clock input terminal, for an external crystal, if the on-chip oscillator is utilized. The crystal is connected between terminals 1 and 39 (CLOCK and XTAL) in parallel with a resistance (10 megohms typ.). Frequency trimming capacitors may be required at terminals 1 and 39.					
WAIT, CLEAR (2 Control Lines)	Provide four control modes as listed in the following truth table:					
	CLEAR WAIT MODE					
,	L L Load					
•	L H Reset					
	H L Pause					
	H H Run					
The function of the modes are defined as follo						
Load						

Holds the CPU in the IDLE execution state and allows an I/O device to load the memory without the need for a "bootstrap" loader. It modifies the IDLE condition so that DMA-IN operation does not force execution of the next instruction.

Reset

Registers I, N, Q are reset, IE is set and O's (V_{SS}) are placed on the data bus. TPA and TPB are suppressed while reset is held and the CPU is placed in S1. The first machine cycle after termination of reset is an initialization cycle. During this cycle the CPU remains in S1 and registers X, P, and R(0) are reset. Interrupt and DMA servicing are suppressed during the initialization cycle.

The next cycle is an S0, S1, or an S2 but never an S3. With the use of a 71 instruction followed by 00 at memory locations 0000 and 0001, this feature may be used to reset IE, so as to preclude interrupts until ready for them. Powerup reset can be realized by connecting an external RC to CLEAR.

Pause

Stops the internal CPU timing generator on the first negative high-to-low transition of the input clock. The oscillator continues to operate, but subsequent clock transitions are ignored.

Run

May be initiated from the Pause or Reset mode functions. If initiated from Pause, the CPU resumes operation on the first negative high-to-low transition of the input clock. When initiated from the Reset operation, the first machine cycle following Reset is always the initialization cycle. The initialization cycle is then followed by a DMA (S2) cycle or fetch (S0) from location 0000 in memory.

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Preliminary CDP1802D, CDP1802CD

VDD. VSS. VCC (Power Levels)

The internal voltage supply VDD is isolated from the Input/ Output voltage supply V_{CC} so that the processor may operate at maximum speed while interfacing with various external circuit technologies, including T²L at 5 volts. V_{CC} must be less than or equal to VDD. All outputs swing from VSS to VCC. The recommended input voltage swing is



-9255-22634 Fig. 6-CDP1802 microprocessor state

transitions (Run Mode).

in Fig. 6. Each machine cycle requires the same period of time-8 clock pulses. The execution of an instruction requires either two or three machine cycles, S0 followed by a single S1 cycle or two S1 cycles. S2 is the response to a DMA request and S3 is the interrupt response.

The CDP1802 and CDP1802C CPU state transitions when in the RUN mode are shown

OPERATING AND HANDLING CONSIDERATIONS FOR CDP1802D AND CDP1802CD

1. Handling

All inputs and outputs of this device have a network for electrostatic protection during handling. Recommended handling practices for COS/MOS devices are described in ICAN-6000 "Handling and Operating Considerations for MOS Integrated Circuits", available on request from RCA Solid State Division, Box 3200, Somerville, N.J. 08876.

2. Operating

Operating Voltage

CDP1802D, CDP1802CD 40-Lead Dual-In-Line Ceramic

During operation near the maximum supply voltage limit, care should be taken to avoid or suppress power supply turnon and turn-off transients, power supply ripple, or ground noise; any of these conditions must not cause VDD-VSS to

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exceed the absolute maximum rating. V_{CC} must be less than equal to V_{DD} . Power supplies should be sequenced to insure compliance. Input Signals

To prevent damage to the input protection circuit, input signals should never be greater than VDD nor less than VSS. Input currents must not exceed 10 mA even when the power supply is off.

Unused Inputs

A connection must be provided at every input terminal. All unused input terminals must be connected to either VDD or VSS, whichever is appropriate.

Output Short Circuits

Shorting of outputs to VDD or VSS may damage COS/MOS devices by exceeding the maximum device dissipation.

DIM.	MILLI	AETERS	INCHES	
	MIN.	MAX.	MIN.	MAX,
A	50.30	51.30	1.980	2.020
С	2.42	3.93	0 095	0 155
D	0.43	0.56	0.017	0 023
F	1.27 REF.		0.050 REF.	
G	2 54 BSC		0.100 BSC	
н	0 76	1 78	0 0 3 0	0 070
1	0 20	0 30	0 008	0 012
ĸ	3 18	4 45	0 125	0 175
L	14 74	15 74	0 580	0 620
M	-	70	-	70
Ρ	0 64	1 27	0 025	0 050
N	40		40	

NOTES

(0 33 mm)

1. Leads within 0.13 mm (0.005) radius of true position at maximum material condition

Dimension "L" to center of leads when formed parallel. 3. When this device is supplied solder dipped, the maximum fead thickness (narrow purtion) will not exceed 0.013 in.

When incorporating RCA Solid State Devices in entern incorporating NCA Solid State Context in equipment, it is recommended that the designer refer to "Operating Considerations for NCA Solid State Device", Form No. 1CE 402, evaluable on request from NCA Solid State Division, Box 3200, Somerville, N.J. Ould 76.

RCA|Solid State Division|Somerville, NJ 08876

DIMENSIONAL OUTLINE